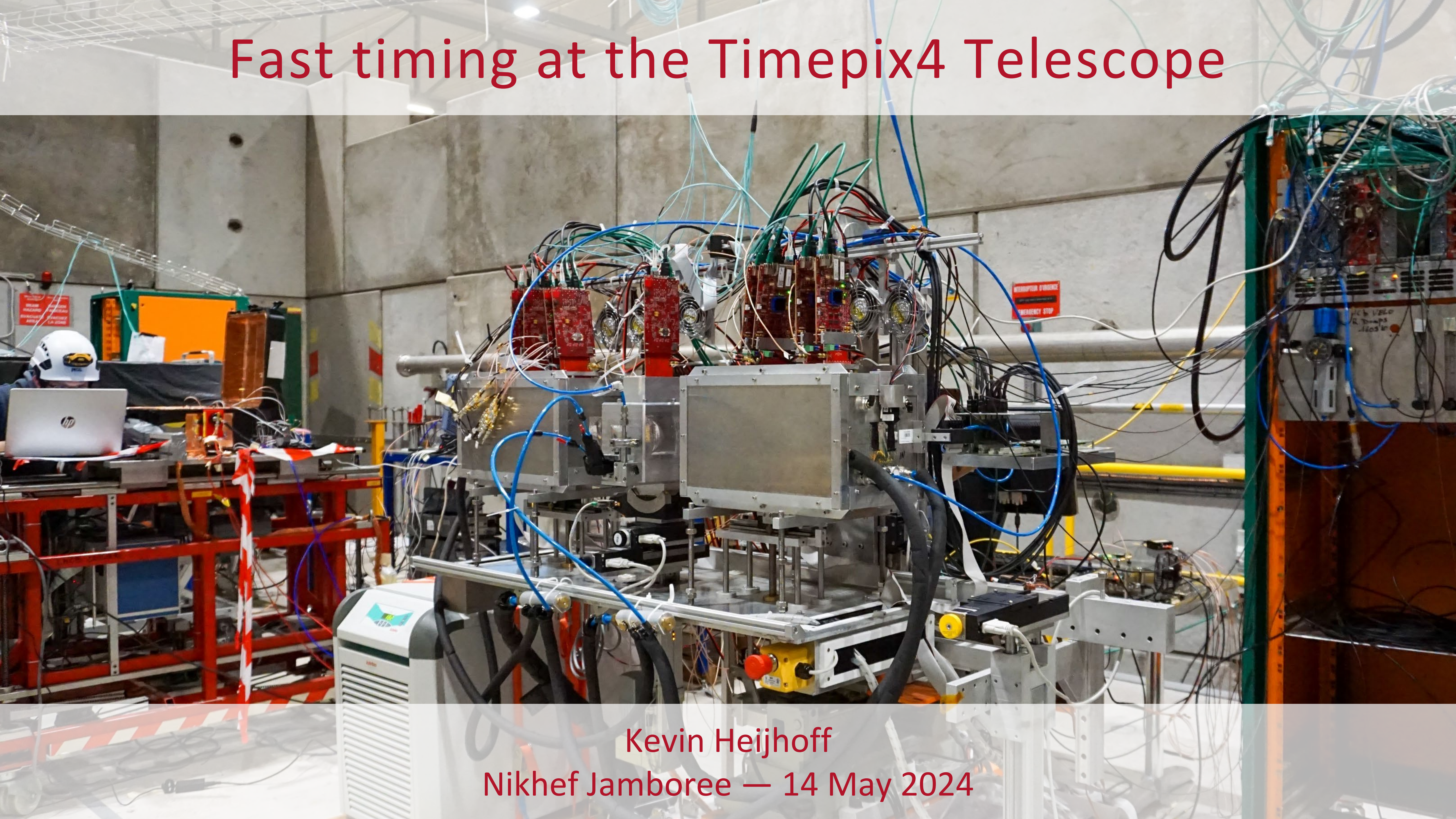


# Fast timing at the Timepix4 Telescope



Kevin Heijhoff  
Nikhef Jamboree — 14 May 2024

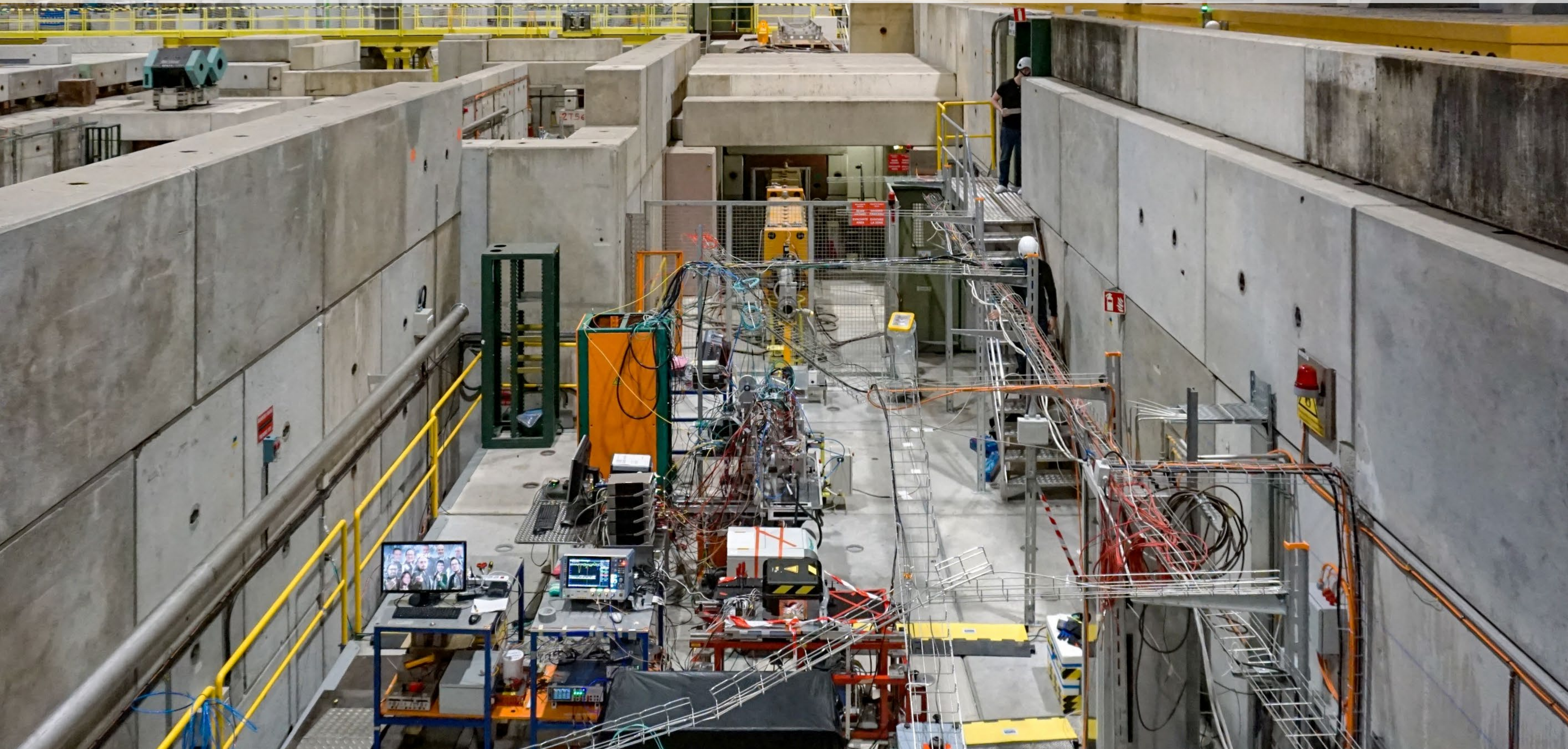


# SPS North Area





# SPS North Area





# SPS North Area

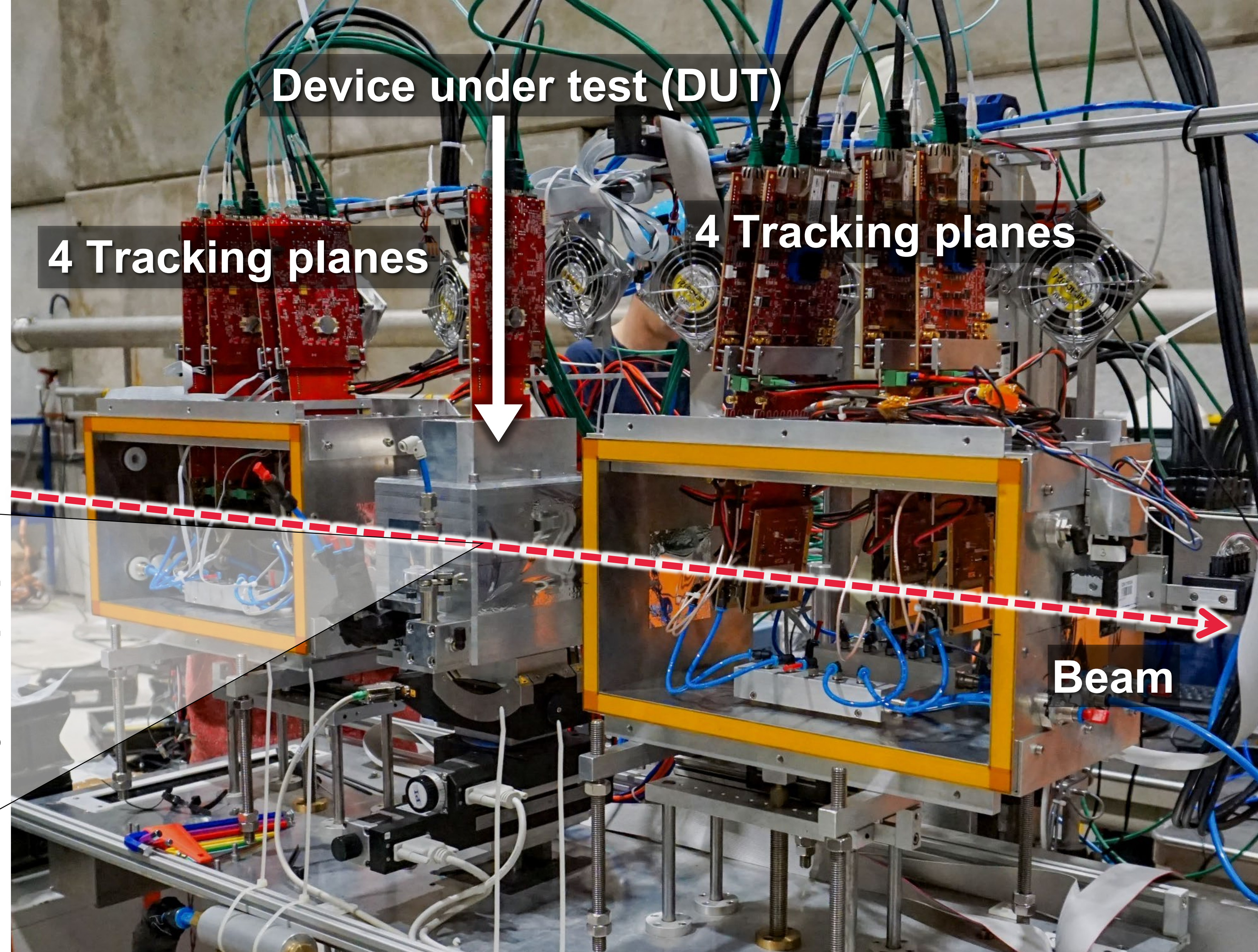
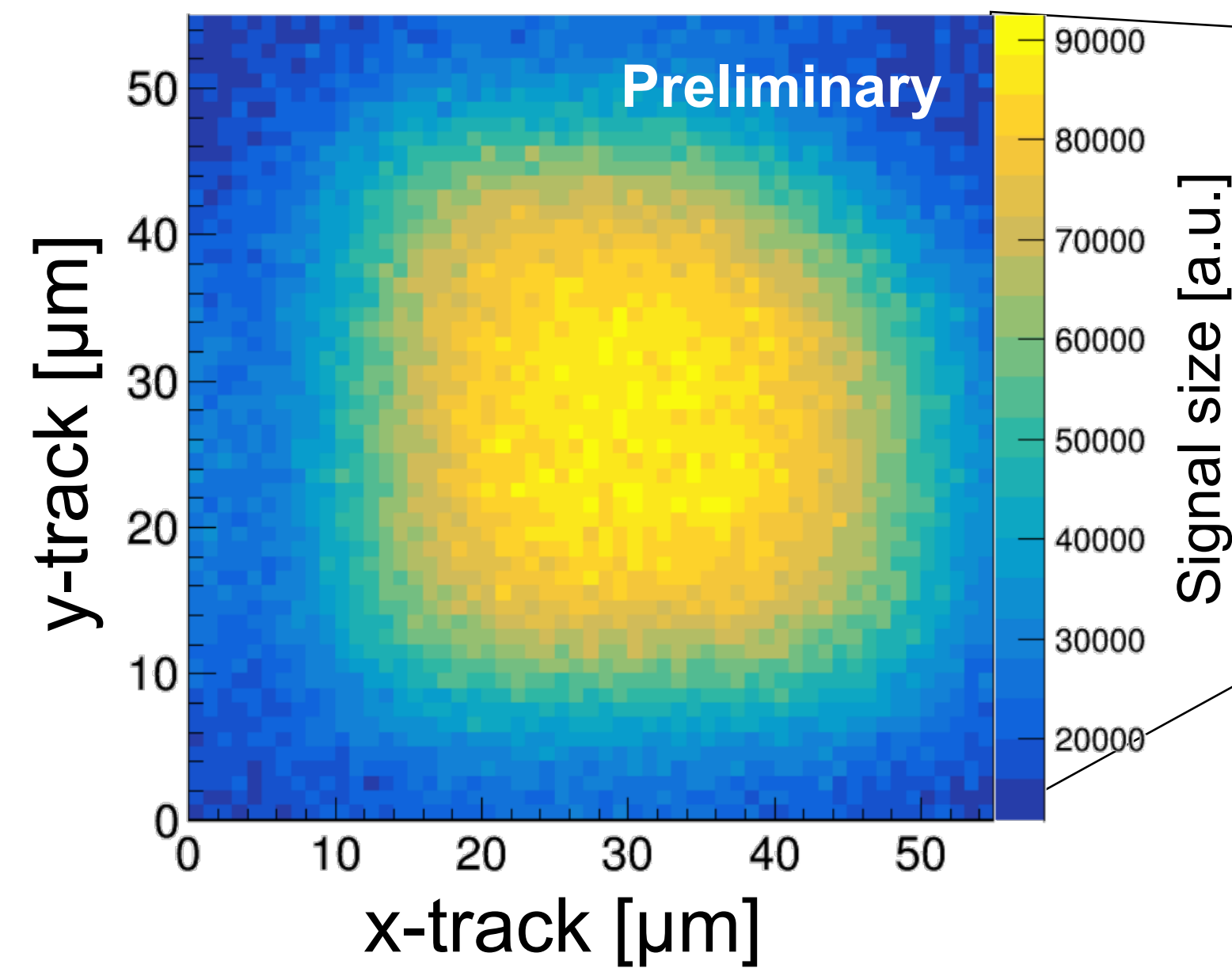




# Timepix4 Telescope

- Study prototype sensors for 4D trackers at high rate
- 4D tracking demonstrator
- $< 50$  ps track-time resolution at high rate

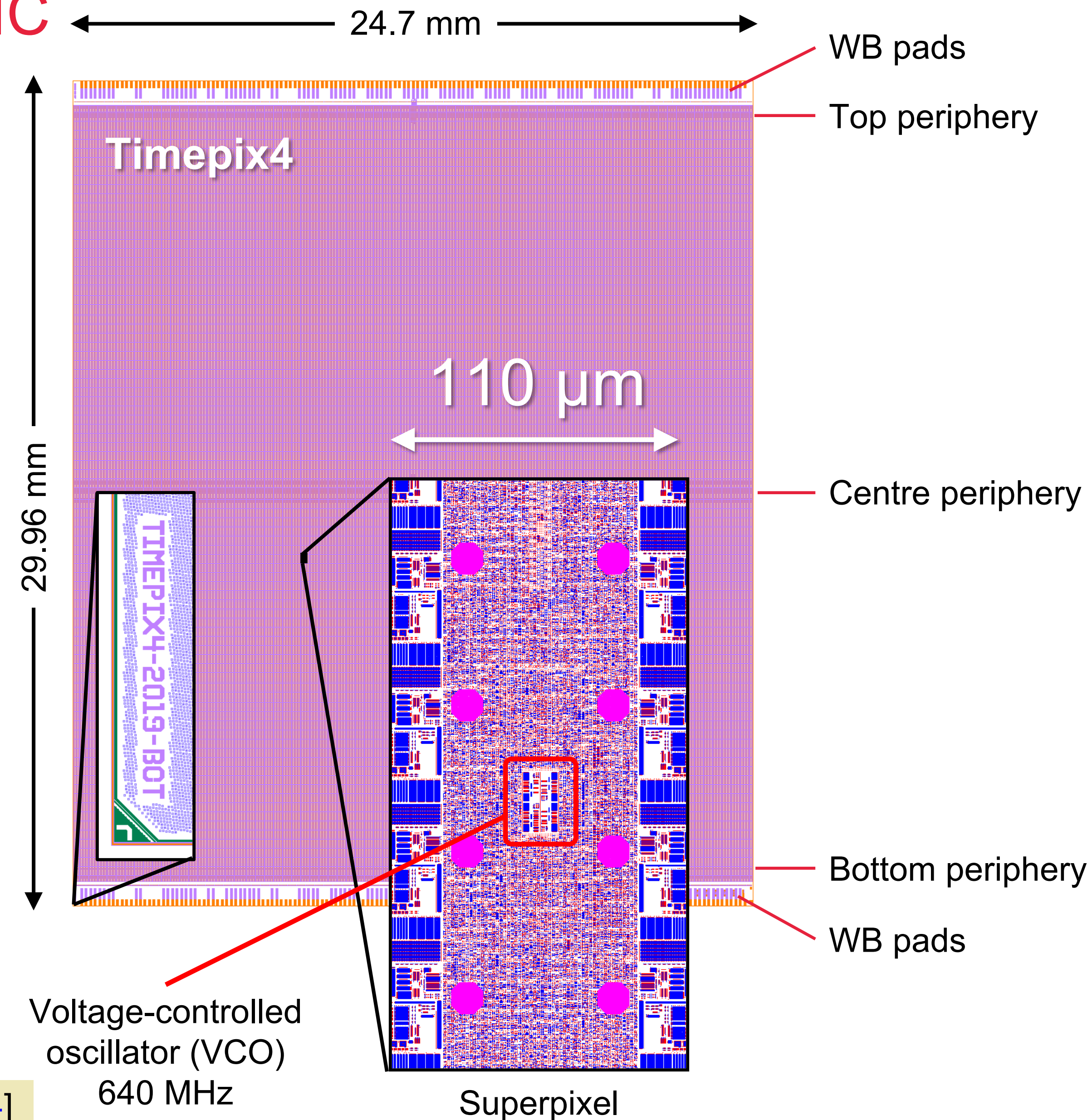
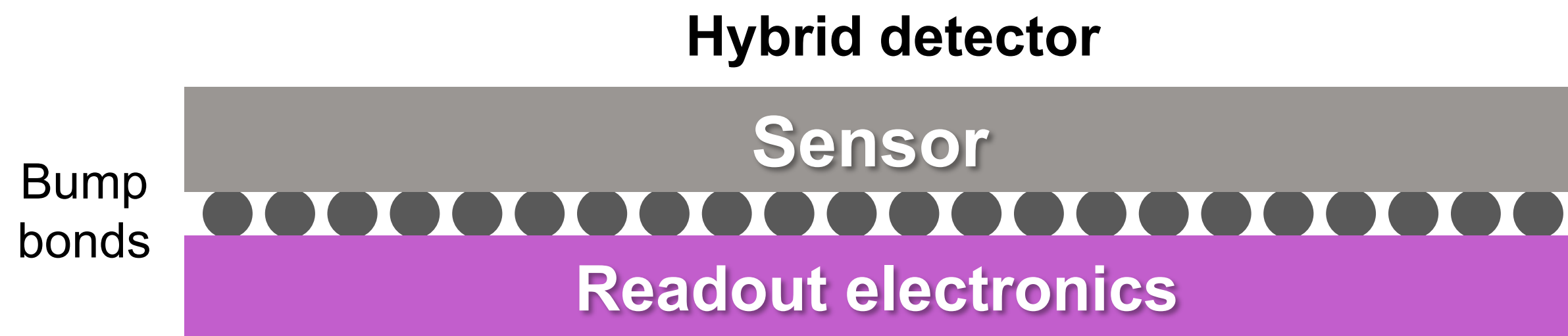
Single pixel gain





# Timepix4: Hybrid pixel detector readout ASIC

- Developed by CERN, Nikhef, and IFAE
- 65 nm CMOS
- 448×512 pixels, 55×55  $\mu\text{m}^2$  pitch
- Simultaneous measurement of time and charge deposition (by measuring time over threshold)
- Time-bin size of 25 ns/128 = **195 ps (= resolution of 56 ps)**
- Max rate:  $360 \times 10^6$  hits/cm<sup>2</sup>/s (160 Gb/s for single chip)



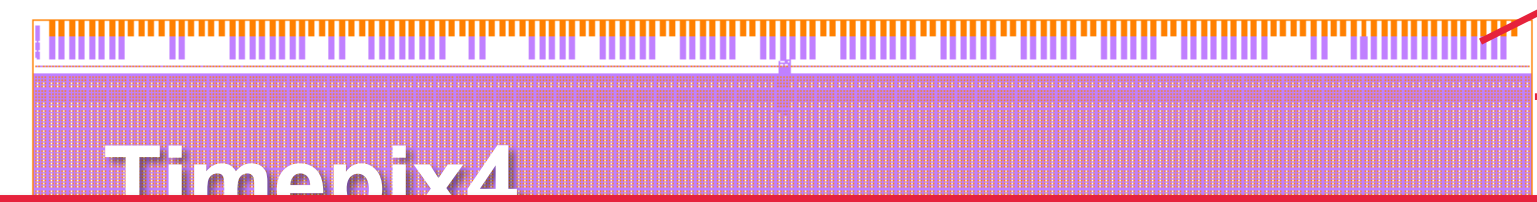
X. Llopart *et al* 2022 *JINST* 17 C01044 [DOI: [10.1088/1748-0221/17/01/C01044](https://doi.org/10.1088/1748-0221/17/01/C01044)]



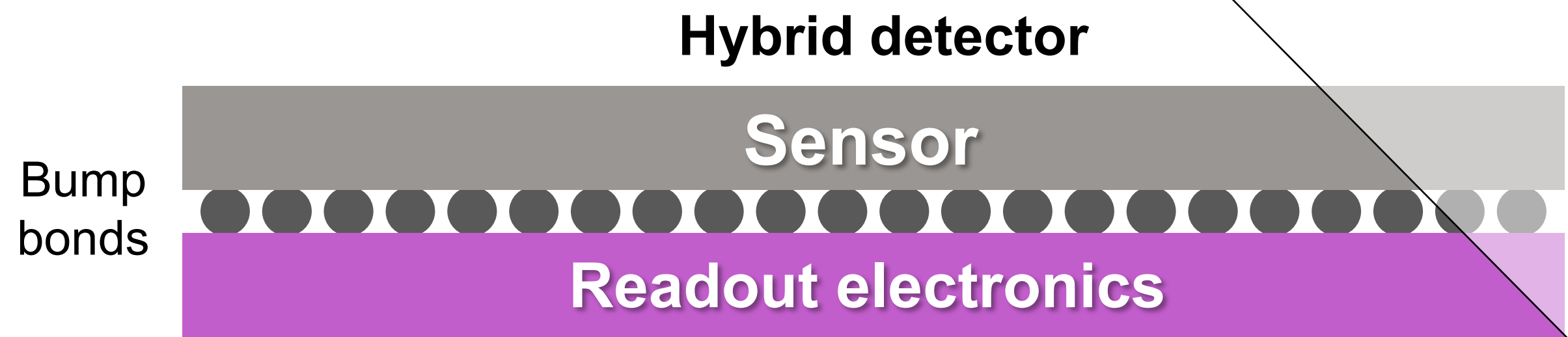
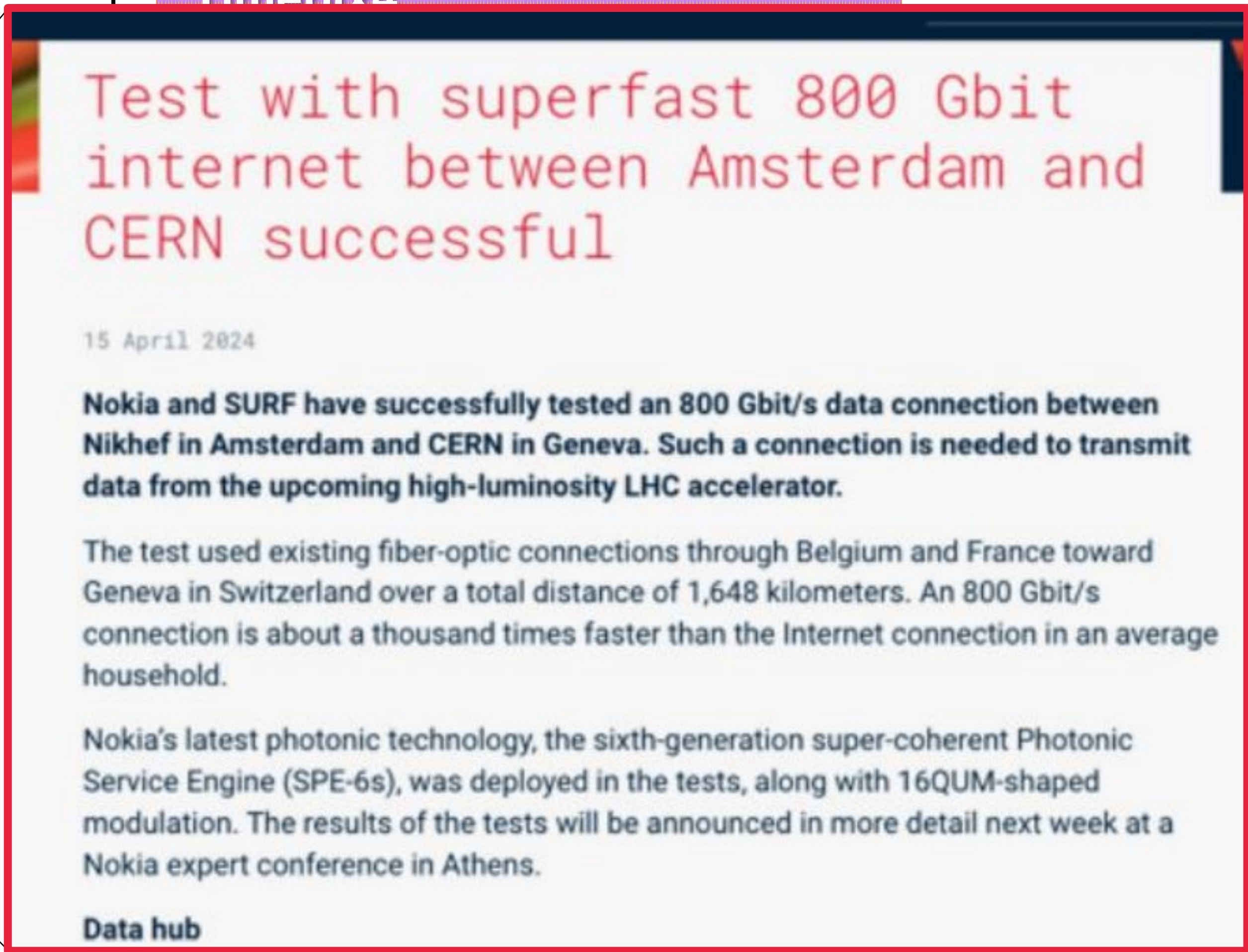
# Timepix4: Hybrid pixel detector readout ASIC

← 24.7 mm →

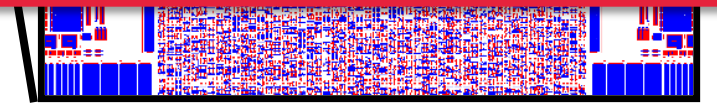
WB pads  
Top periphery



- Developed by CERN, Nikhef, and IFAE
- 65 nm CMOS
- 448×512 pixels, 55×55 μm<sup>2</sup> pitch
- Simultaneous measurement of time and charge deposition (by measuring time over threshold)
- Time-bin size of 25 ns/128 = **195 ps (= resolution of 56 ps)**
- Max rate: 360×10<sup>6</sup> hits/cm<sup>2</sup>/s (160 Gb/s for single chip) **×5**



oscillator (VCO)  
640 MHz

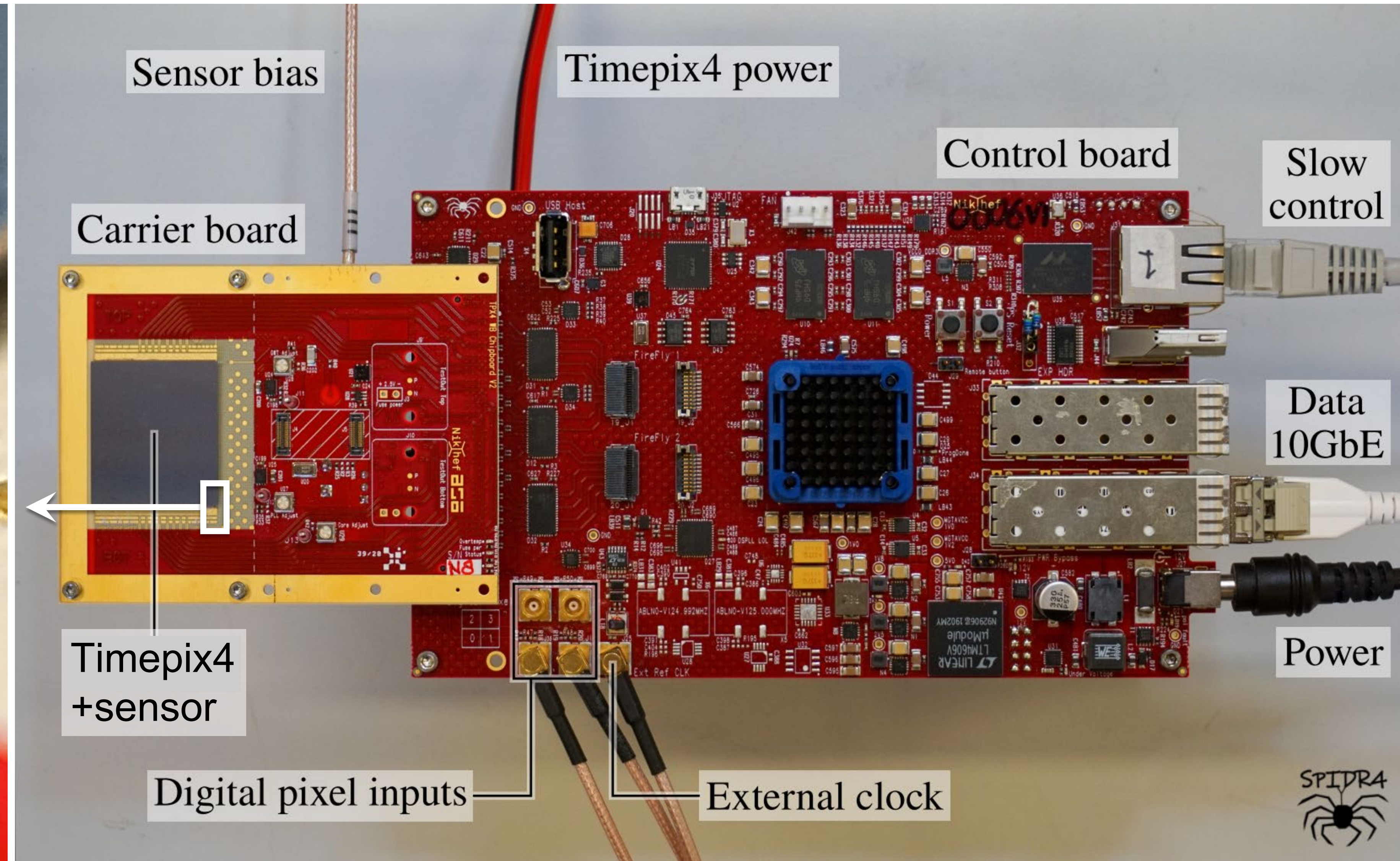
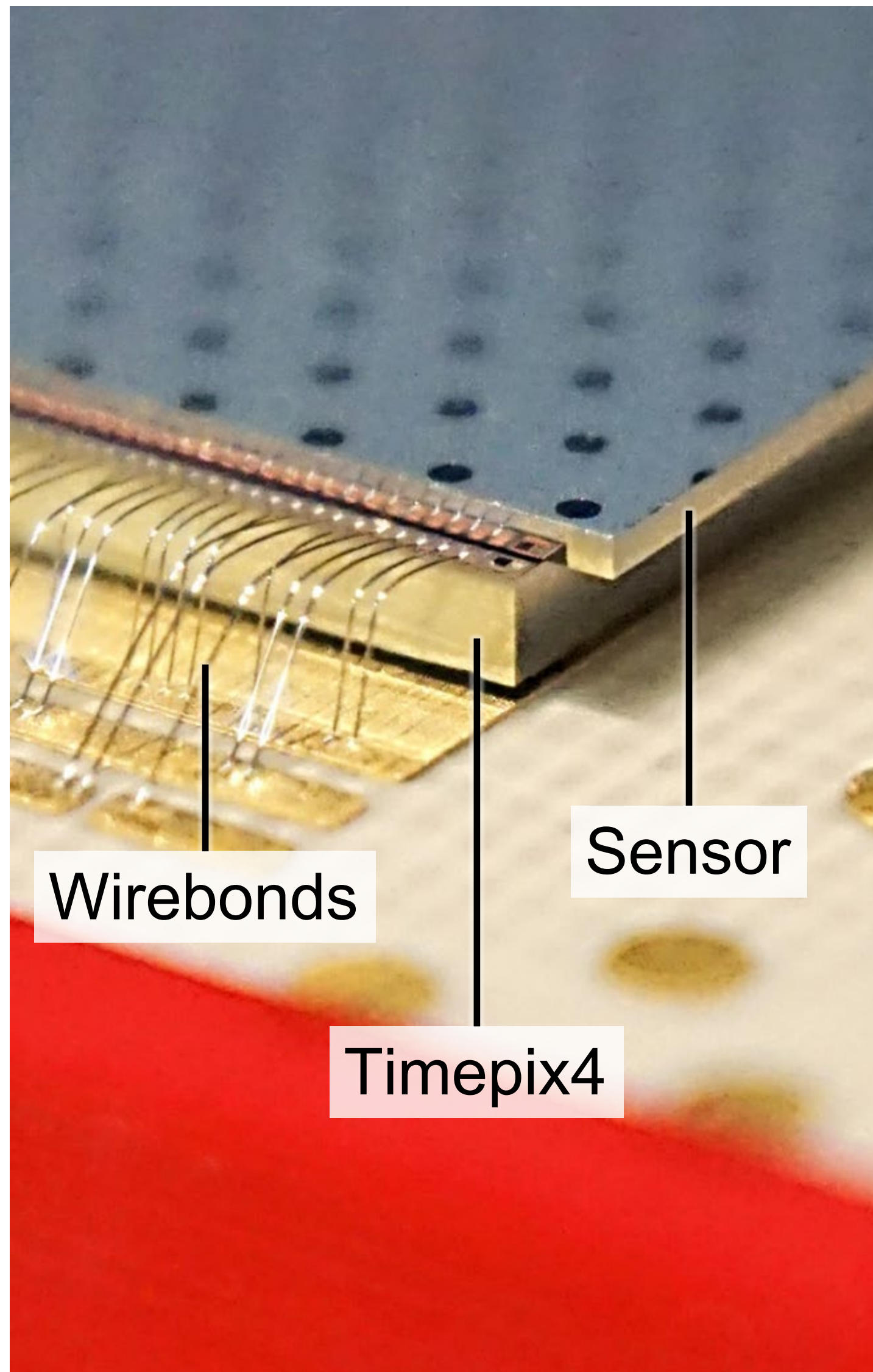


Superpixel

X. Llopart *et al* 2022 *JINST* 17 C01044 [DOI: [10.1088/1748-0221/17/01/C01044](https://doi.org/10.1088/1748-0221/17/01/C01044)]

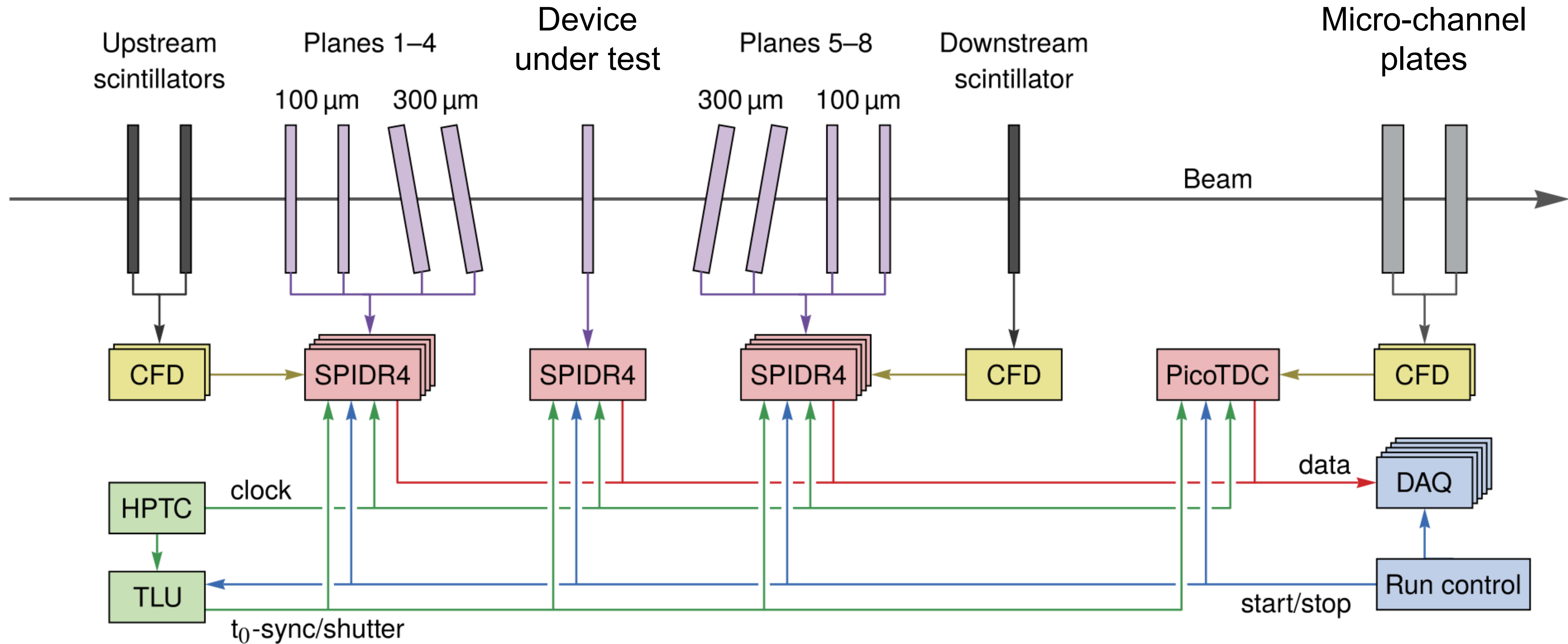


# Speedy Pixel Detector Readout 4 (SPIDR4)





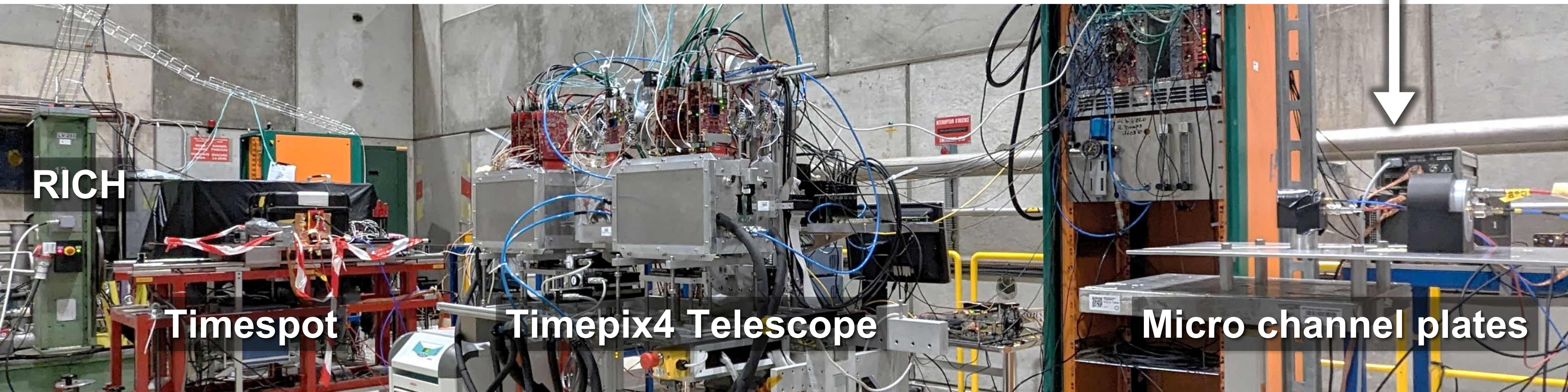
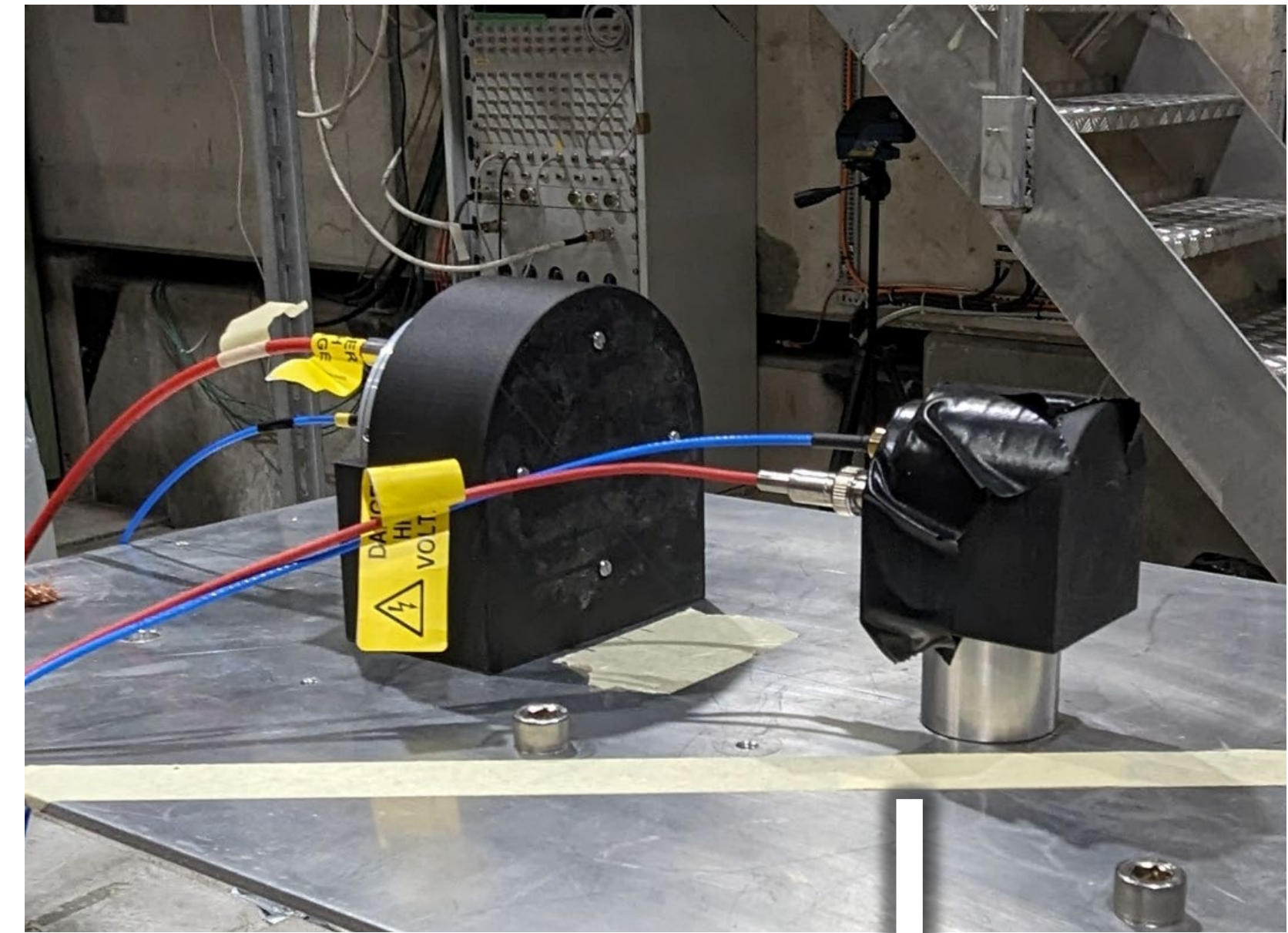
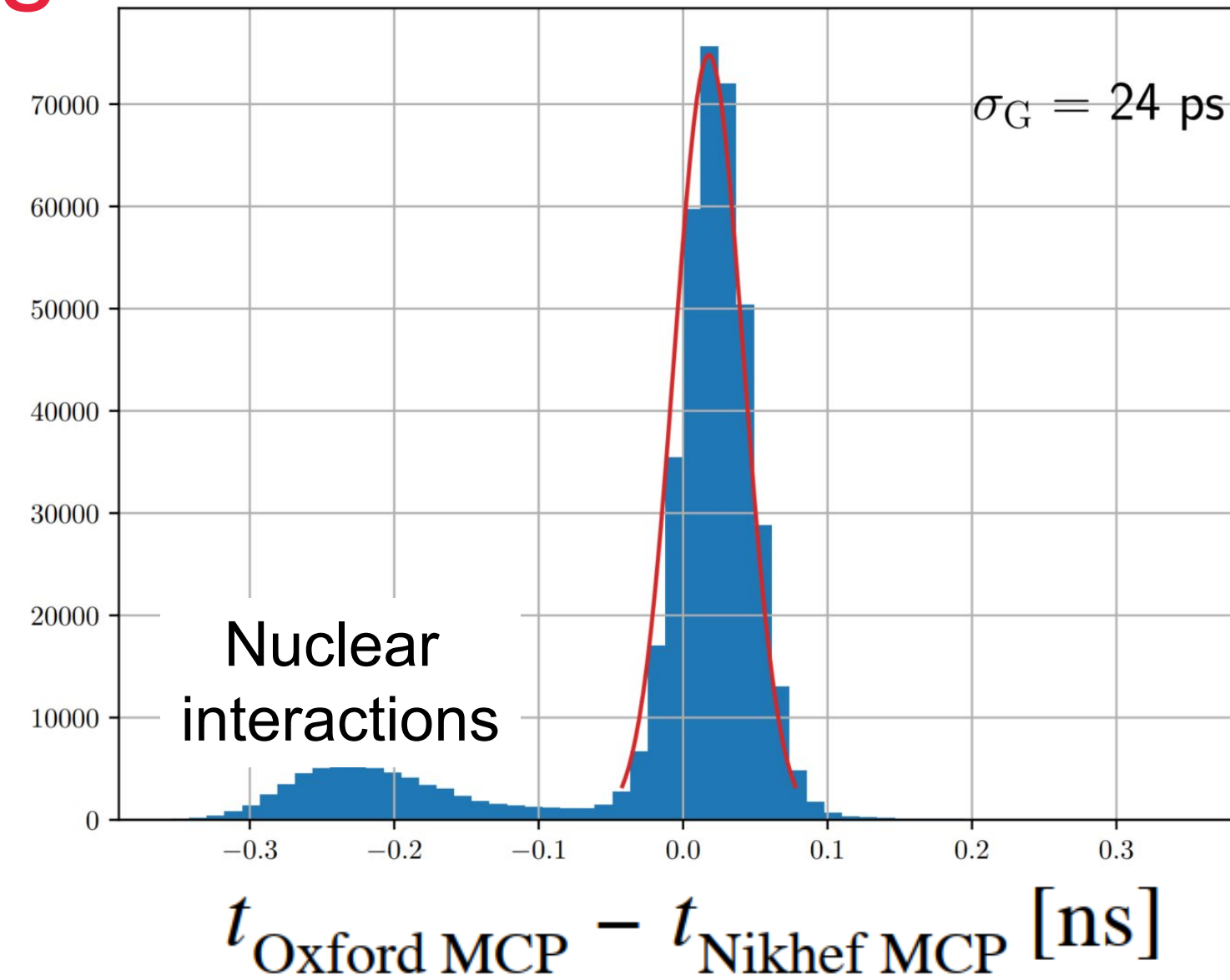
# Telescope configuration





# Micro channel plate detectors

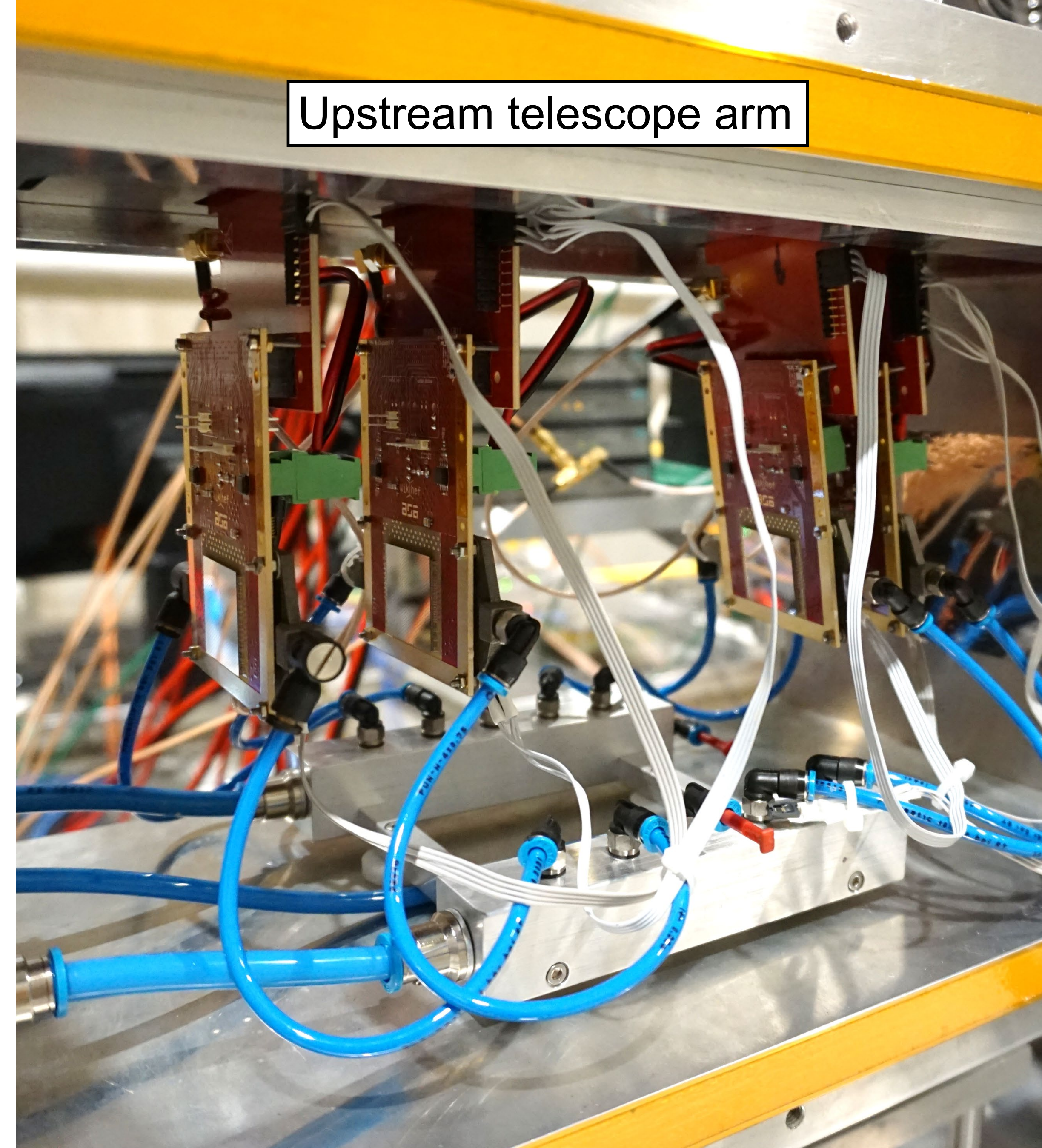
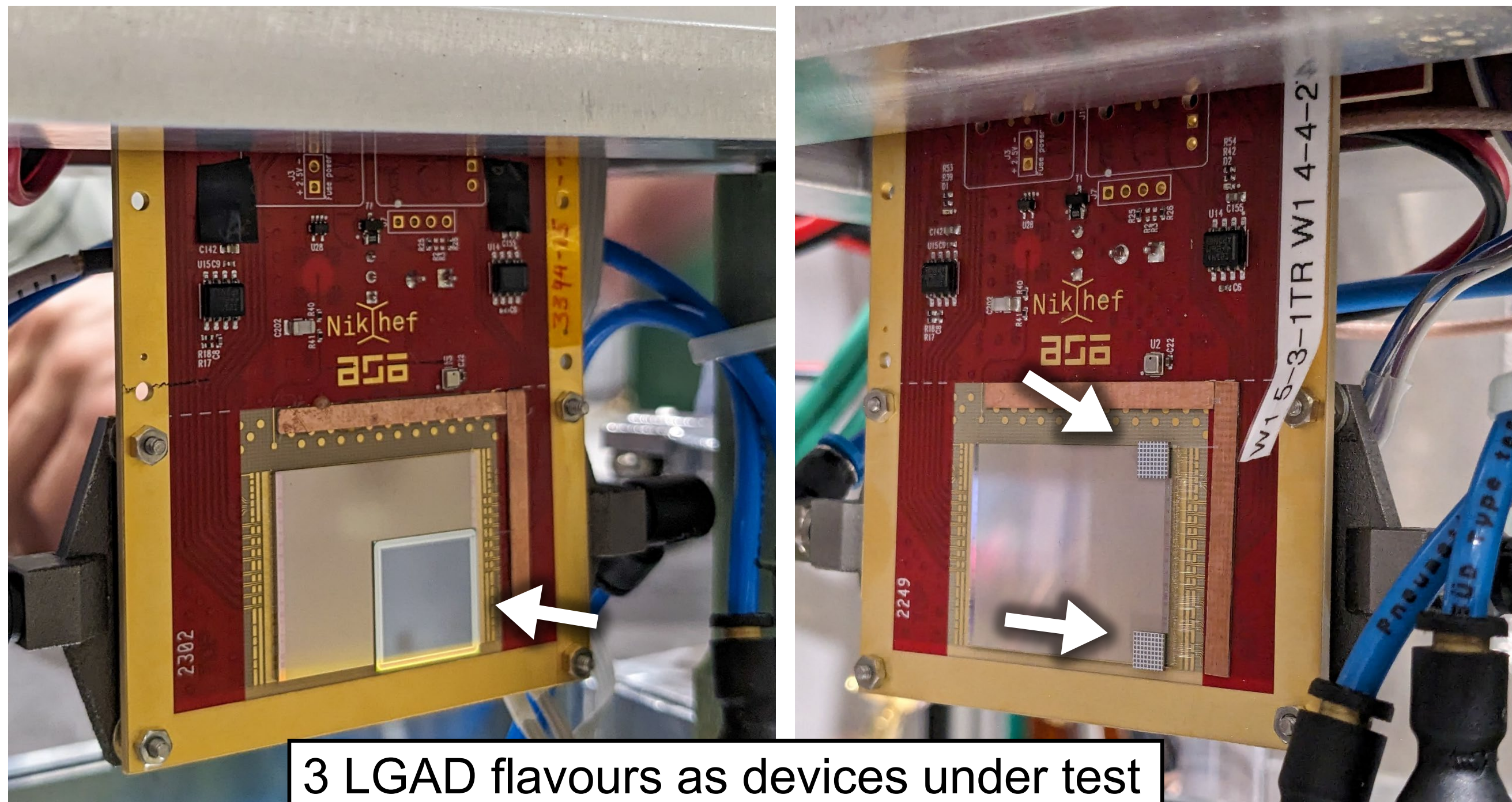
- Time reference to study telescope timing
- Considering installing Timpix4 plane to VETO events with nuclear interactions
- Current time resolution: 17 ps (single MCP)
- Combined MCP resolution: 12 ps





# Plane assemblies

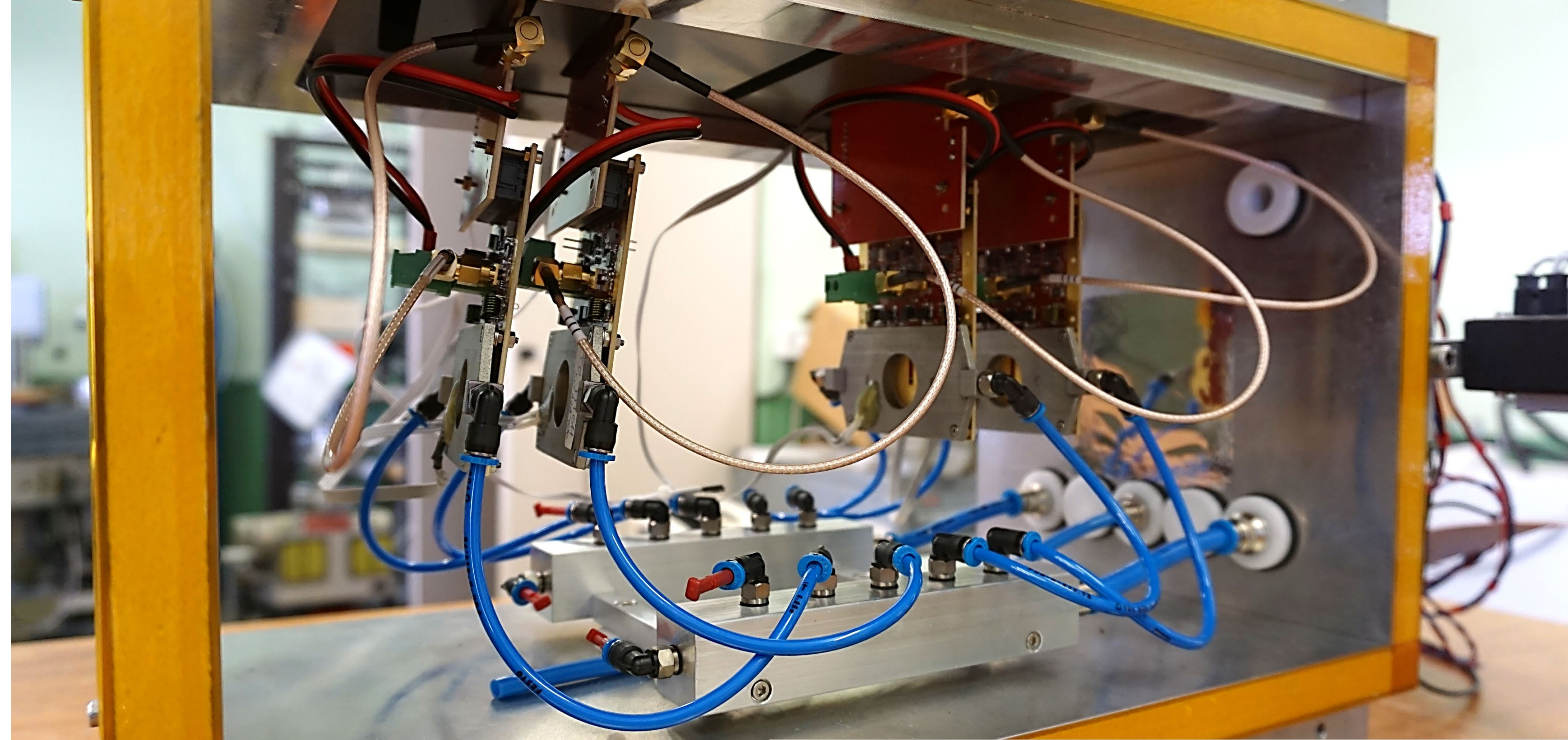
- Eight telescope planes with n-on-p planar silicon sensors
- 4 x 300  $\mu\text{m}$  sensors for spatial resolution (angled)
- 4 x 100  $\mu\text{m}$  sensors for time resolution (perpendicular)
- Sensor upgrades are anticipated (LGAD, 3D, ...)



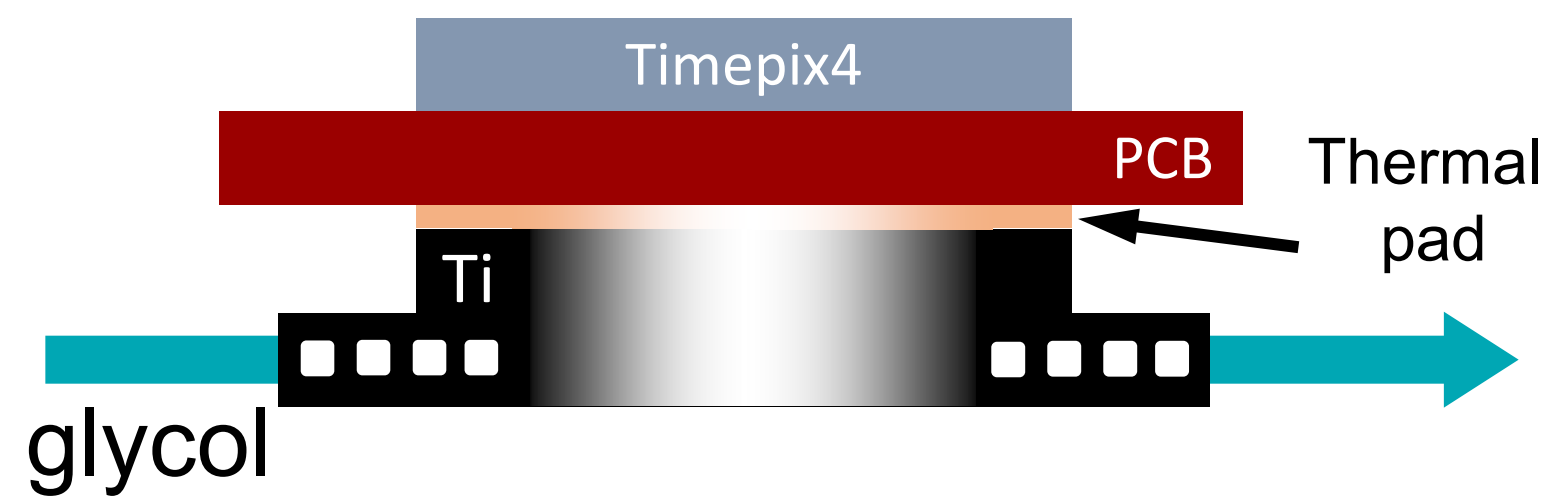


# Assembly cooling

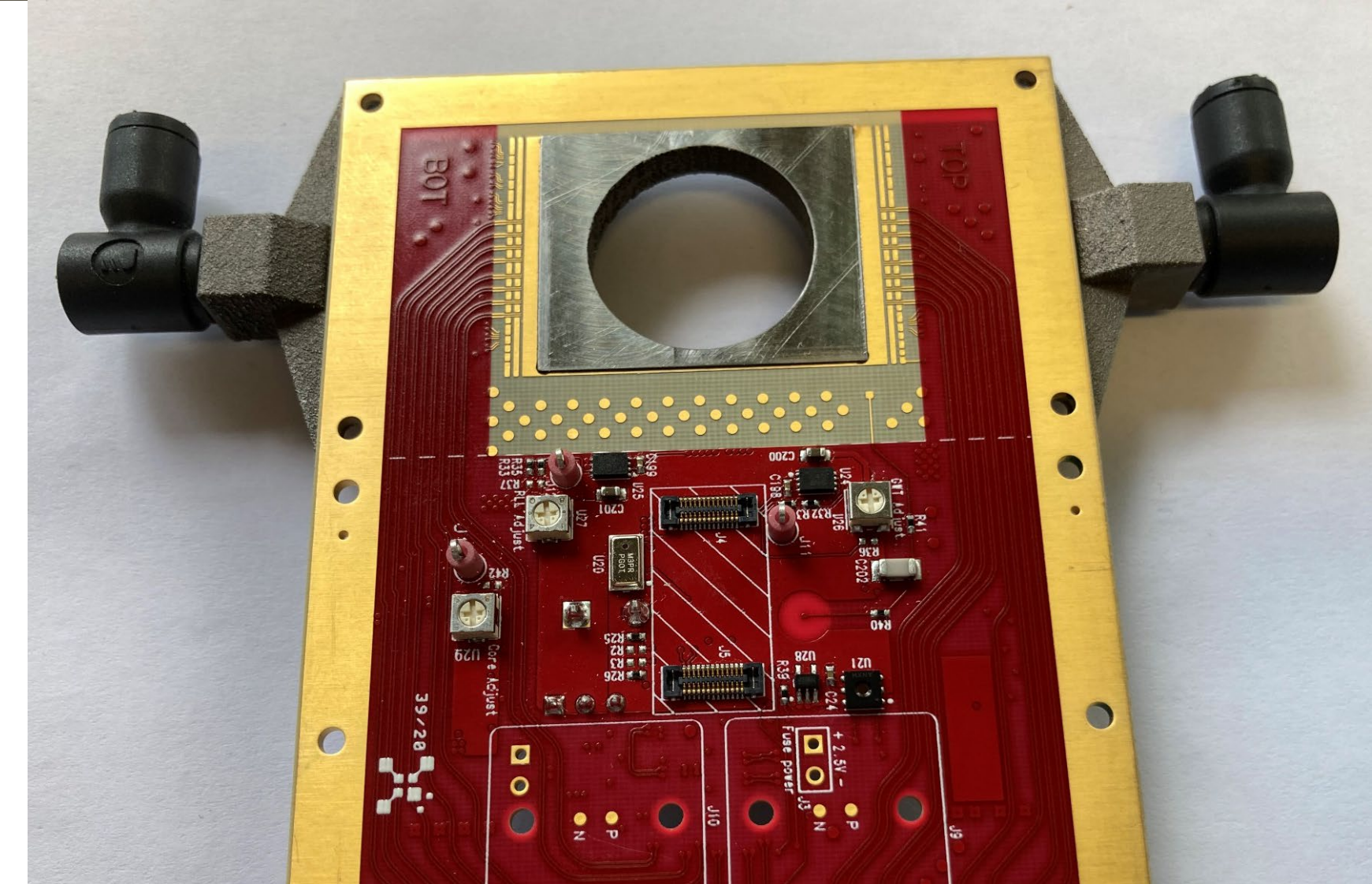
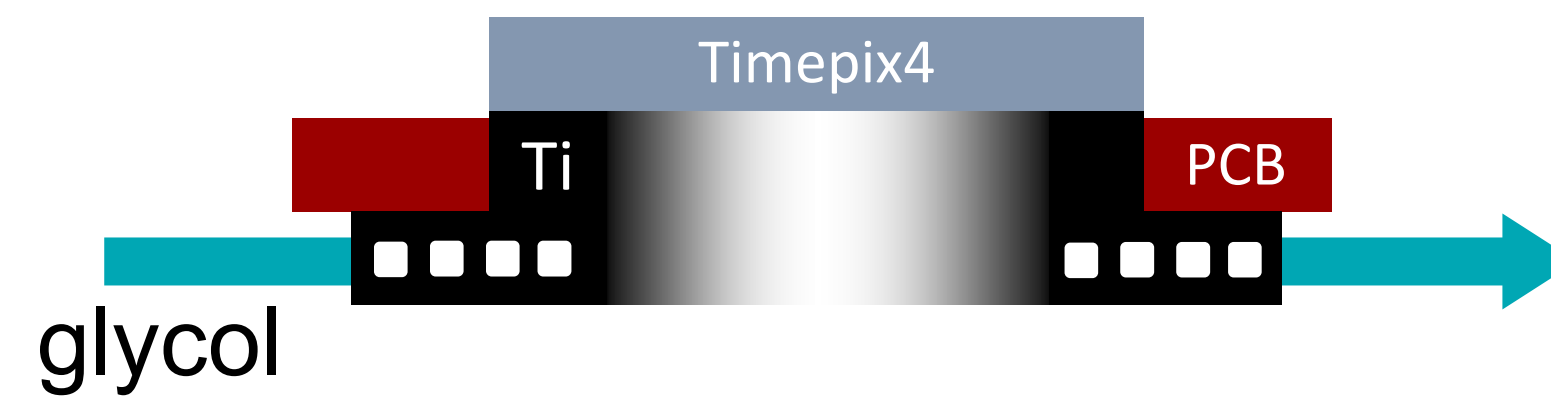
- All assemblies have a 3D-printed titanium cooling block
- Cooled using glycol at 20 °C
- Could go to -20 °C in the future
- Plan to mill PCB to have direct thermal contact with Timepix4



## Current thermal interface



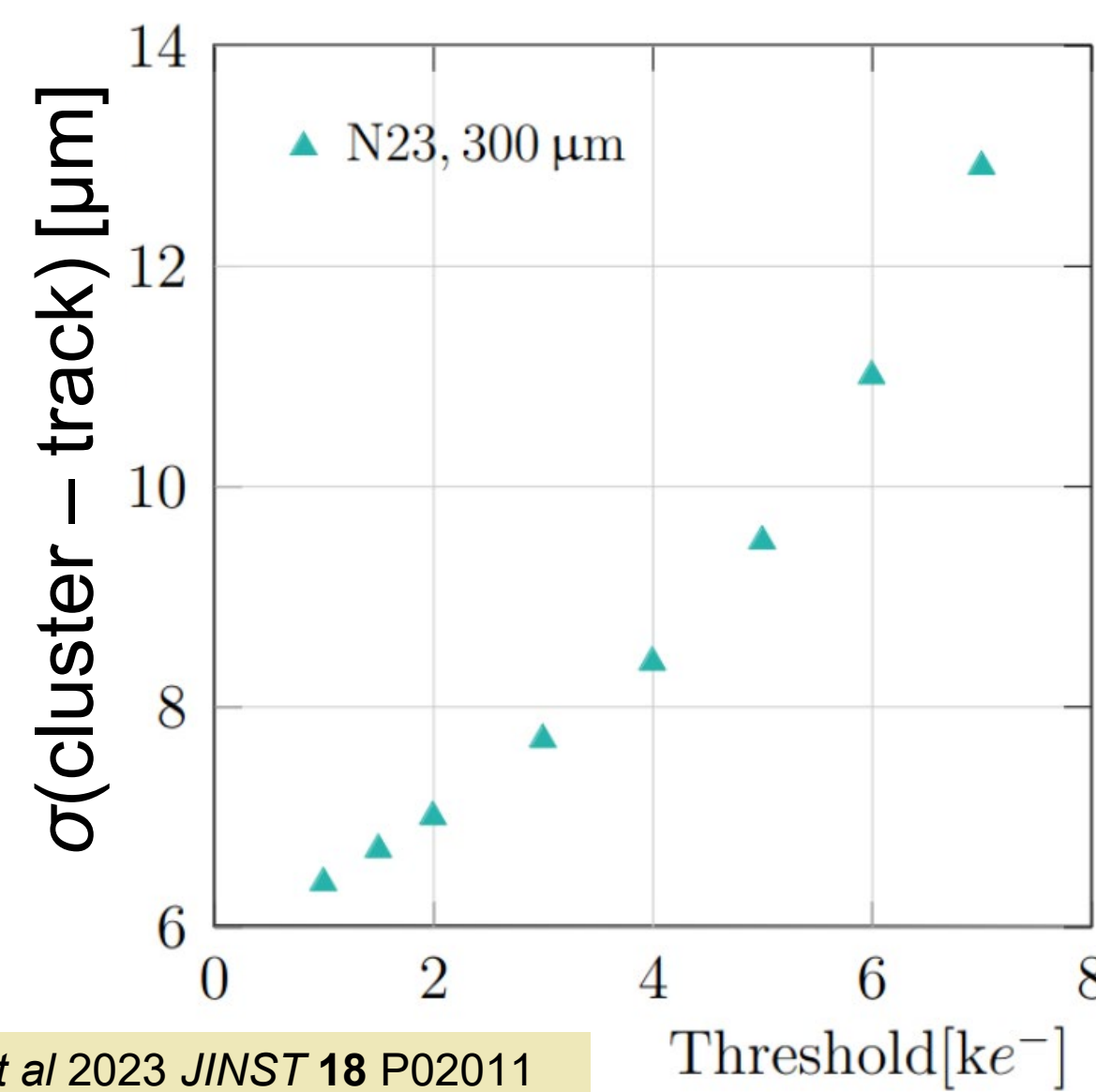
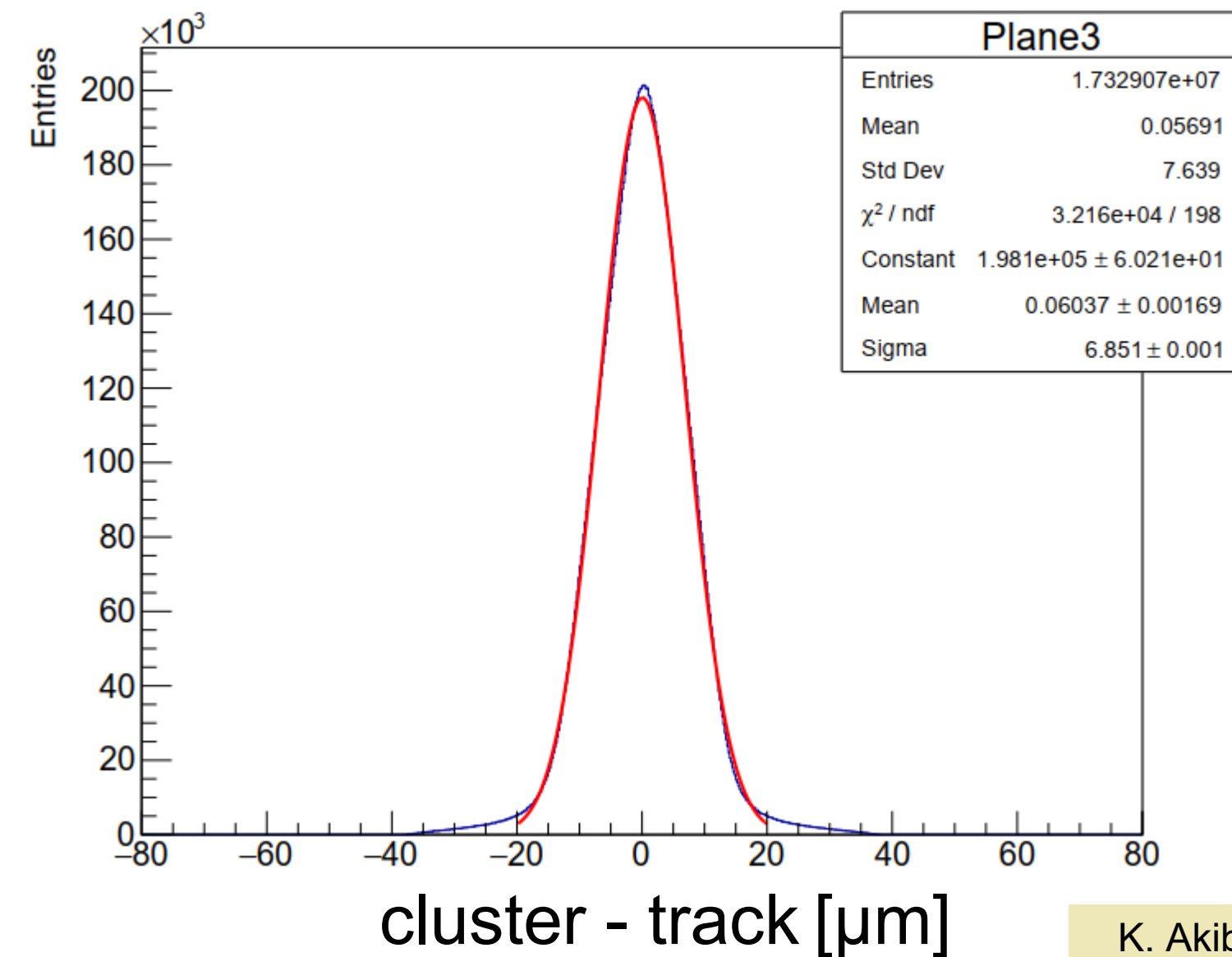
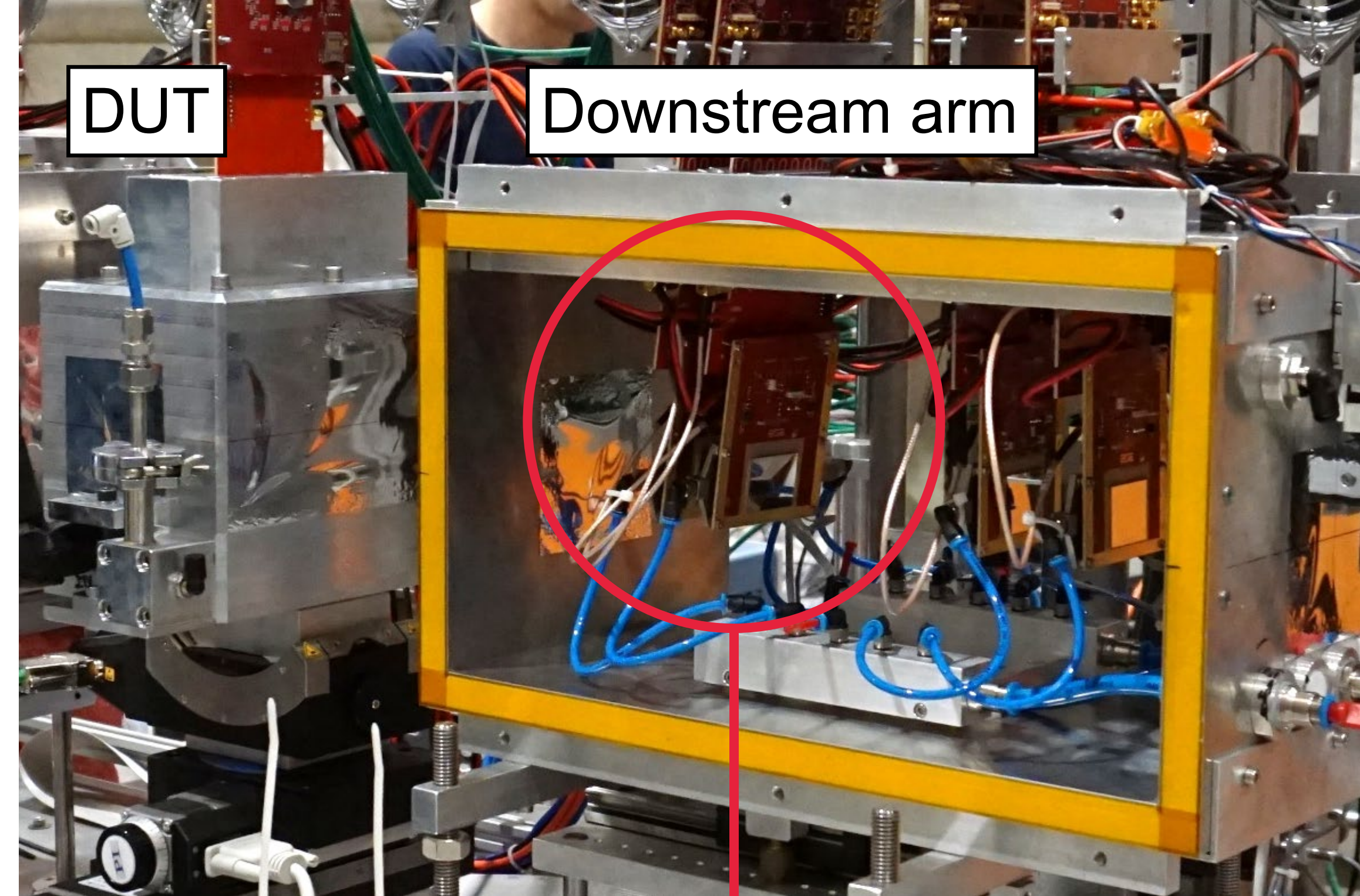
## Future thermal interface



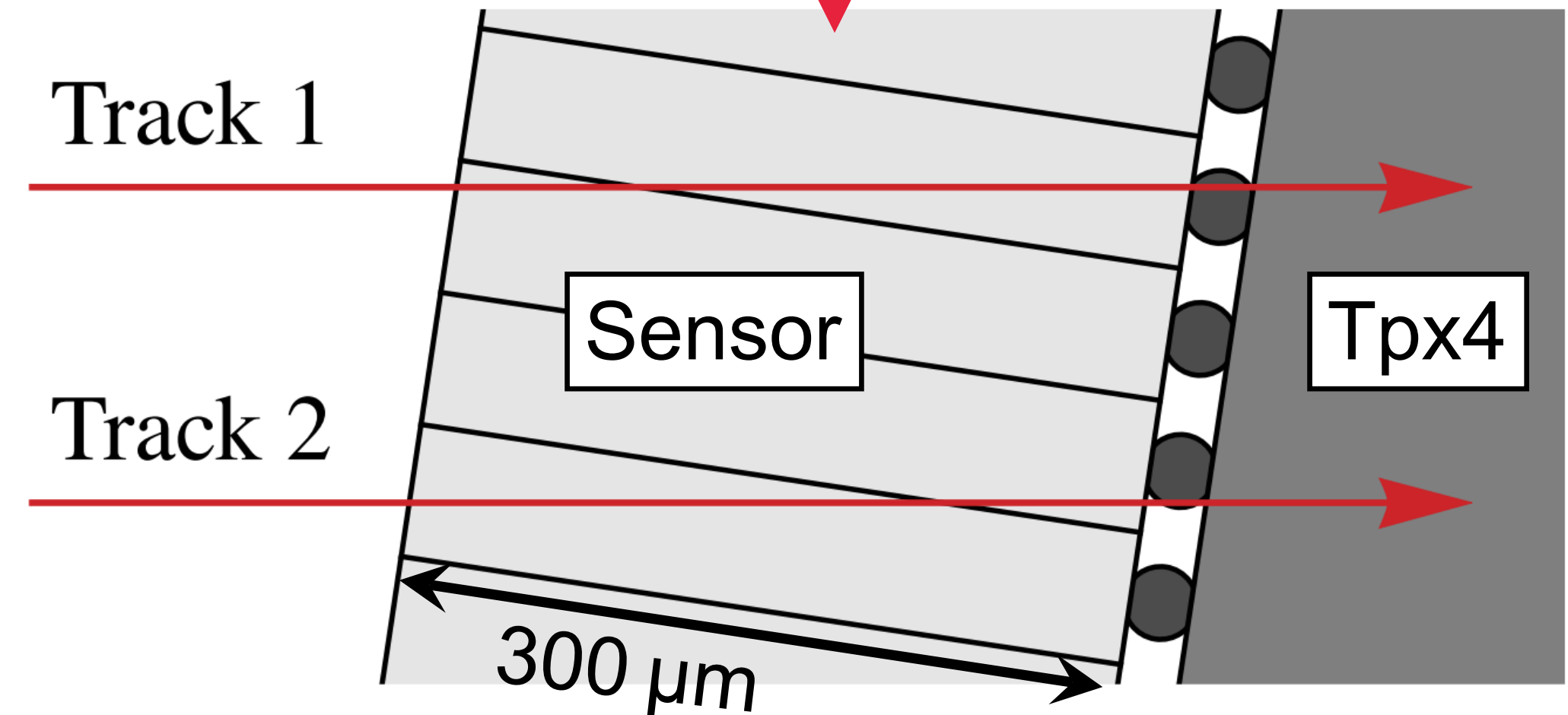


# Single plane spatial resolution

- Pixel size  $55 \mu\text{m} \times 55 \mu\text{m}$
- Four innermost planes rotated  $9^\circ$  around x and y to induce charge sharing between pixels
- Charge-weighted mean gives cluster position
- Single plane resolution:  **$3.3 \mu\text{m}$**
- Resolution depends on detection threshold



K. Akiba *et al* 2023 *JINST* **18** P02011  
[DOI: [10.1088/1748-0221/18/02/P02011](https://doi.org/10.1088/1748-0221/18/02/P02011)]

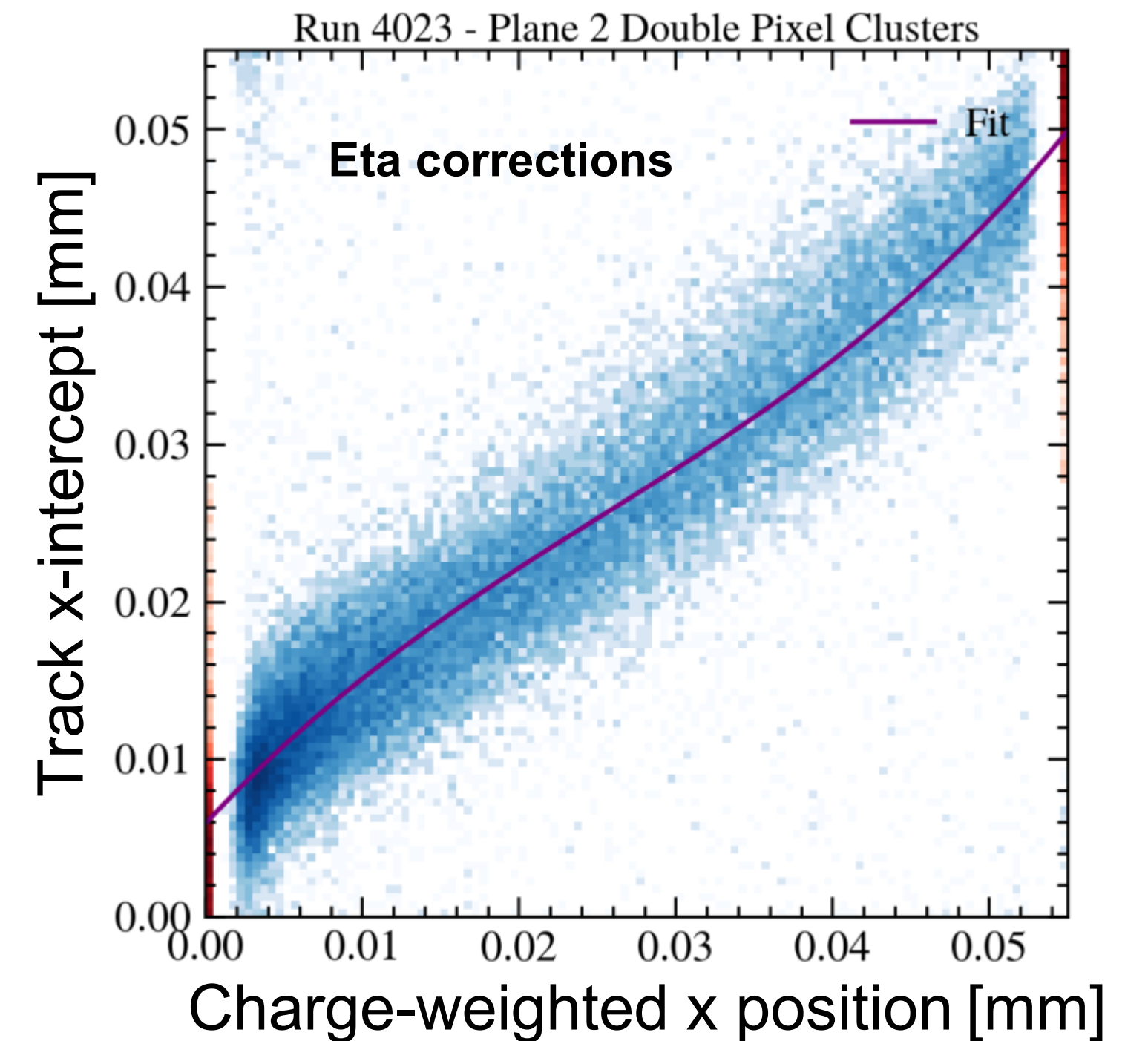
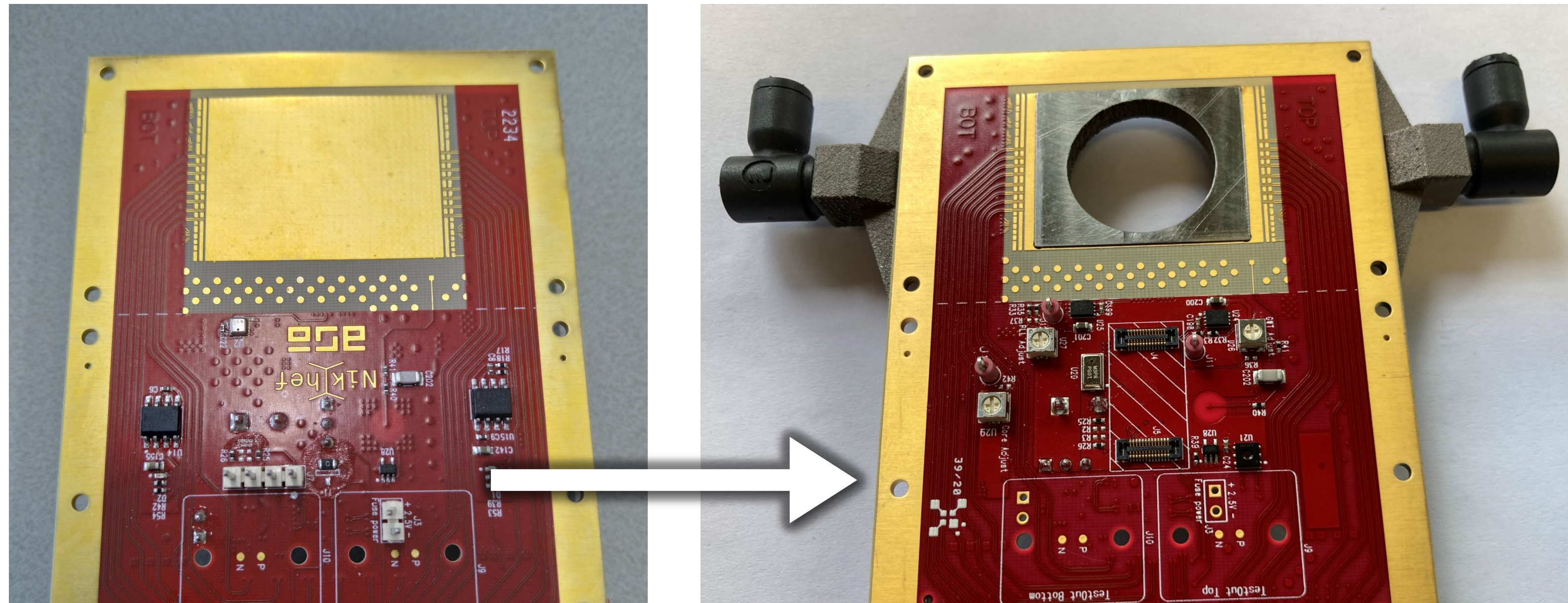
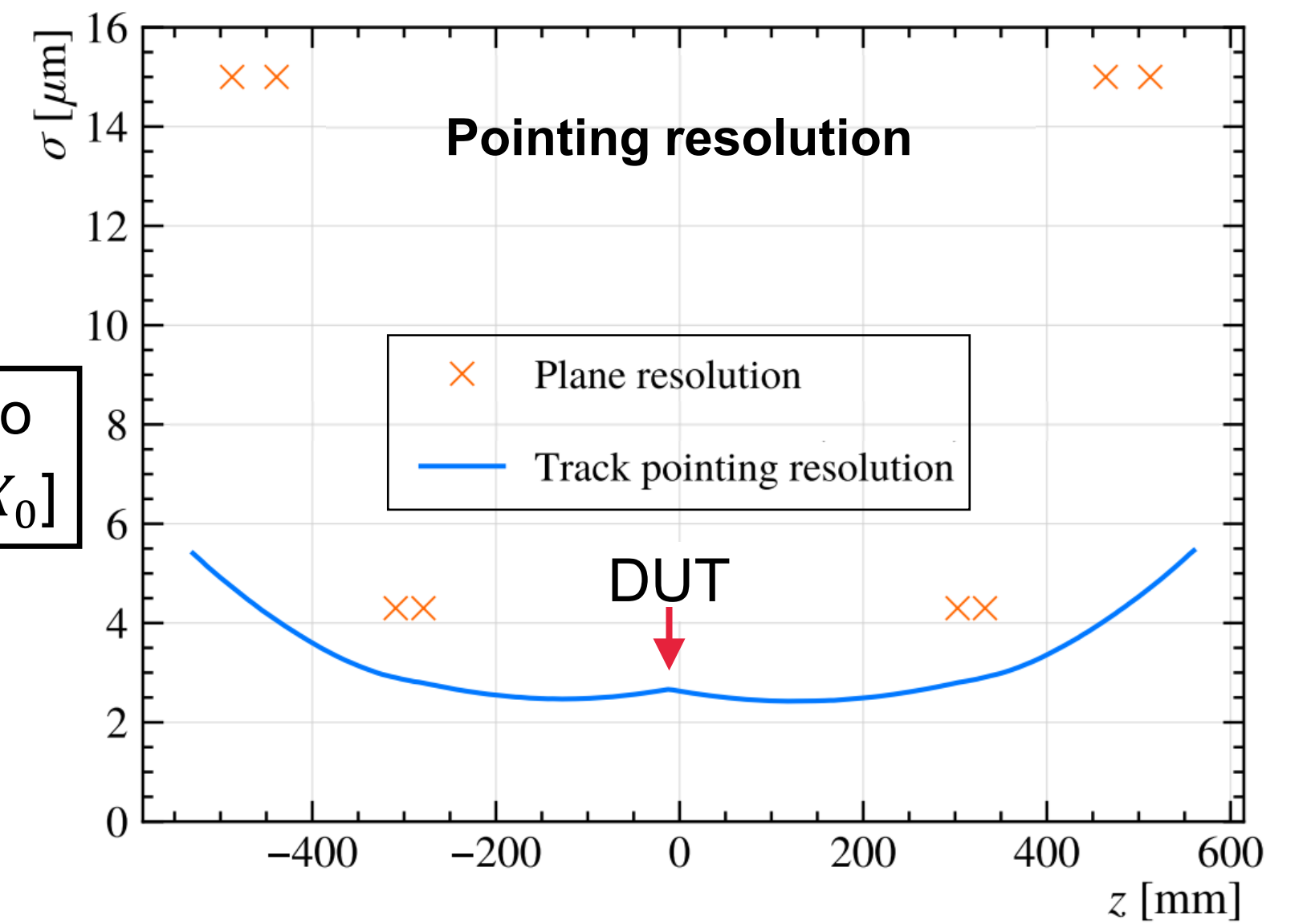




# Track pointing resolution

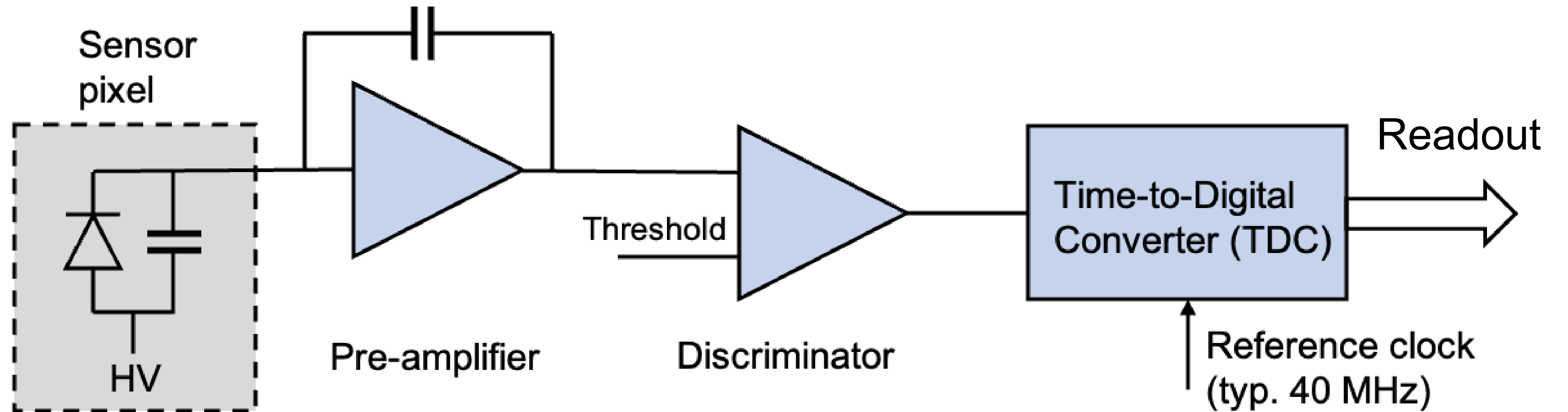
- Pointing resolution at DUT: **2.5  $\mu\text{m}$**  (Mixed hadron beam 180 GeV/c)
- PCB adds 1.8–2.4  $\%X_0$  (ASIC + sensor adds 0.7–1.0  $\%X_0$ )
- Milling out PCB would improve resolution to  $\sim 2.0 \mu\text{m}$
- Investigating “eta corrections” for nonlinear charge sharing
- Other possible improvements:
  - Move telescope arms further inward when possible
  - Operate 300  $\mu\text{m}$  planes at lower detection threshold
  - Add additional thick planes

Scattering proportional to  $\sqrt{x/X_0} [1 + 0.038 \log x/X_0]$





# Time measurements in pixel detectors



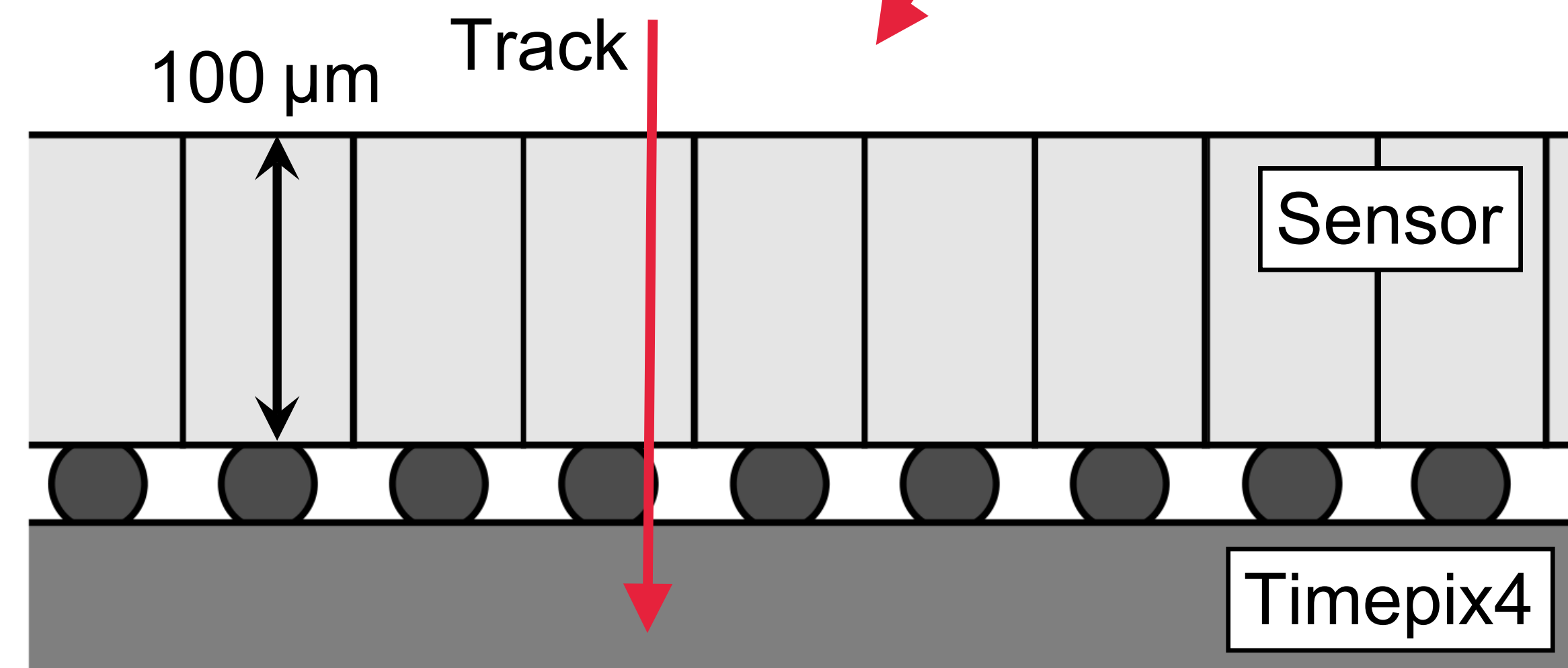
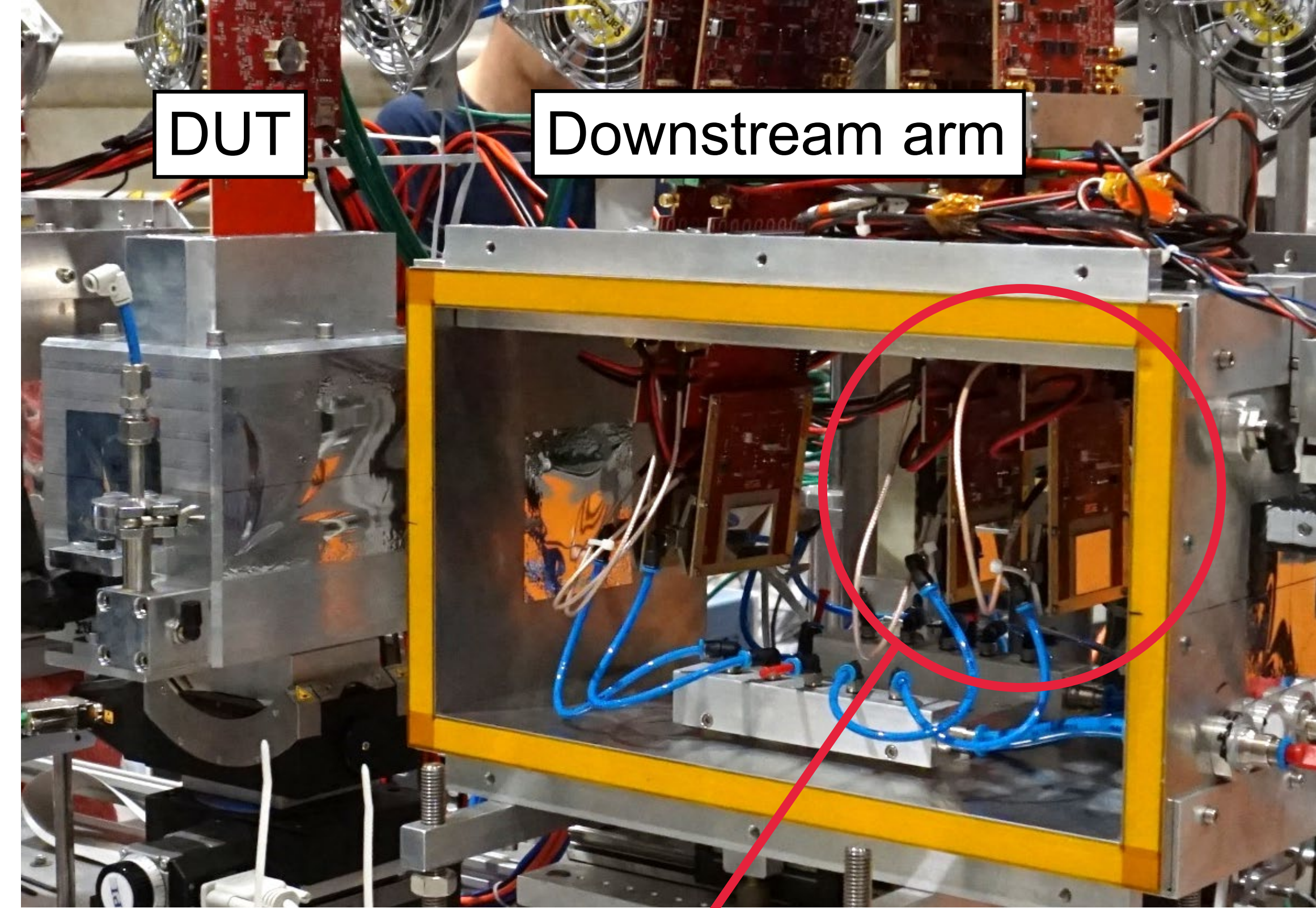
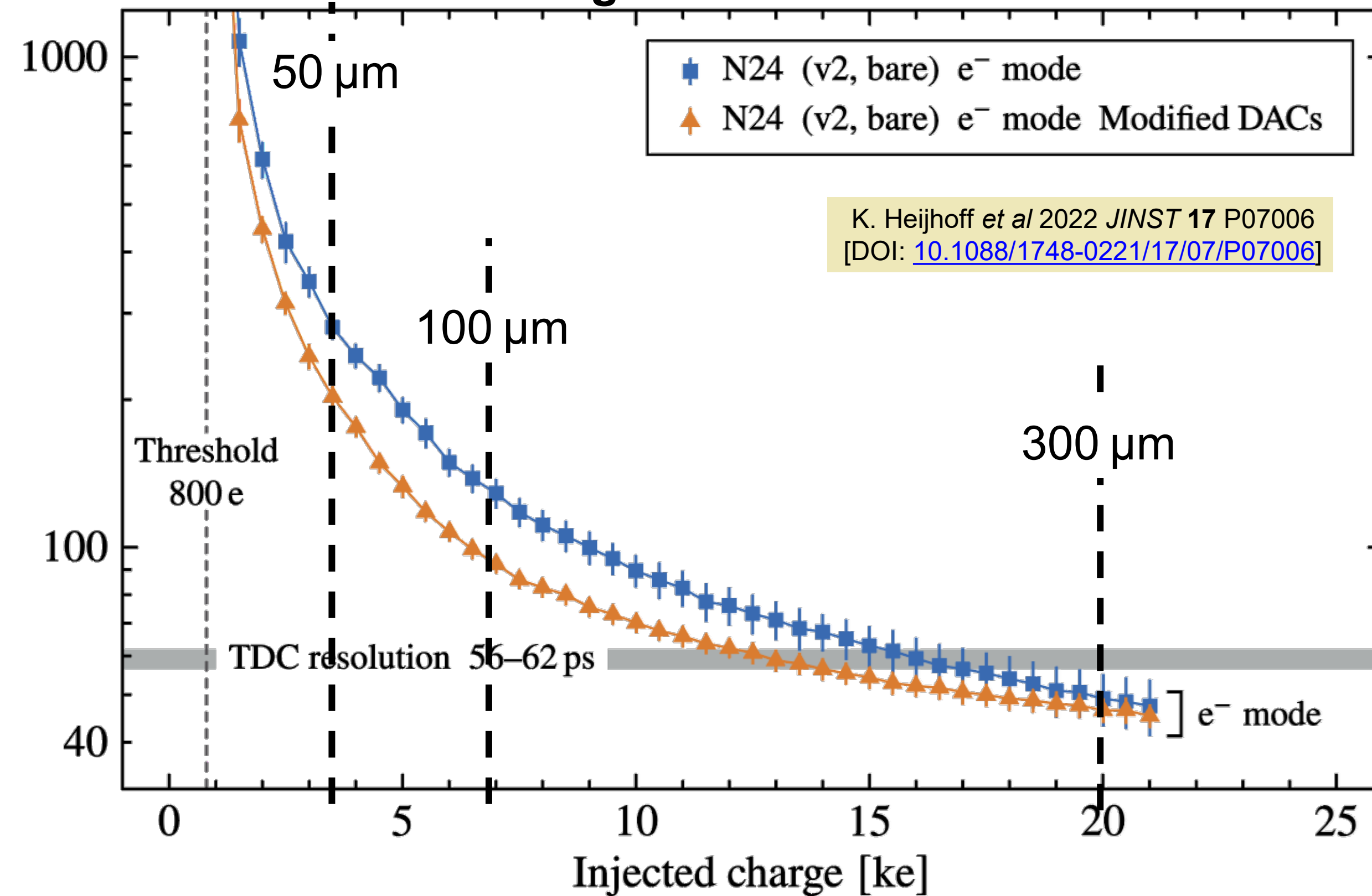
$$\text{Time resolution} = \sigma_t^2(\text{sensor}) + \underbrace{\sigma_t^2(\text{jitter}) + \sigma_t^2(\text{timewalk})}_{\text{Pre-amplifier and Discriminator}} + \sigma_t^2(\text{TDC})$$



# Single plane time resolution

- Thin sensors reduce time errors due to Landau fluctuations
- Perpendicular to beam to maximise signal charge in single pixel
- Reduced signal size reduces analog front-end performance

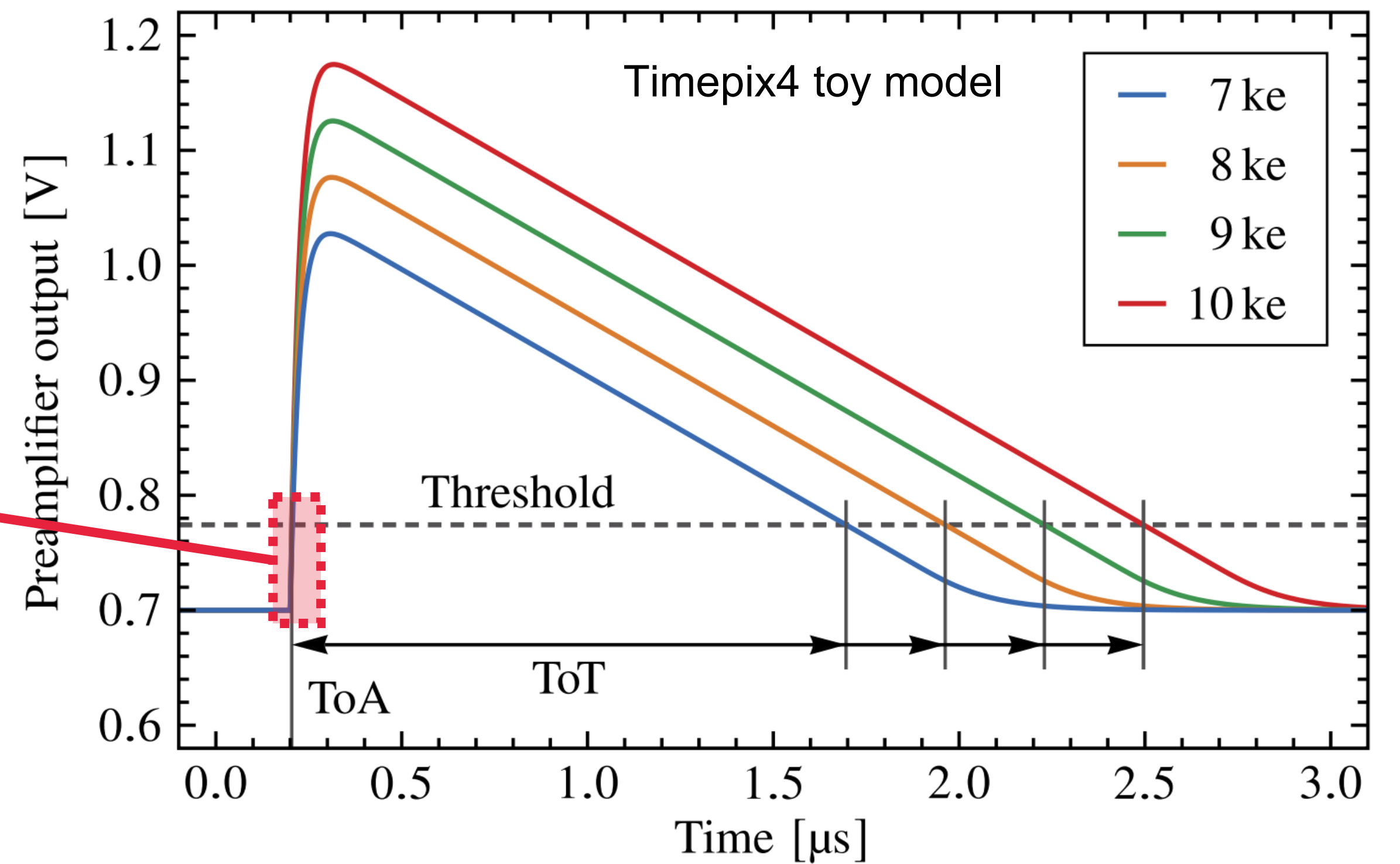
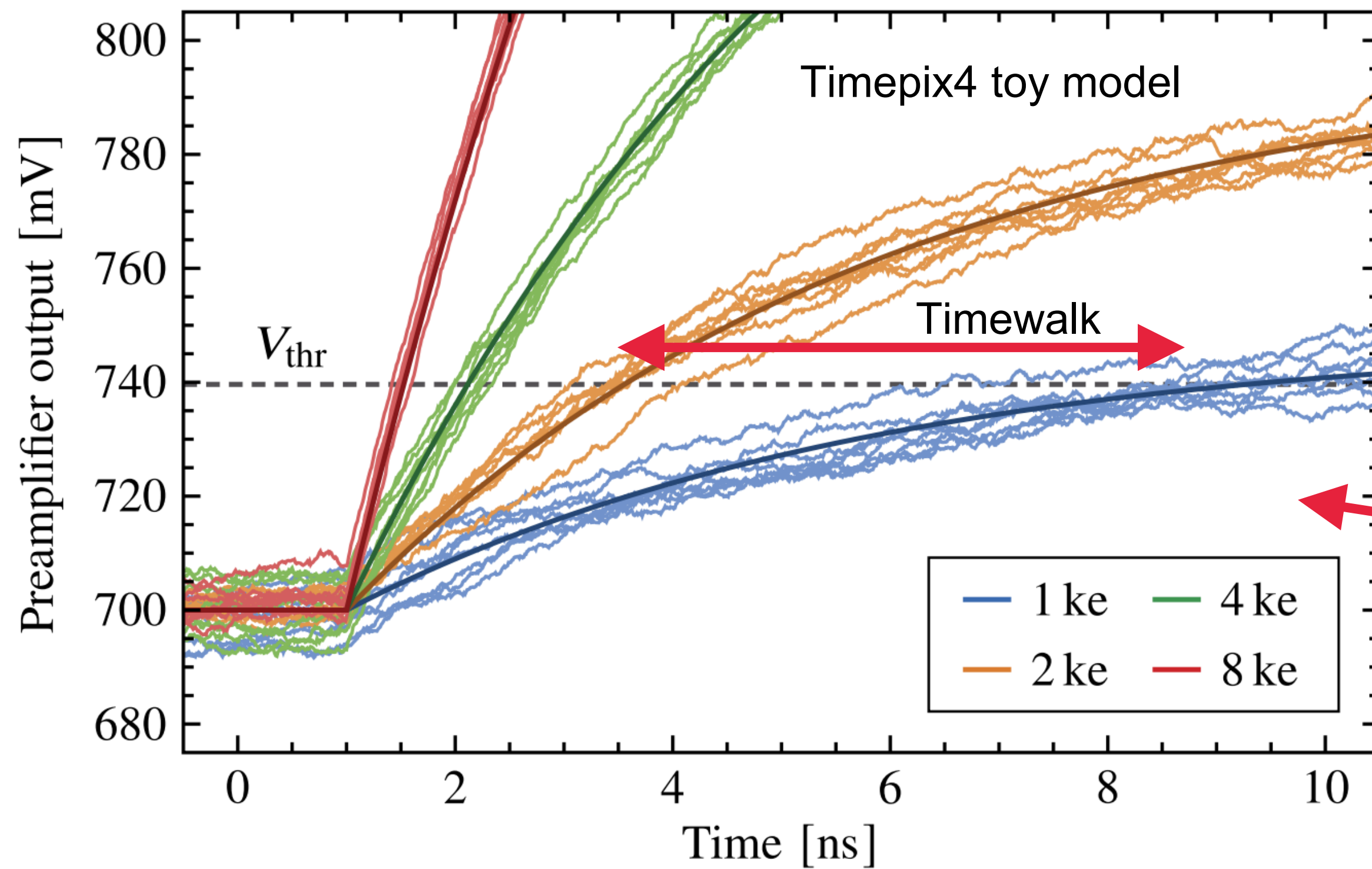
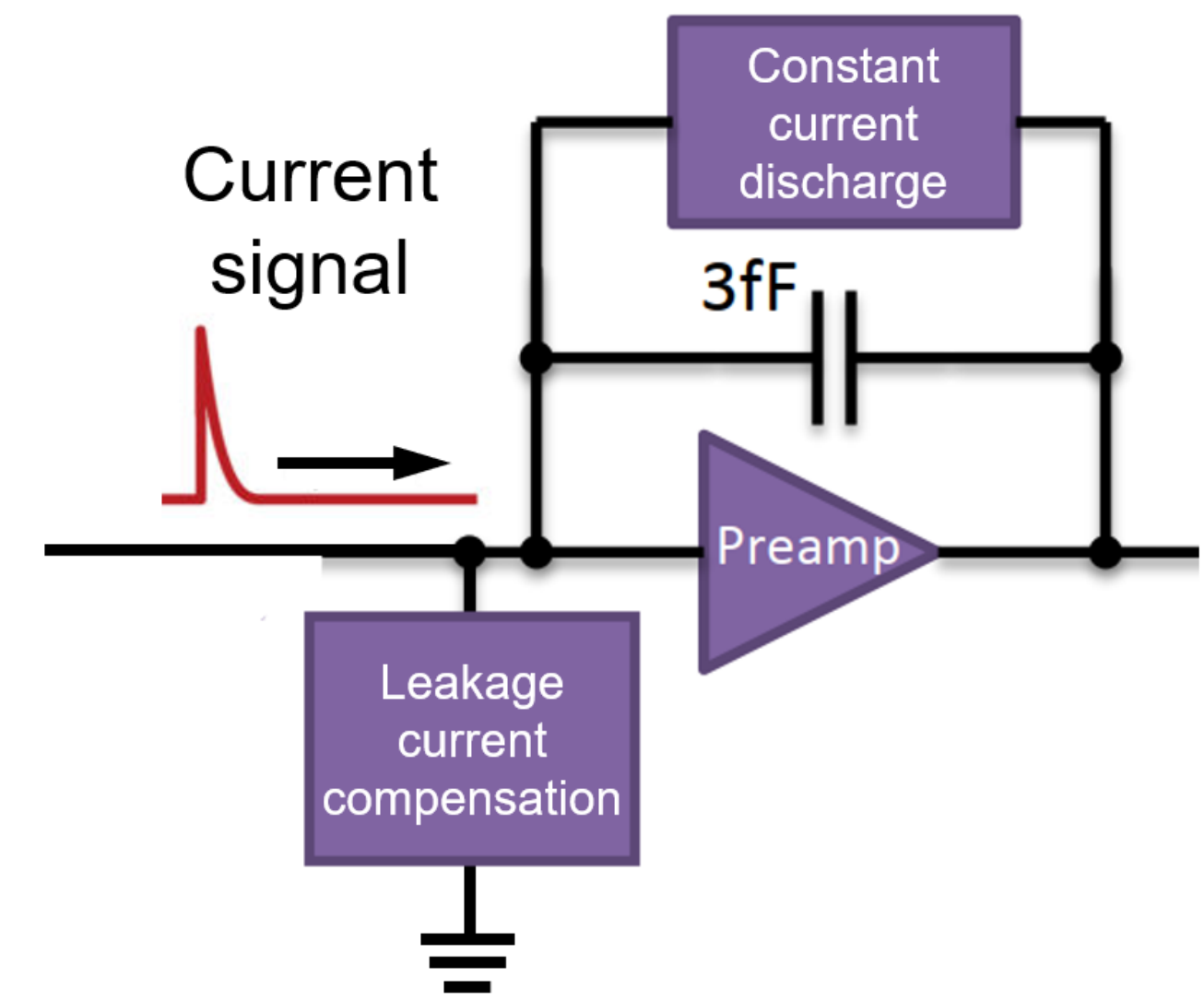
### Analog front-end resolution





# Timewalk

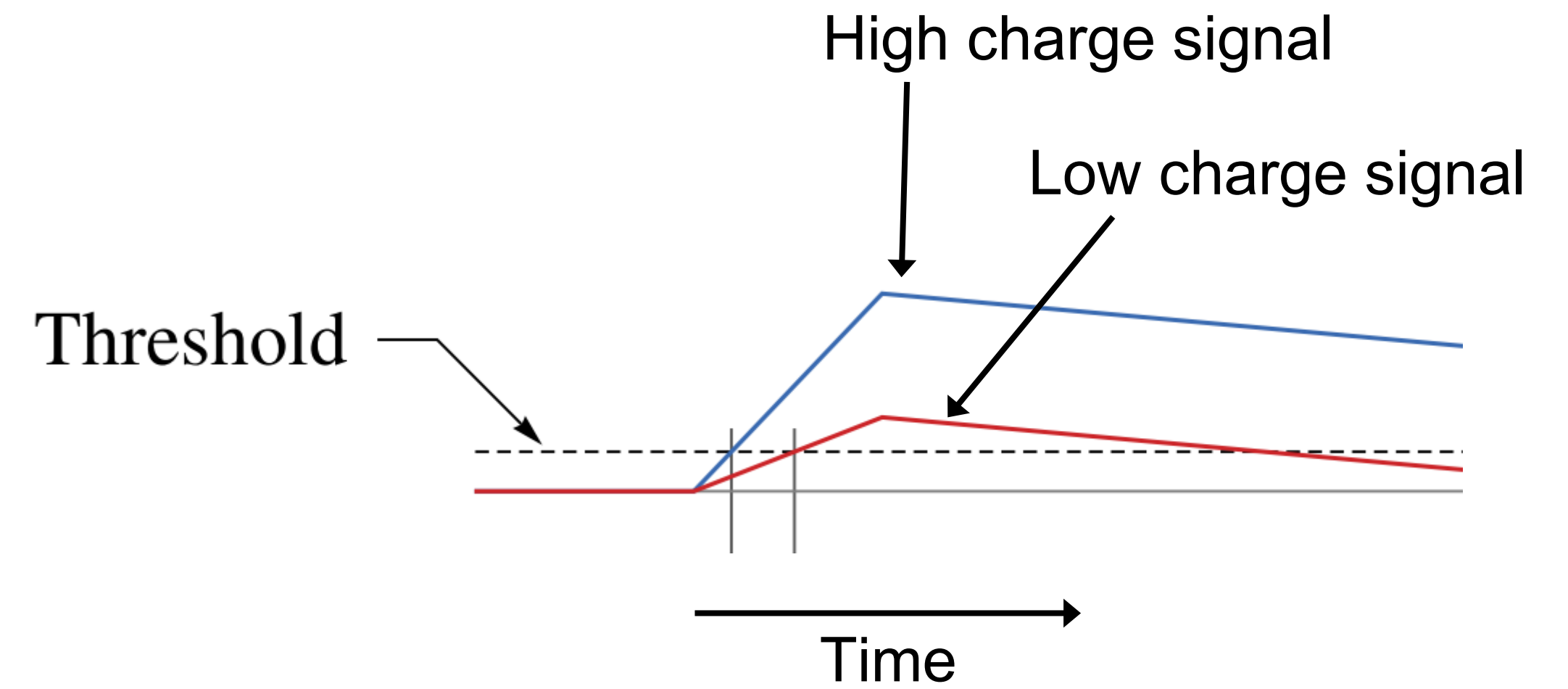
- Time measurement depends on signal size
- Preamplifier output has a fixed risetime
- Reduced signal size makes timewalk corrections crucial



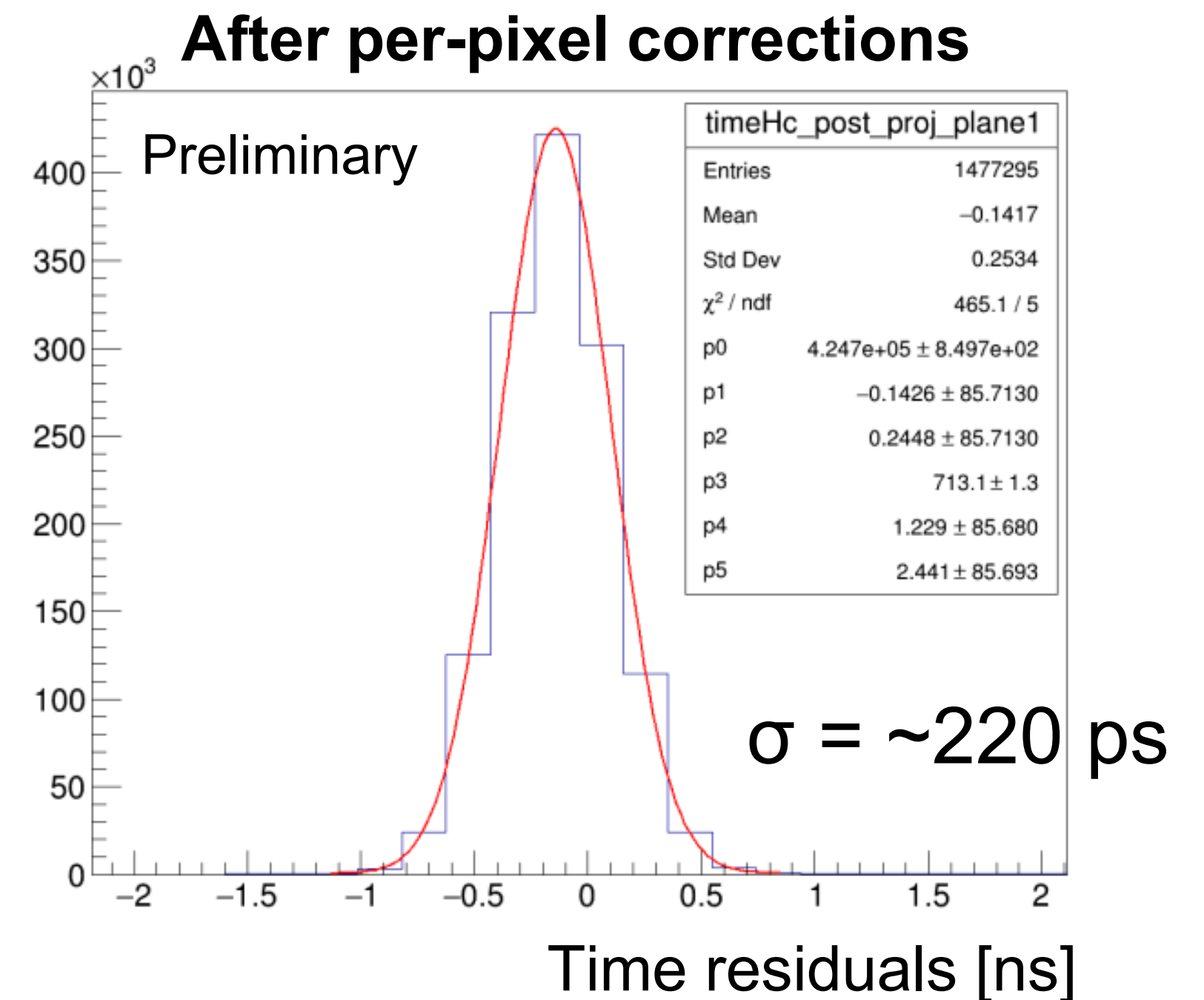
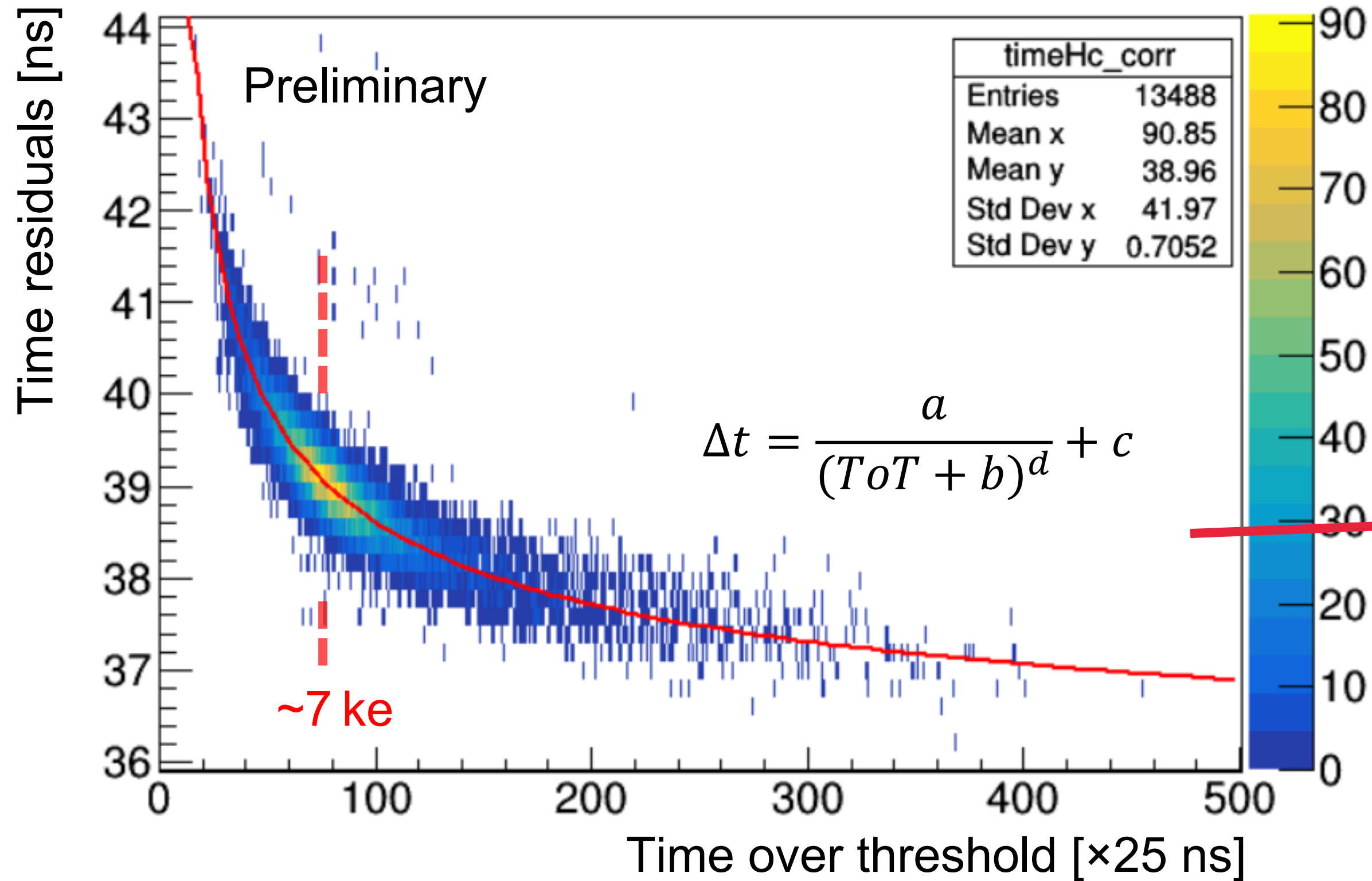


# Single plane time resolution

- Per-pixel timewalk corrections are applied
- Improves Time resolution:  $\sim 500$  ps  $\rightarrow$   $\sim 220$  ps
- Next: clock corrections to improve further

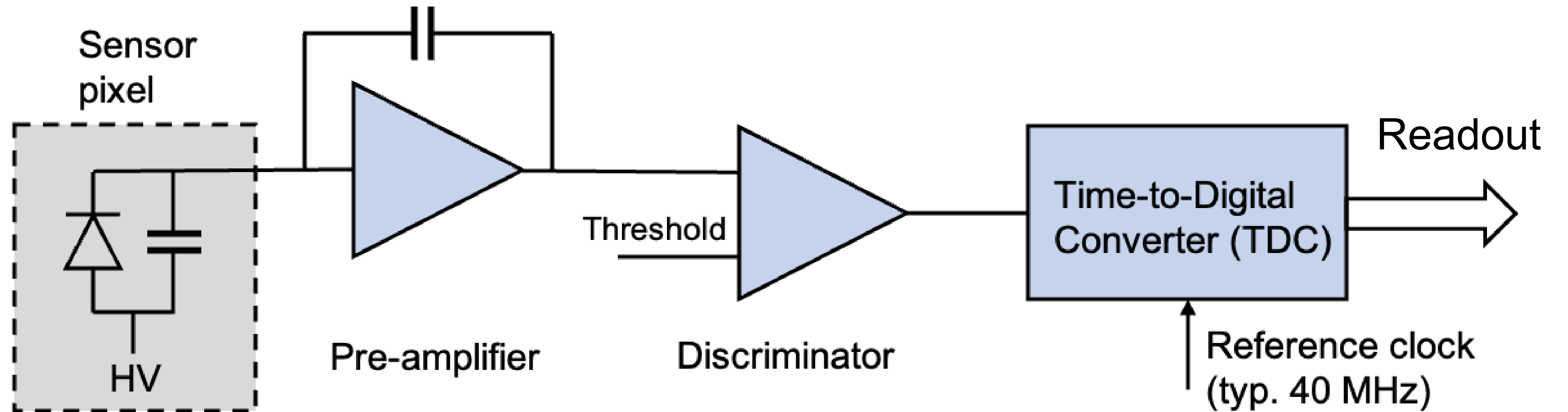


Single pixel timewalk





# Time measurements in pixel detectors

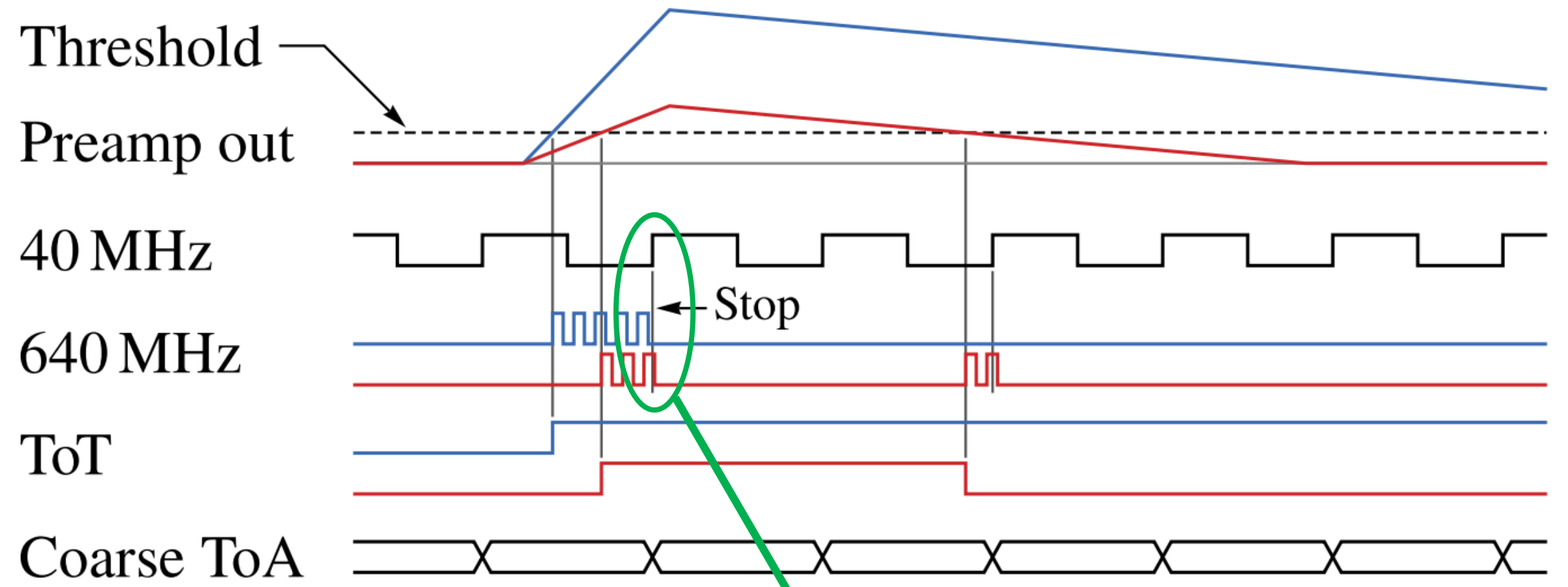
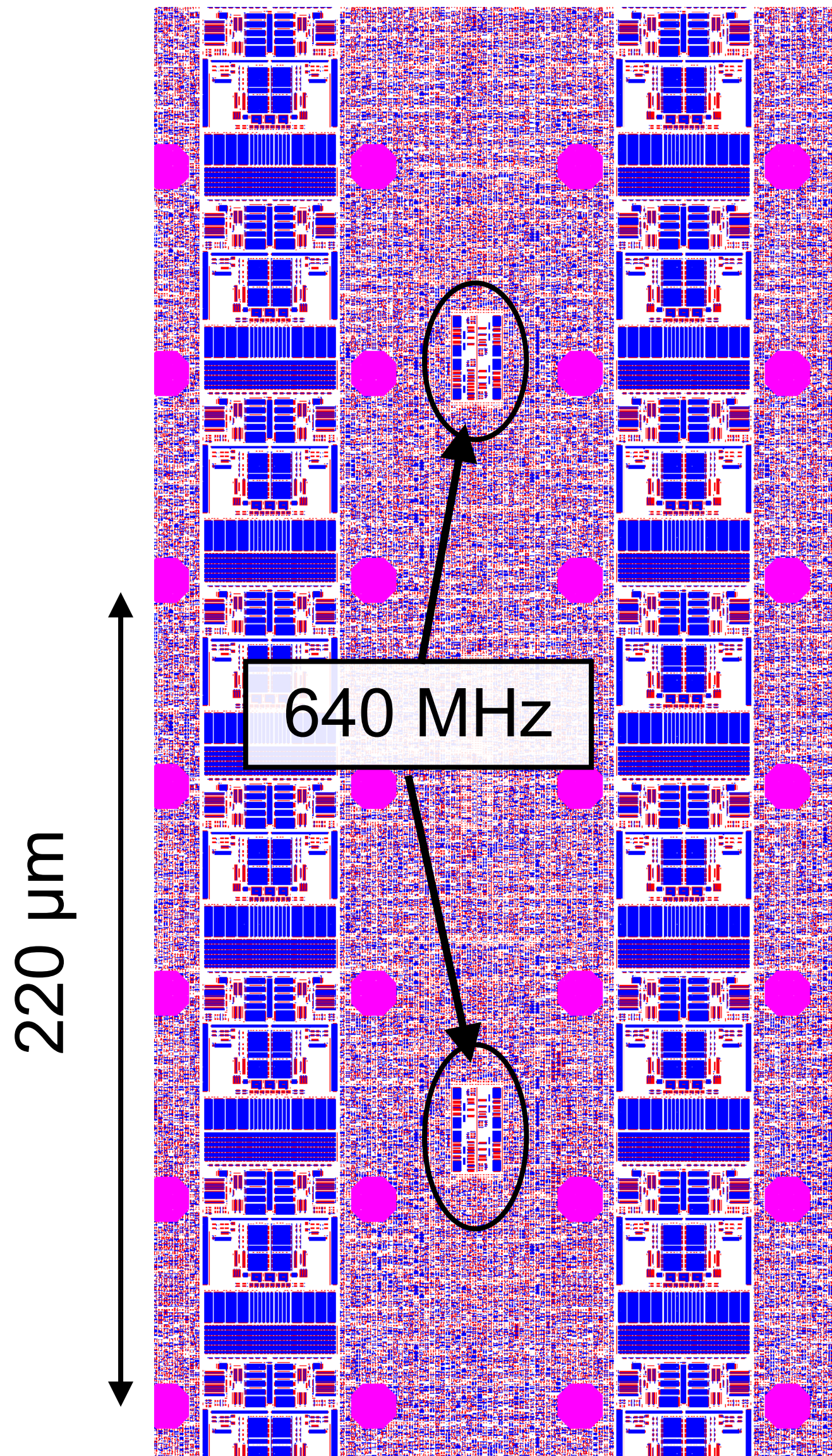


$$\text{Time resolution} = \sigma_t^2(\text{sensor}) + \underbrace{\sigma_t^2(\text{jitter}) + \sigma_t^2(\text{timewalk})}_{\text{}} + \sigma_t^2(\text{TDC})$$

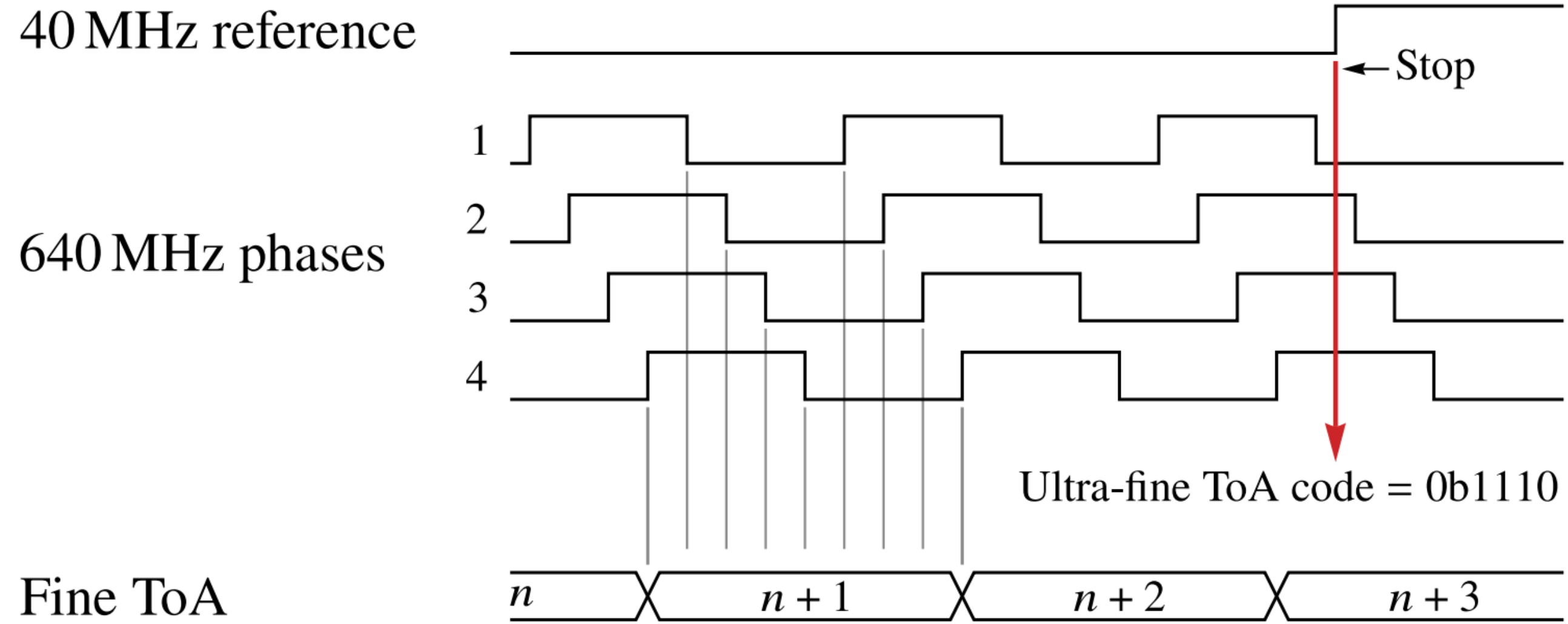


# Time measurement in Timepix4

# Coarse and fine time measurement – 40 MHz and 640 MHz



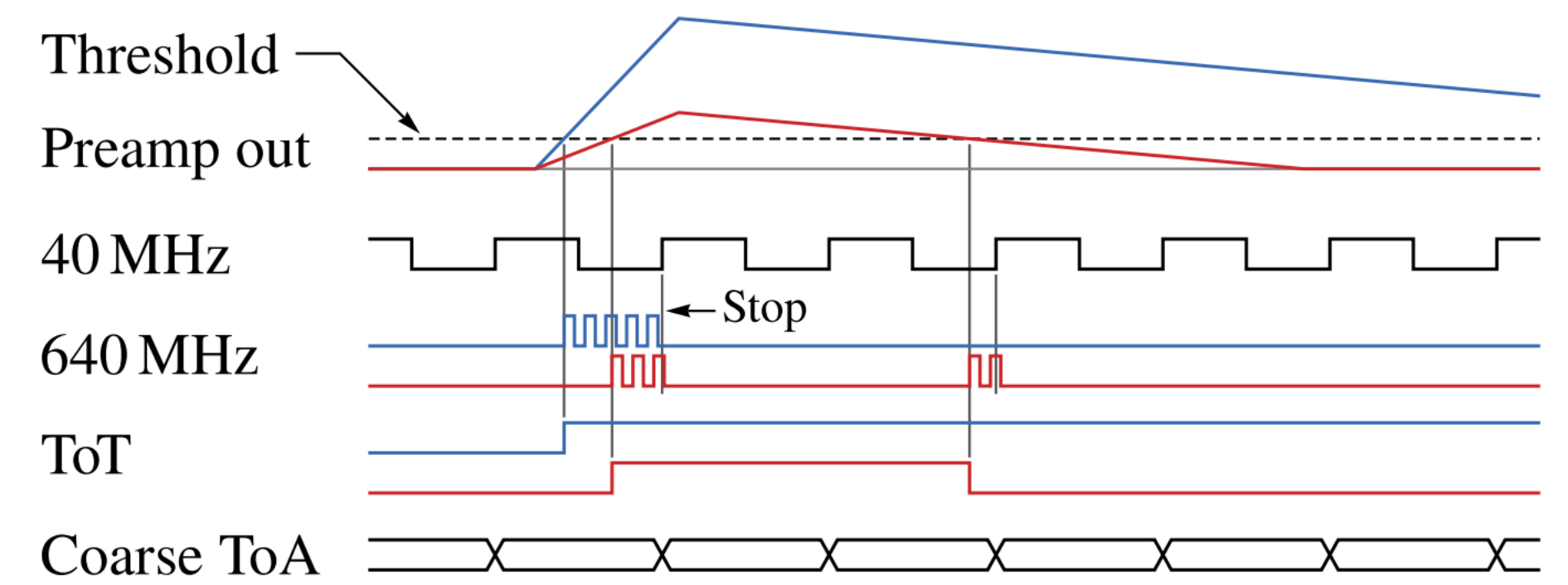
## Ultrafine time measurement – 195 ps



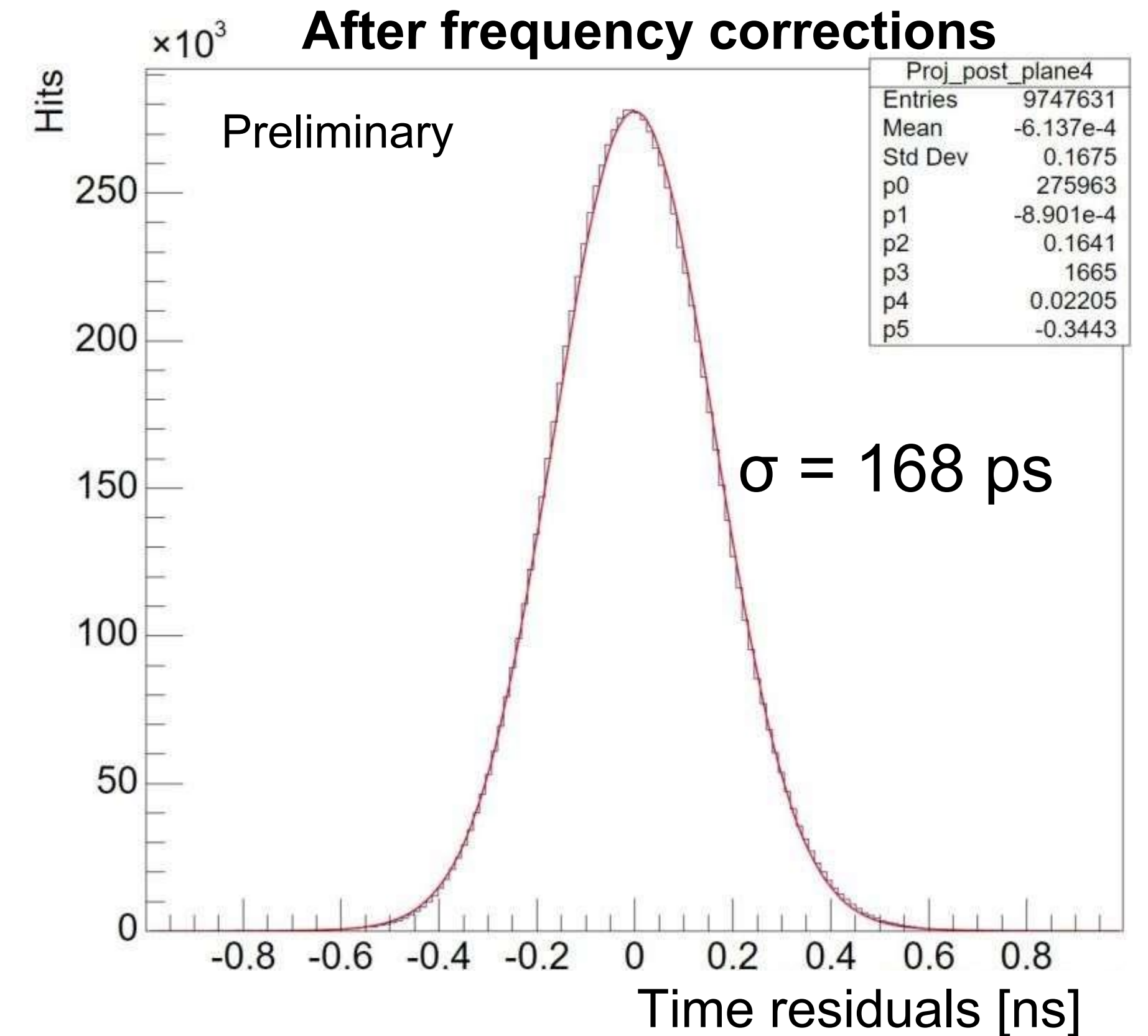
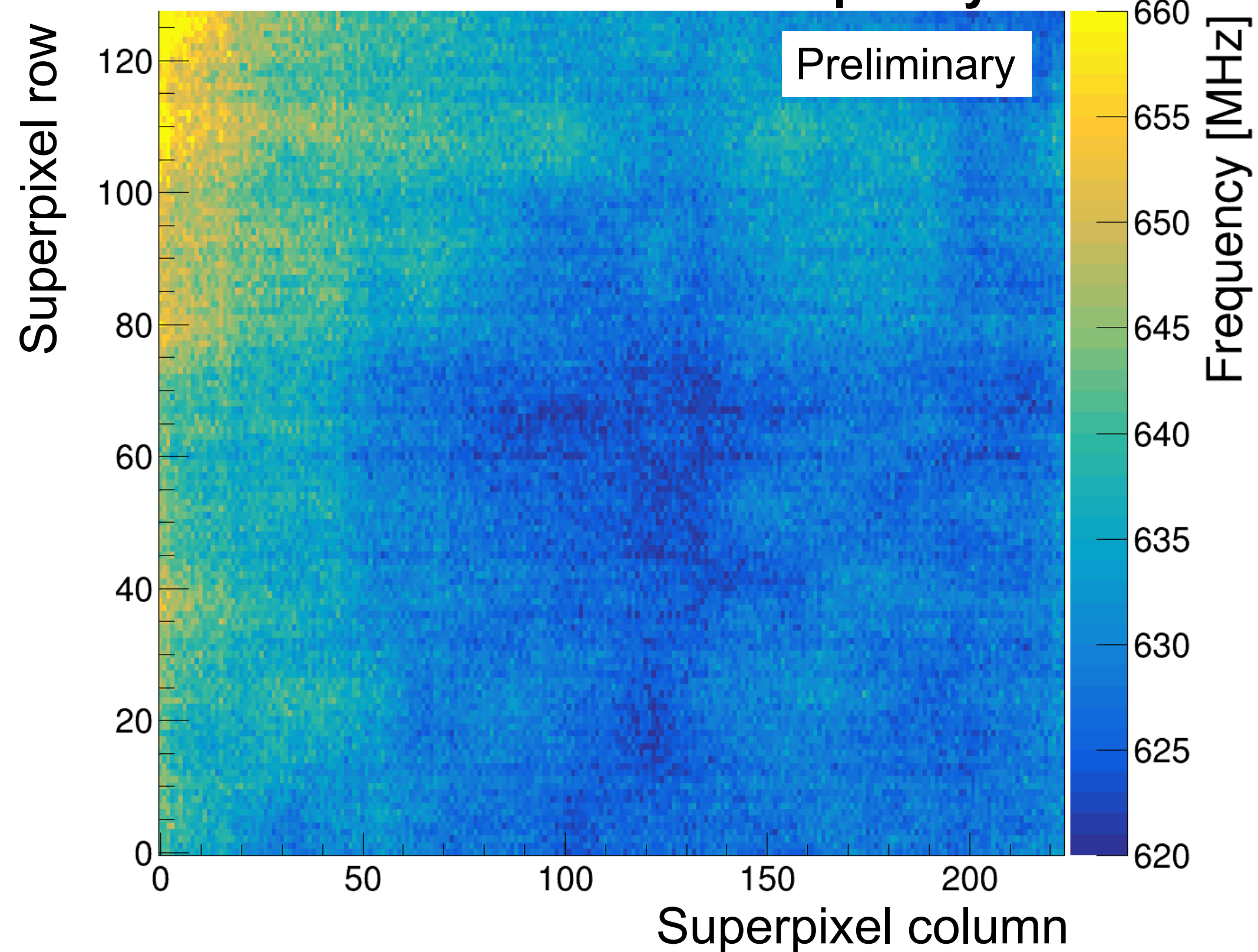


# Time resolution

- VCO frequency must also be calibrated for each superpixel
- Variations are due to design constraints
- Improves single-plane time resolution to:  $\sim 170$  ps
- Four timing planes  $\rightarrow$  90 ps track time resolution



### Variations in clock frequency



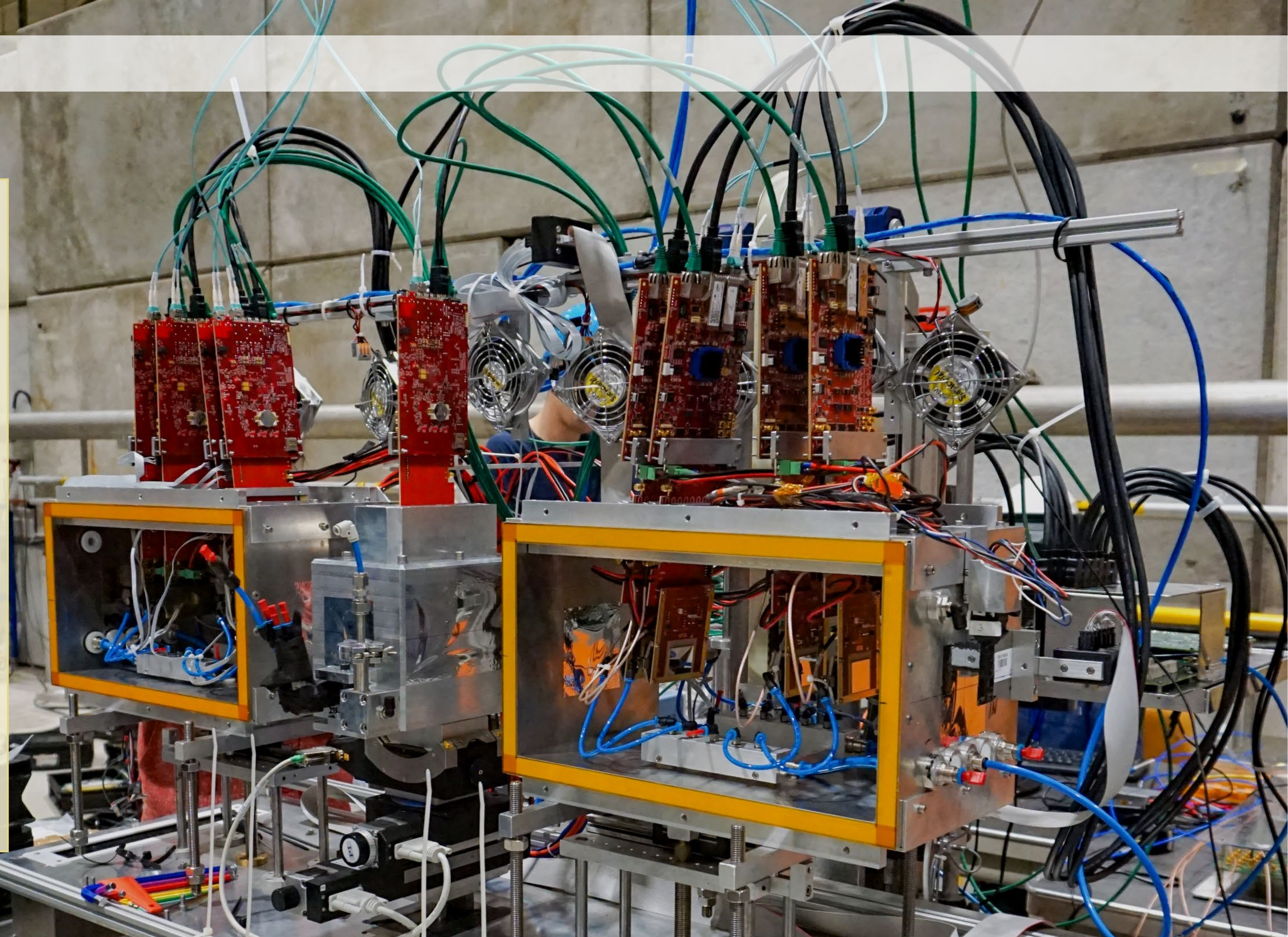


## Only telescope to simultaneously have

- Good spatial resolution
- Precise time measurements
- High-rate capability

## Next:

- Study fast sensors!  
(Actually started last week)
- Upgrade timing planes  
(30 ps track time resolution)
- Or maybe  
fully equip with 3D sensors  
(20 ps track time resolution??)





# People involved

## Testbeam crew

*Nikhef*: Kazu Akiba, Martin van Beuzekom, Tjip Bischoff, Evridiki Chatzianagnostou, Robbert Geertsema, Kevin Heijhoff, Uwe Kraemer, Daan Oppenhuis, Ganrong Wang

*CERN*: Federico De Benedetti, Wiktor Byczynski, Victor Coco, Raphael Dumps, Mohammadtaghi Hajheidari

*IGFAE*: Edgar Lemos Cid, Efrén Rodríguez Rodríguez

*TU Dortmund*: Elena Dall'Occo, David Rolf

*University of Manchester/CERN*: Tim Evans

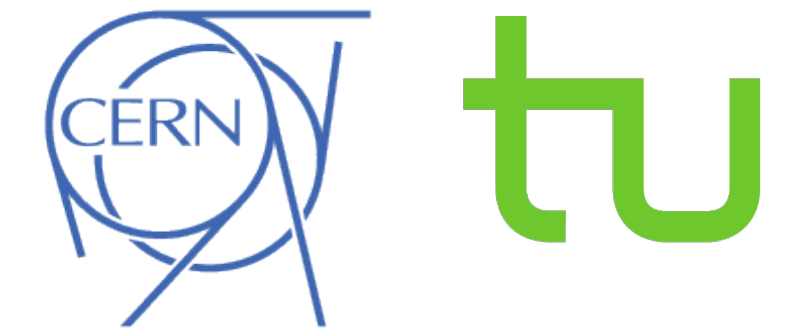
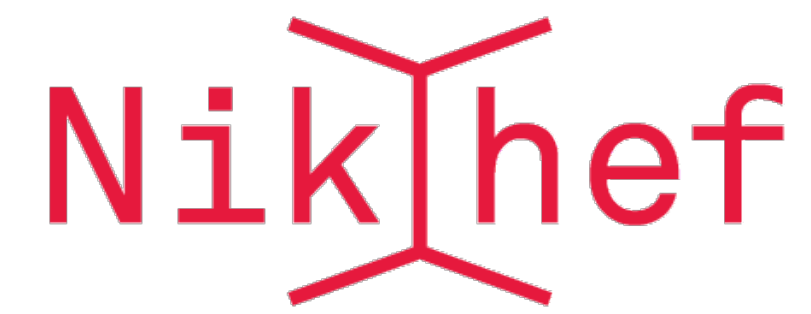
*University of Oxford*: David Bacher, Rui Gao, Fernanda Goncalves Abrantes, Tommaso Pajero,

*University of Birmingham*: Dan Johnson, Marcus Jonathan Madurai

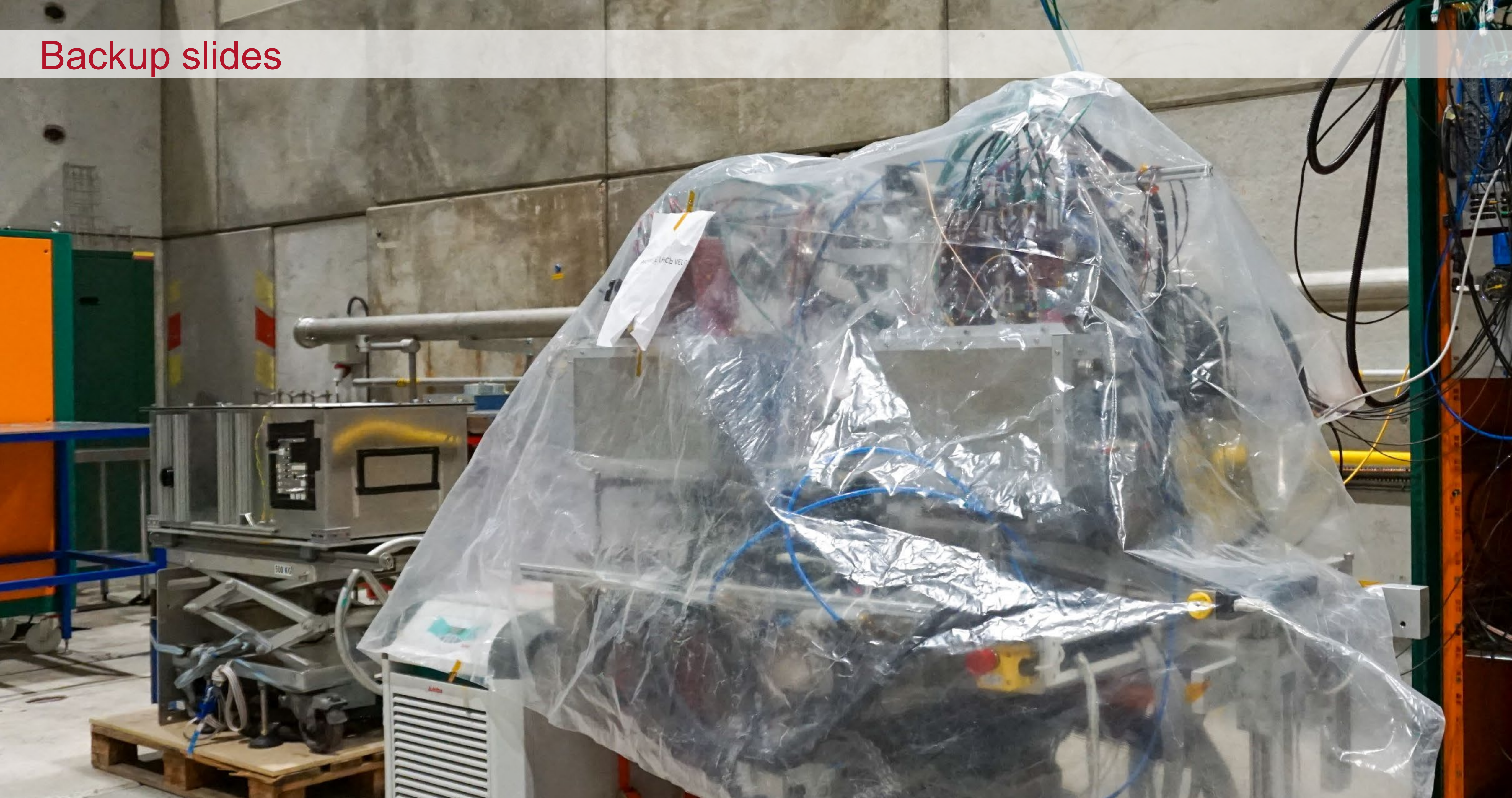
*University of Glasgow*: Naomi Cooke, Aleksandrina Docheva

## And acknowledgements to everyone making this possible, including

Richard Bates, Vincent van Beveren, Henk Boterenbrood, Paula Collins, Maarten van Dijk, Martin Fransen, Abraham Gallas Torreira, Thierry Gys, Vladimir Gromov, Bas van der Heijden, Malcolm John, Xavi Llopart, Loris Martinazolli, and Heinrich Schindler





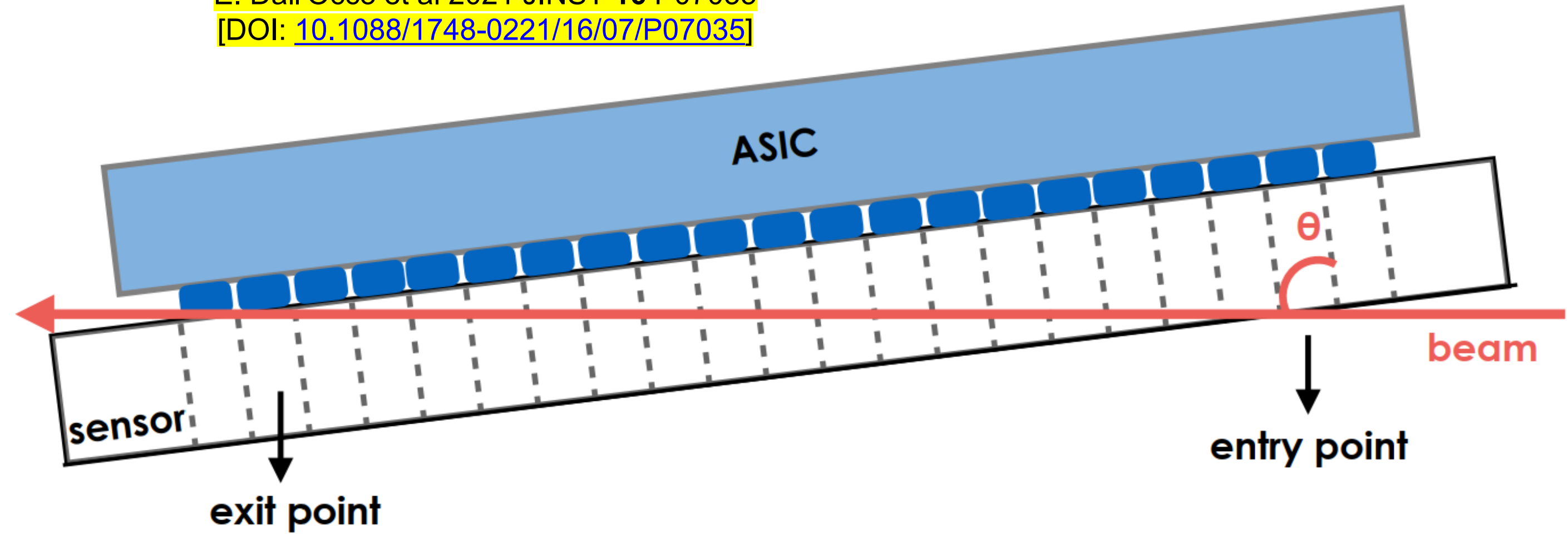




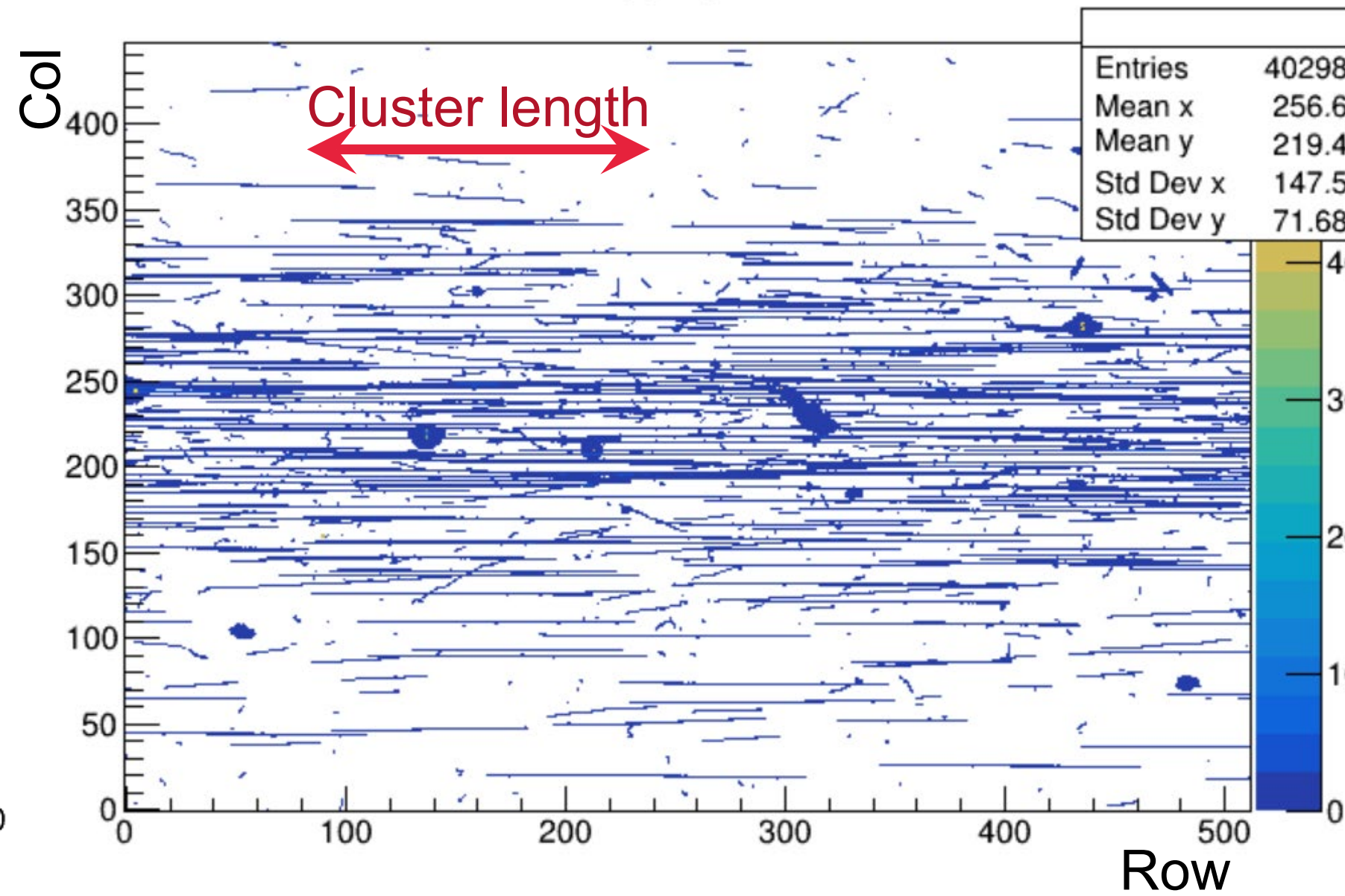
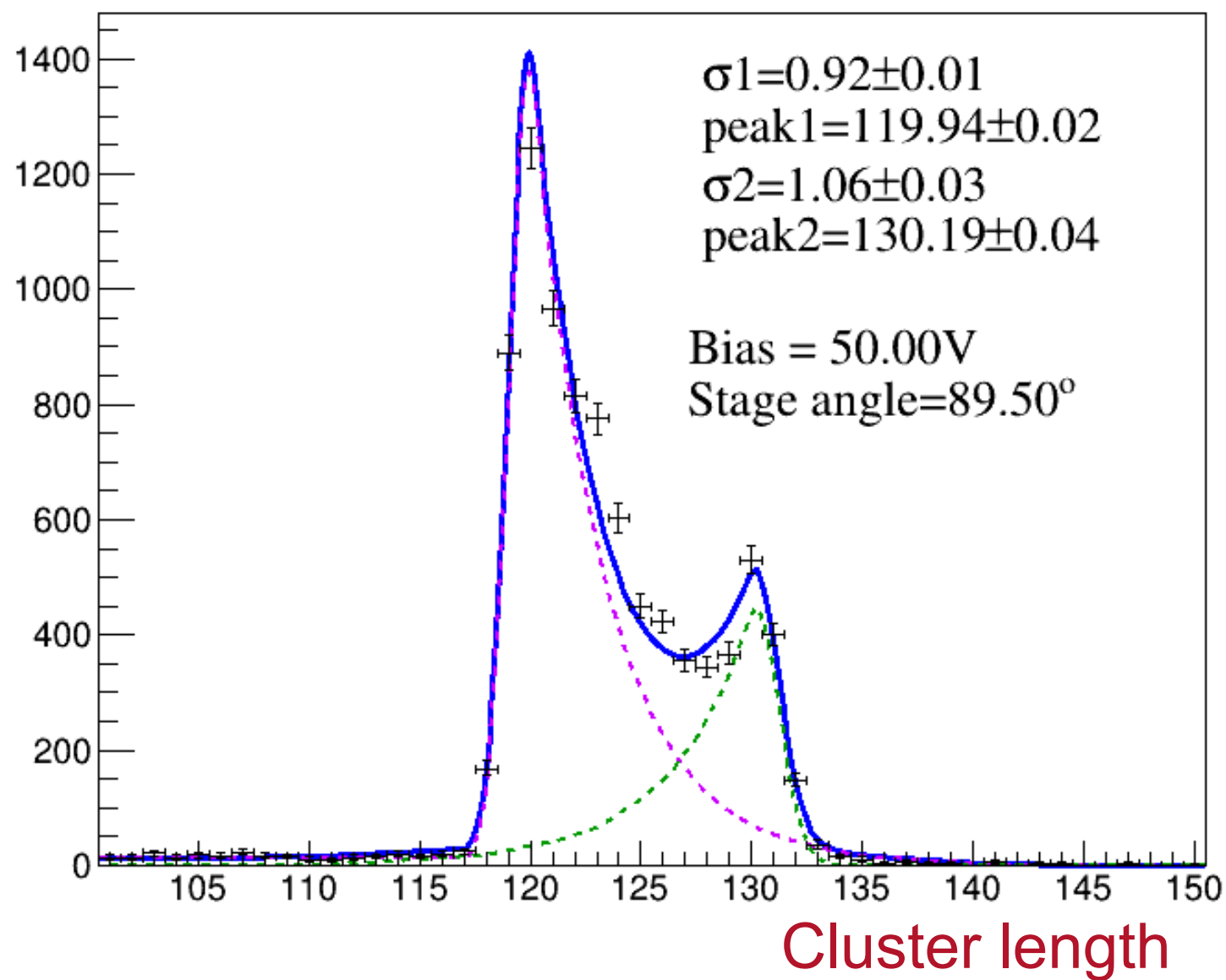
# Grazing angle measurements

- Grazing angle measurements probe different depths of the sensor
- Can be used to determine thickness by measuring cluster length at various angles
- Sensors are thin, but not flat

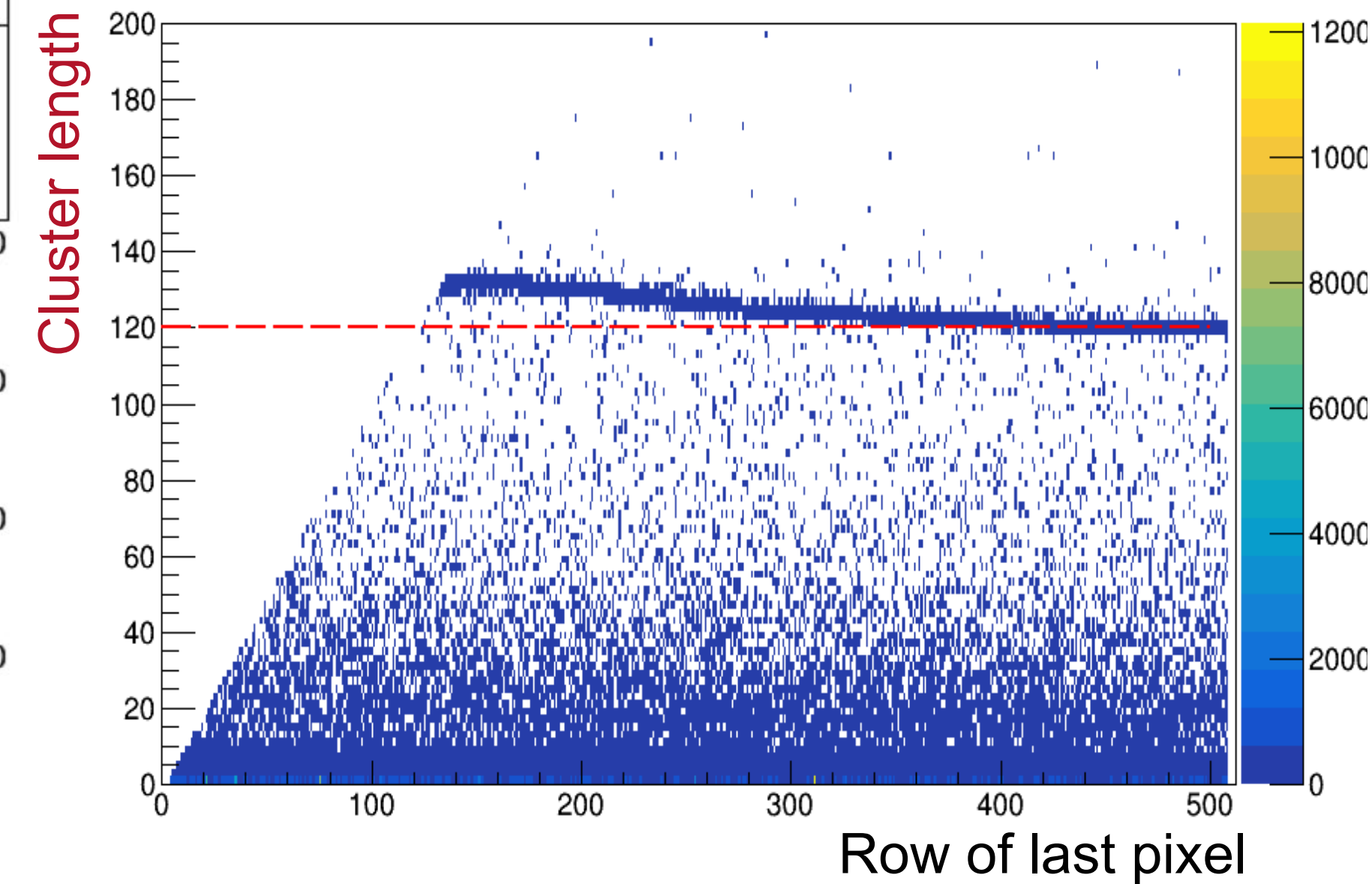
E. Dall'Occo et al 2021 JINST 16 P07035  
 [DOI: [10.1088/1748-0221/16/07/P07035](https://doi.org/10.1088/1748-0221/16/07/P07035)]



N161, Pixel pitch 55um, Thickness 100um, Run 5196



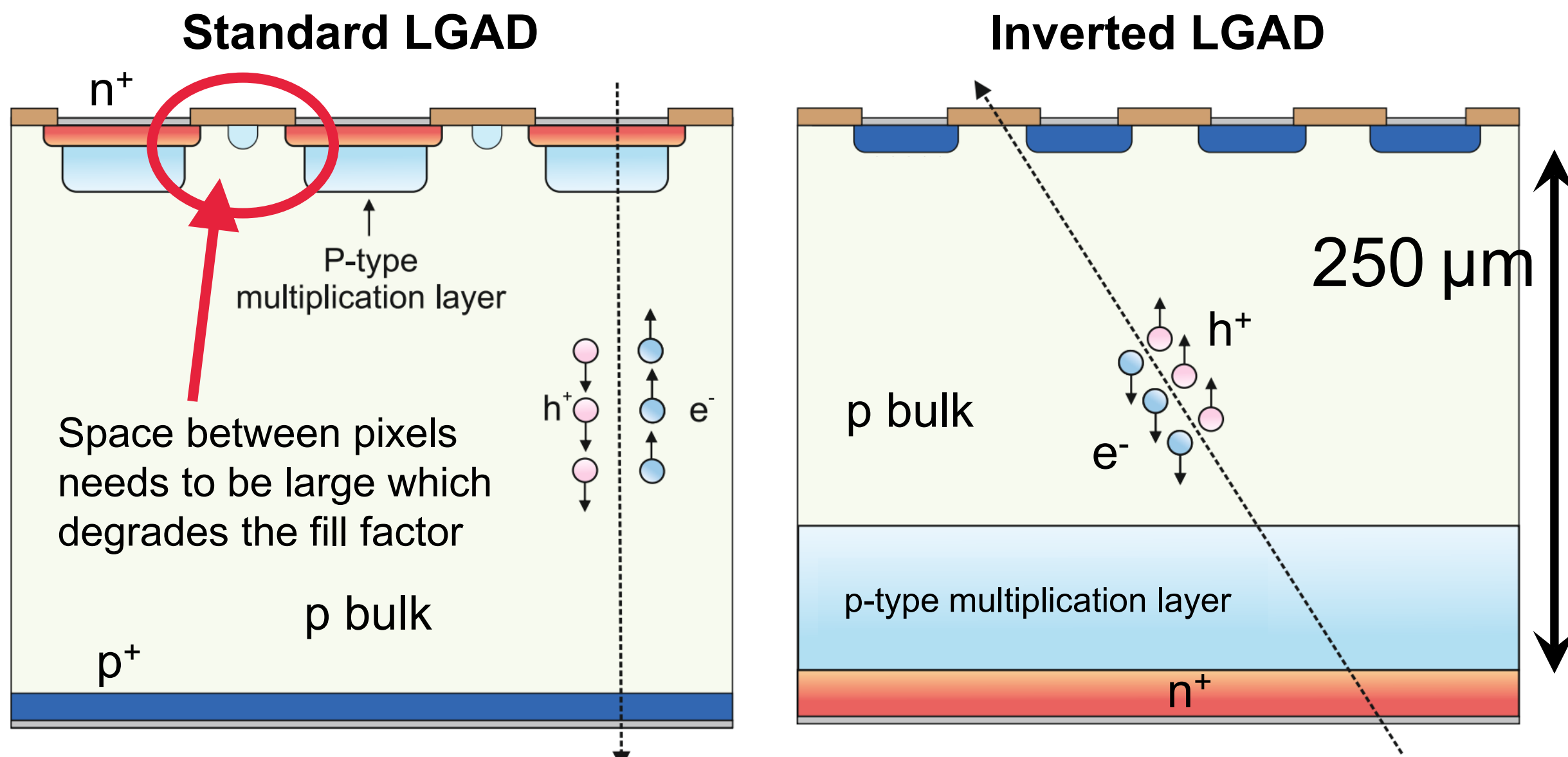
N161, Pixel pitch 55um, Thickness 100um, Run 5196



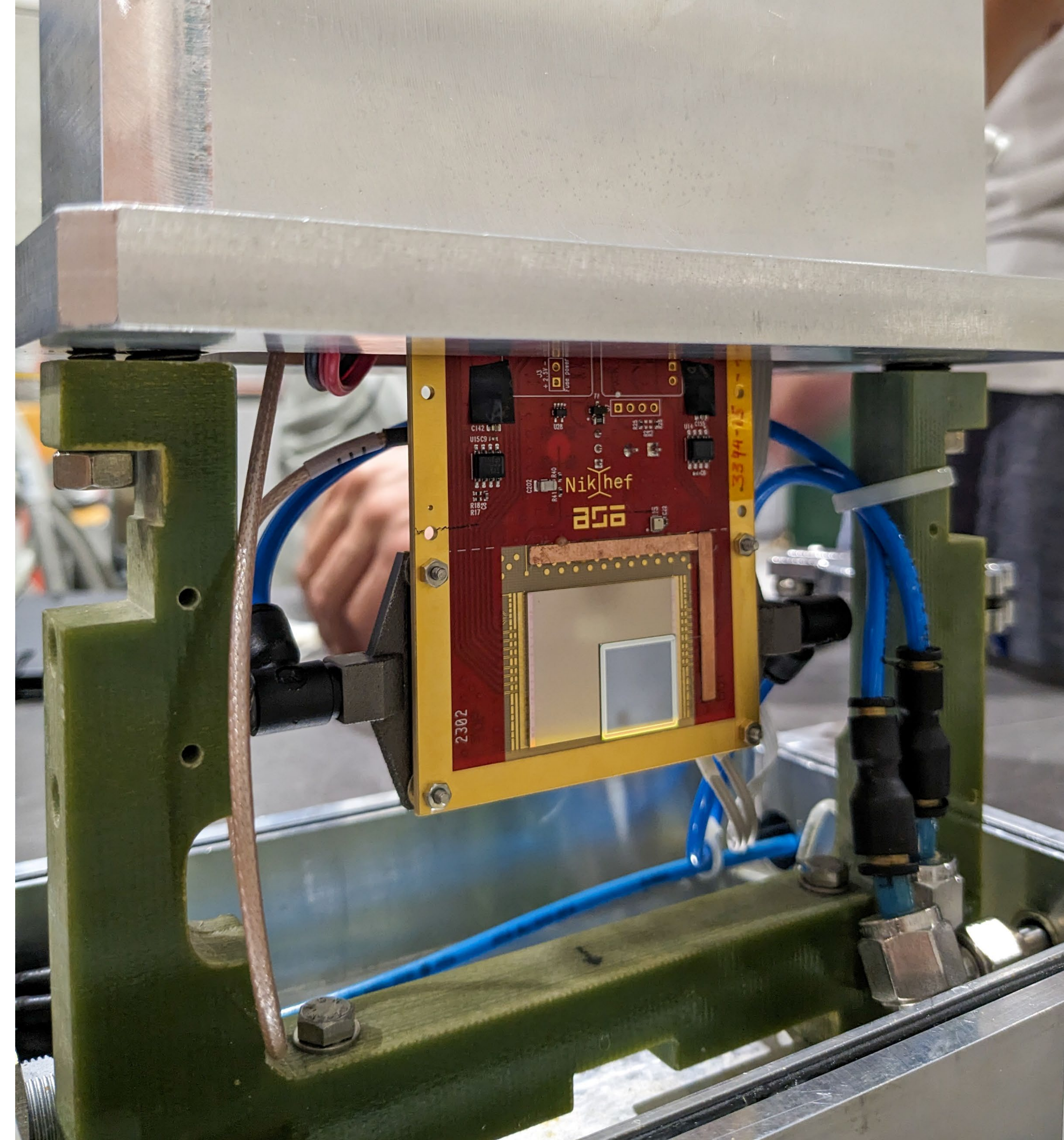


# Inverted LGAD on Timepix4 as DUT

- Low-gain avalanche diodes (LGADs) use charge multiplication to deliver larger input signals
- Small pixel size cannot be achieved in standard LGAD technology (without losing efficiency)
- Inverted LGADs (iLGADs) solve this by placing the gain layer on the backside
- Sensors produced by Micron and provided by Glasgow

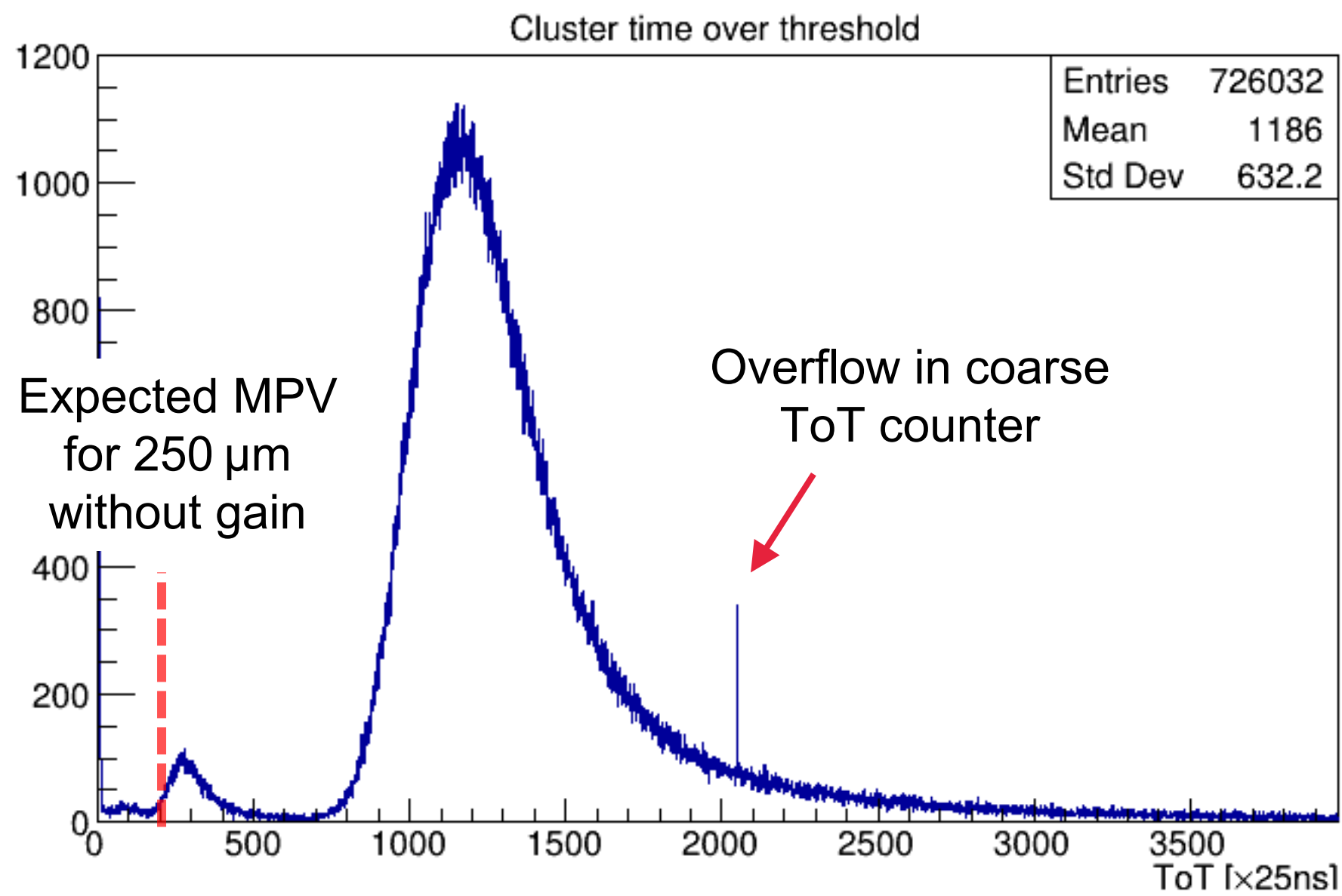


A. Doblas *et al* *Sensors* **2023**, 23, 3450 [DOI: [10.3390/s23073450](https://doi.org/10.3390/s23073450)]

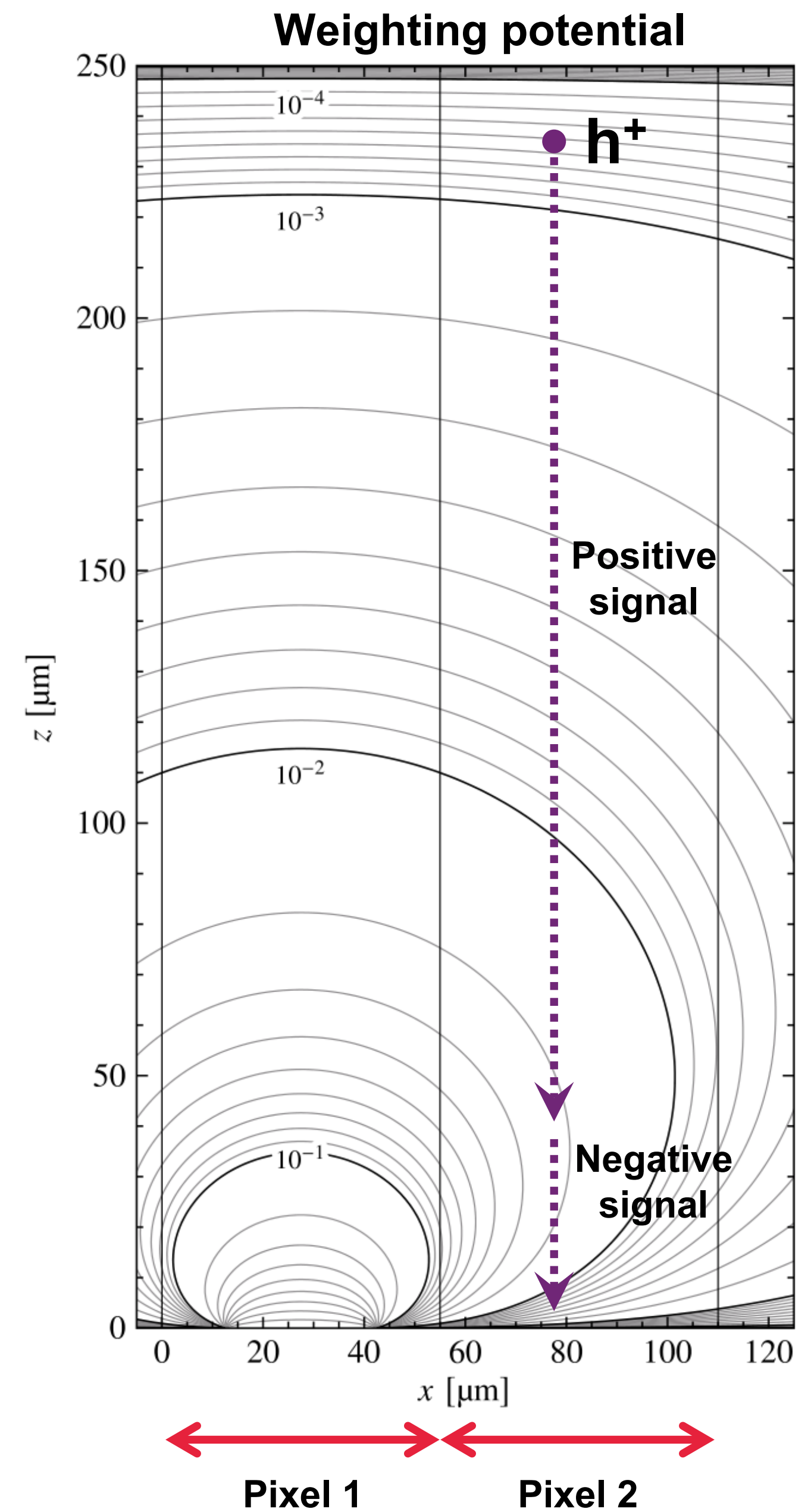
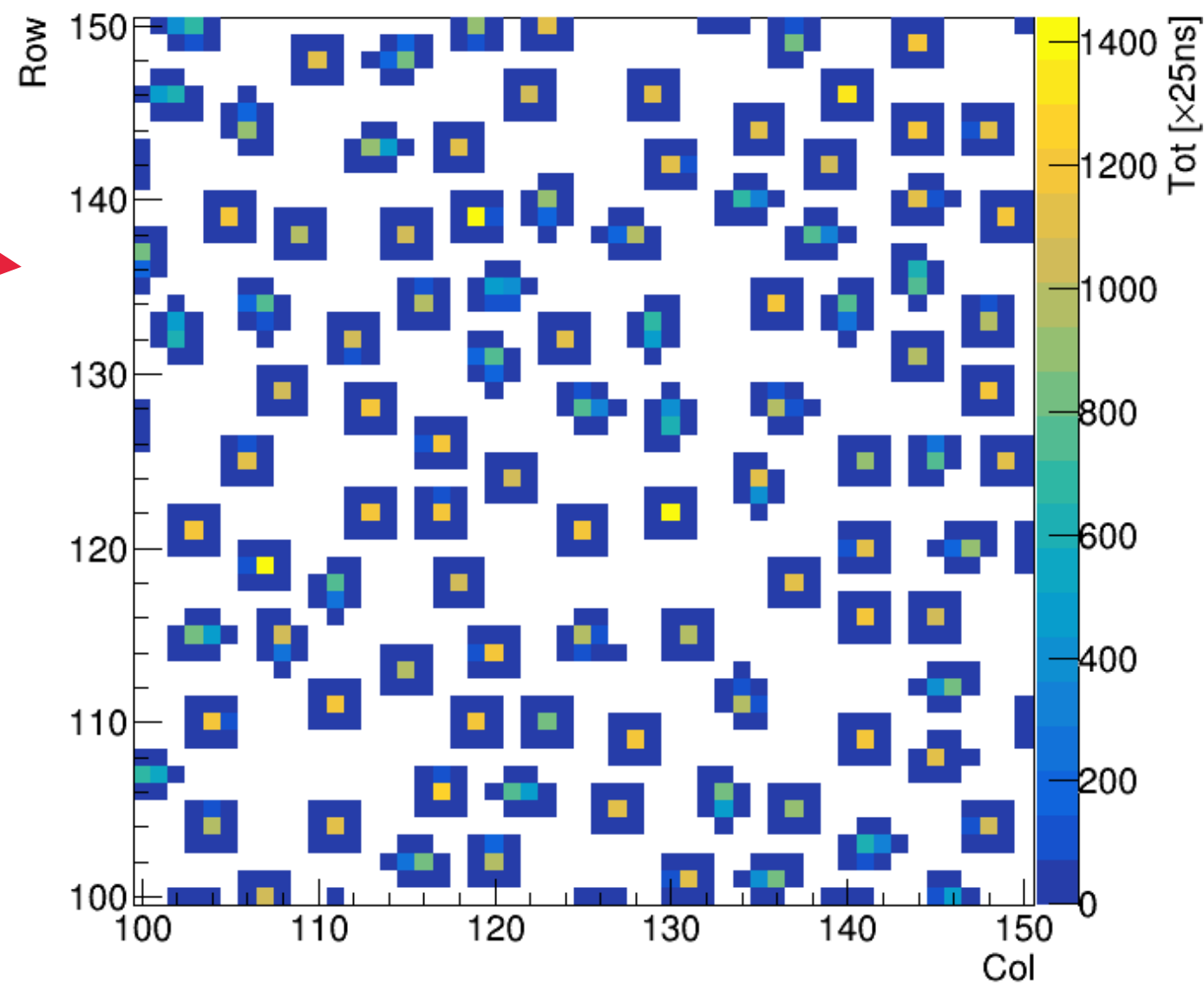
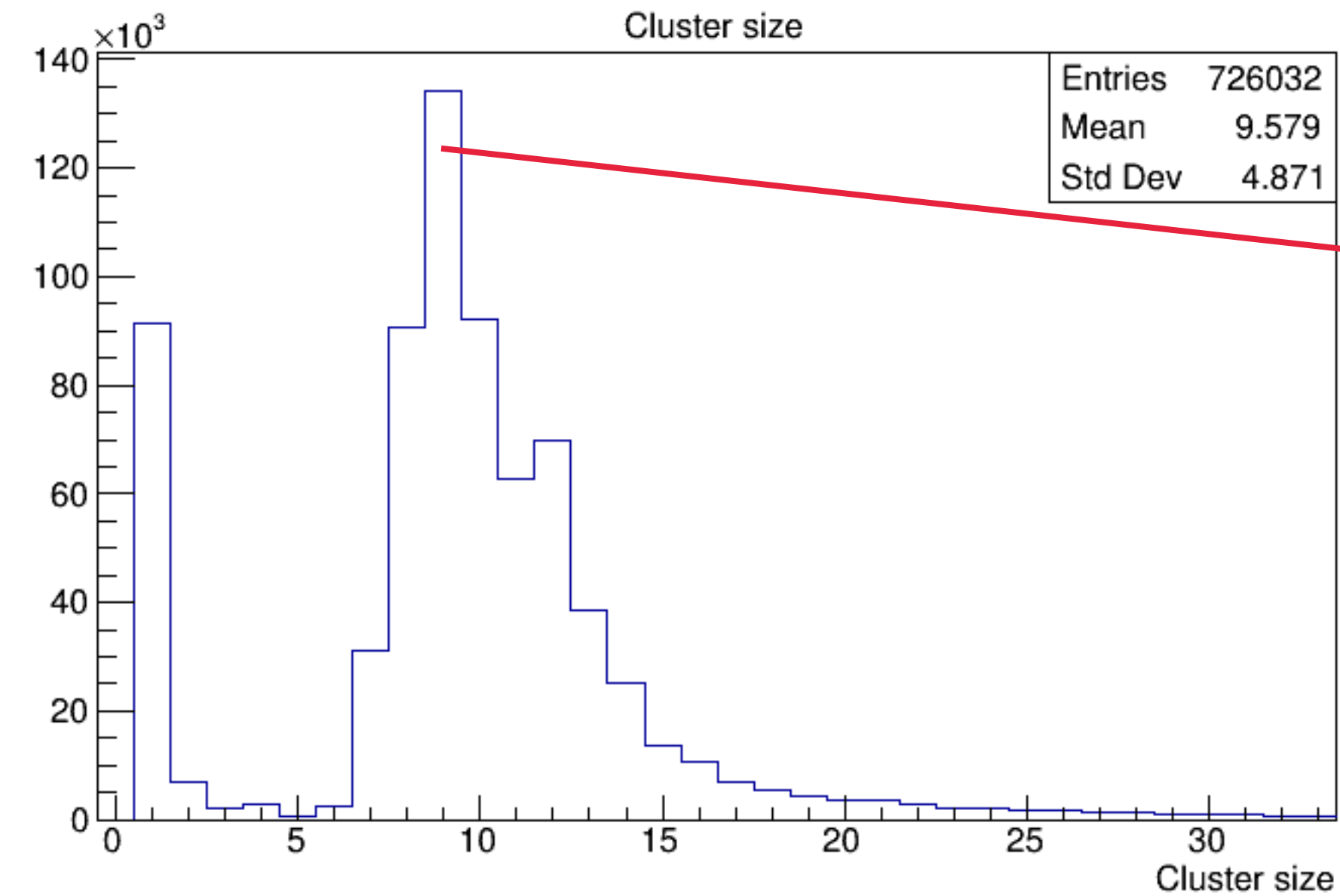




# Inverted LGAD on Timepix4 as DUT

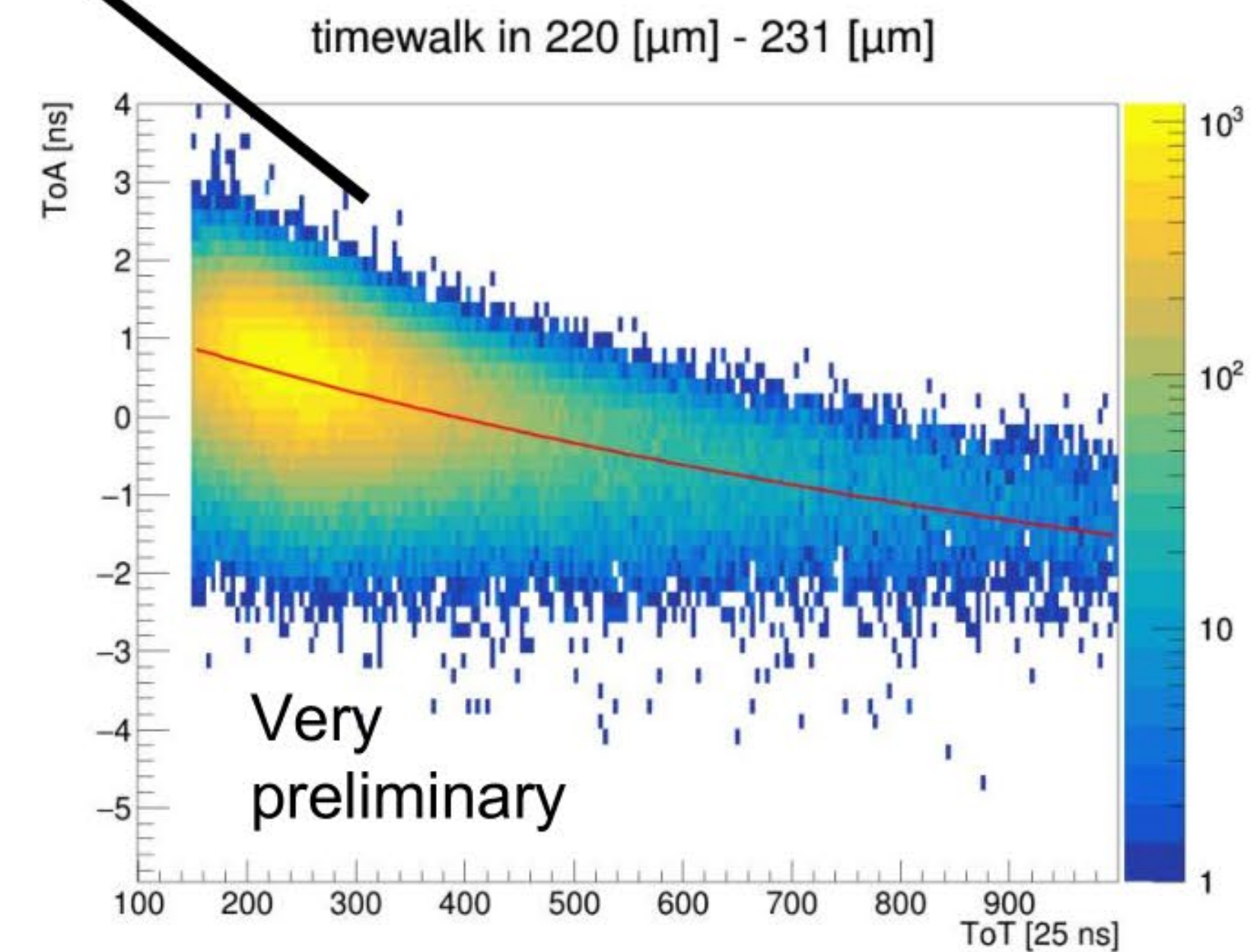
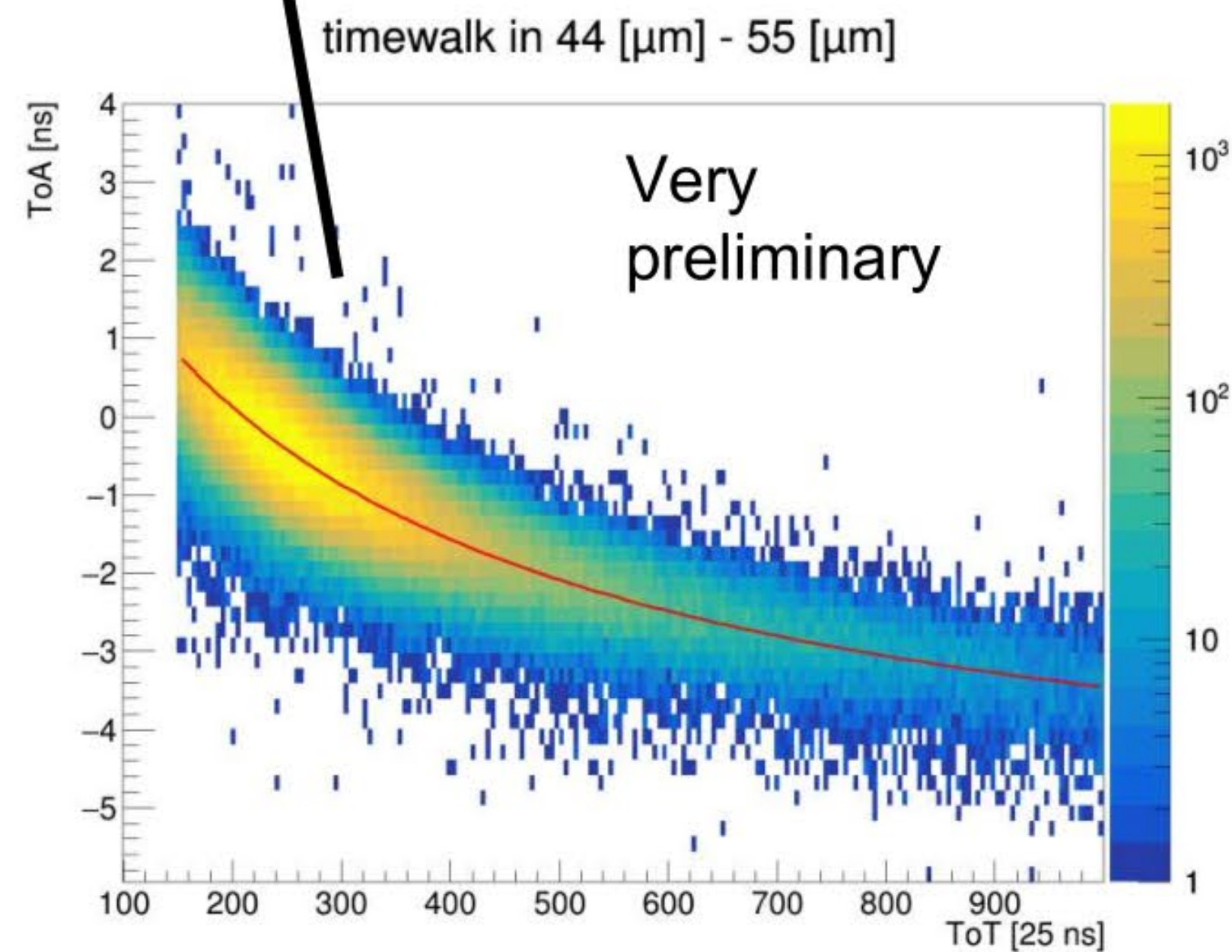
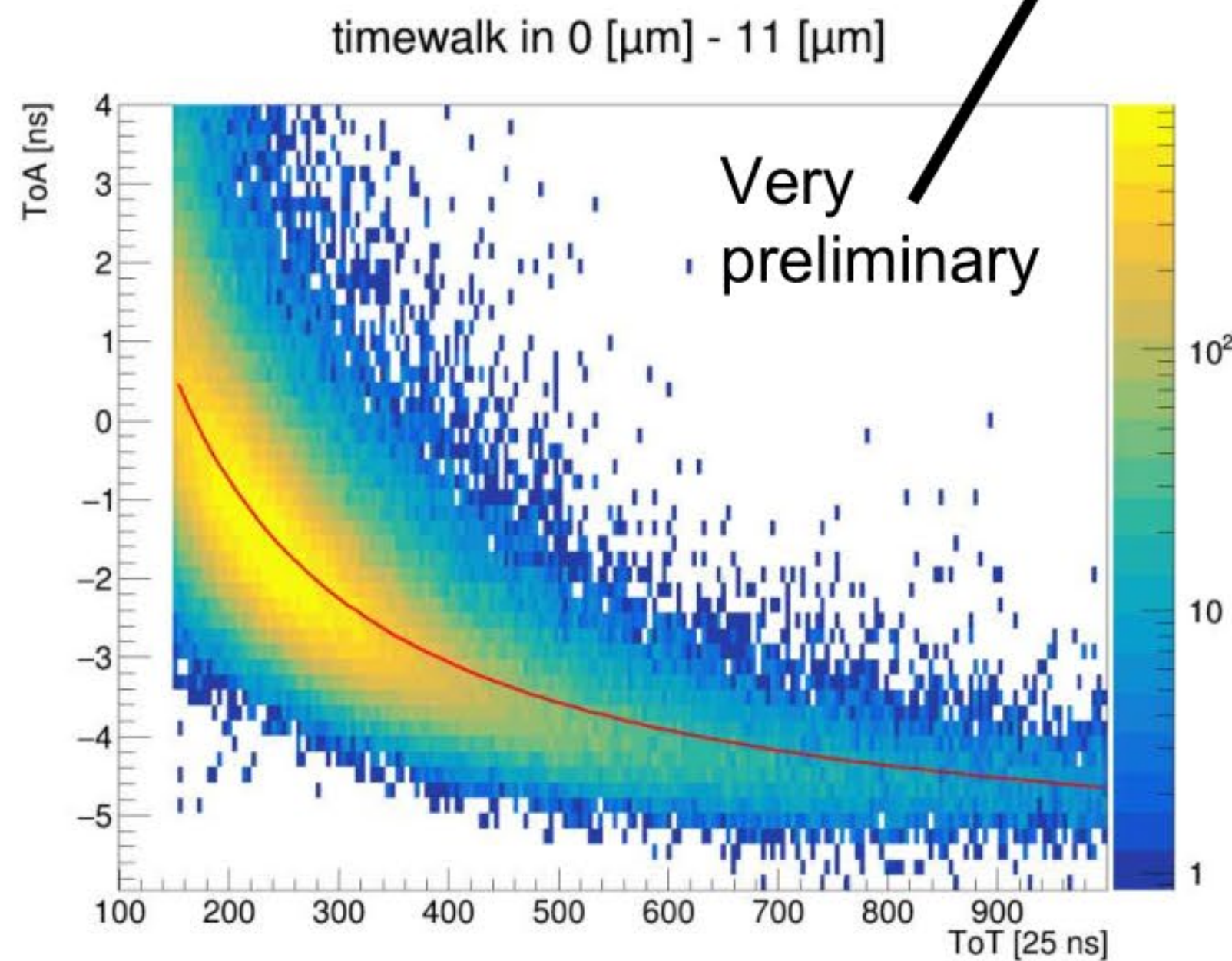
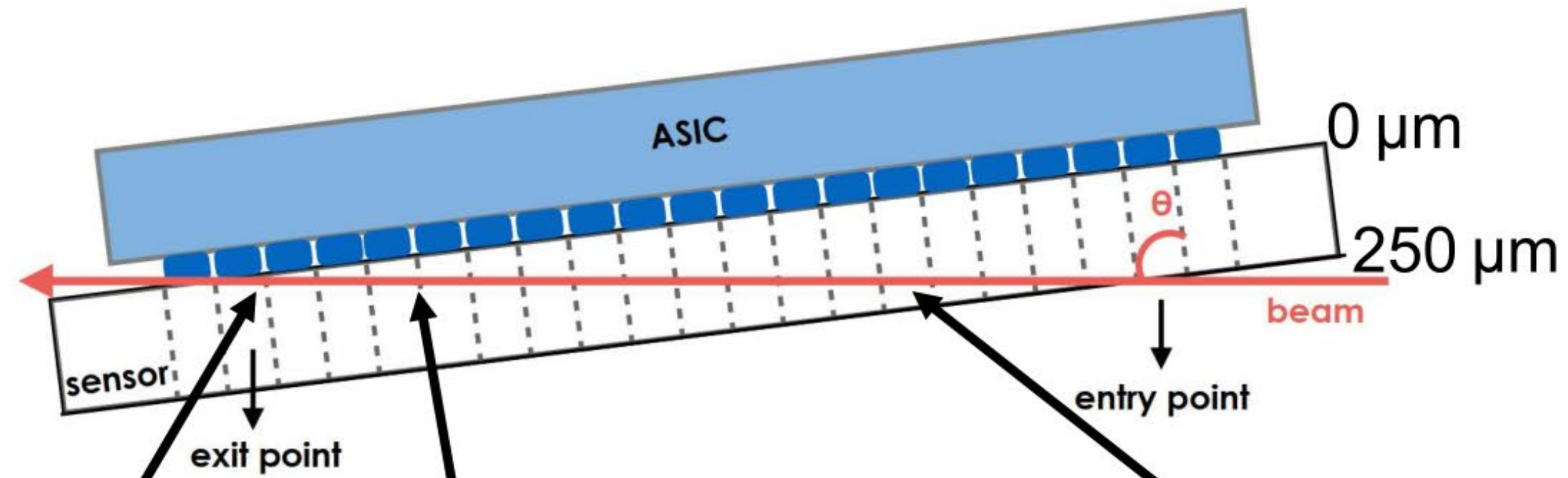


- Large cluster size at perpendicular beam incidence
- Cluster have skirt of low-ToT hits (< 25 ns)
- We suspect due to bipolar signals in neighbouring pixels



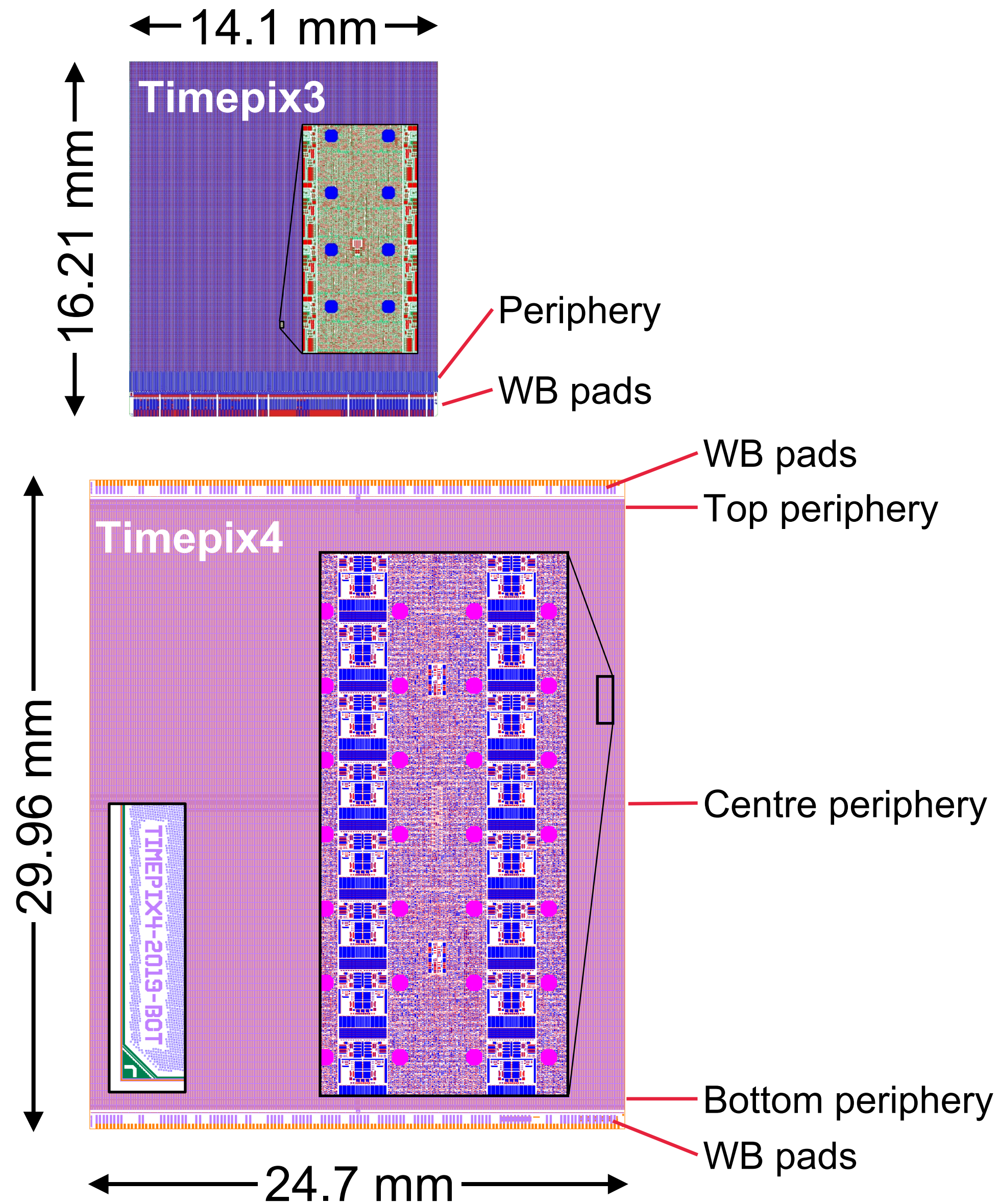


# Timewalk behaviour depends on track depth





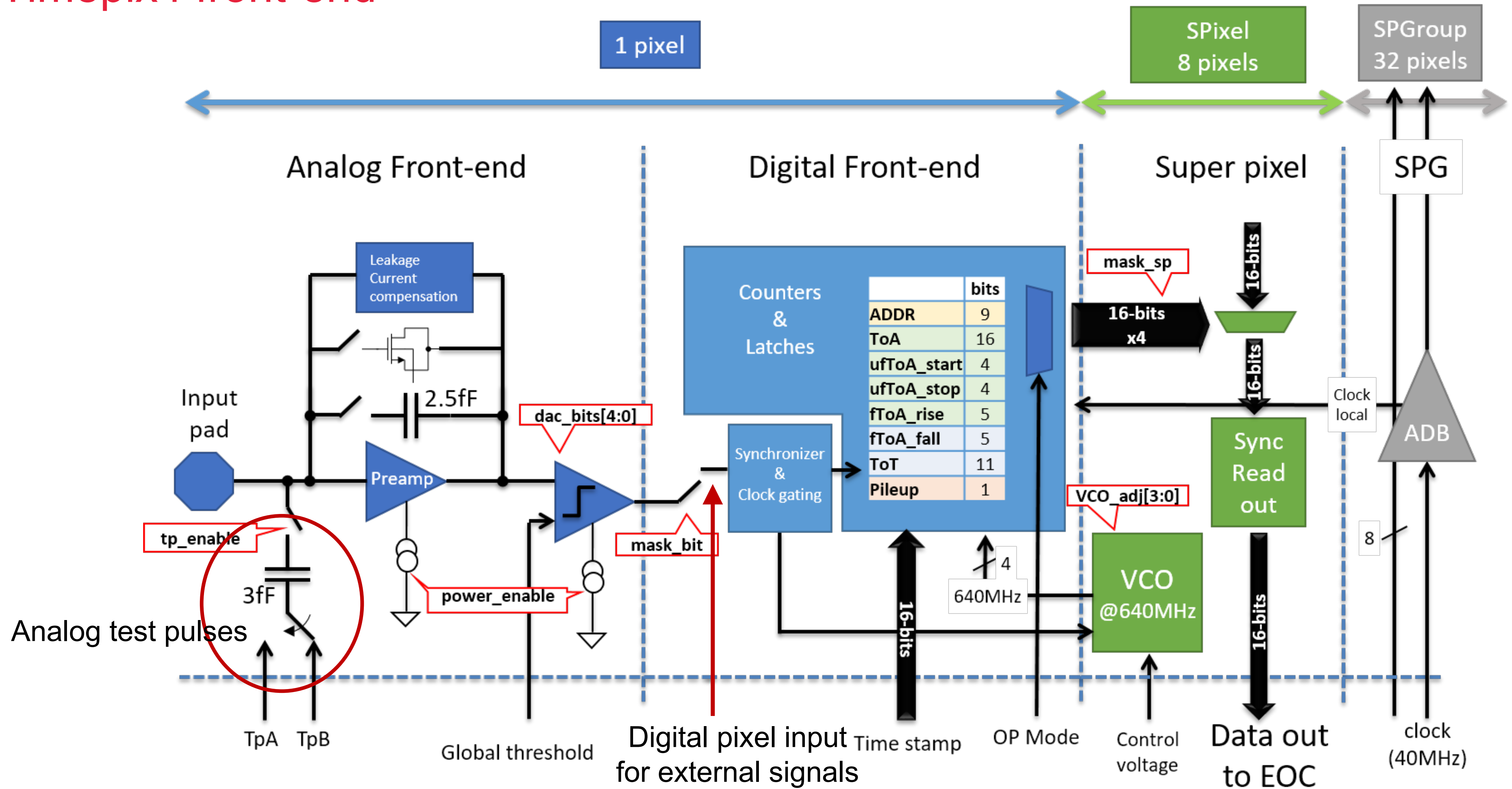
# Timepix3 → Timepix4



		Timepix3 (2013)	Timepix4 (2019)	
<b>Technology</b>		130nm – 8 metal	65nm – 10 metal	
<b>Pixel Size</b>		55 x 55 $\mu\text{m}$	55 x 55 $\mu\text{m}$	
<b>Pixel arrangement</b>		3-side buttable 256 x 256	4-side buttable 512 x 448 <b>3.5x</b>	
<b>Sensitive area</b>		1.98 $\text{cm}^2$	<b>6.94 <math>\text{cm}^2</math></b>	
<b>Readout Modes</b>	Data driven (Tracking)	Mode	TOT and TOA	
		Event Packet	48-bit	64-bit
		Max rate	0.43x10 <sup>6</sup> hits/mm <sup>2</sup> /s	<b>3.58x10<sup>6</sup> hits/mm<sup>2</sup>/s</b> <b>8x</b>
	Max Pix rate	1.3 KHz/pixel	<b>10.8 KHz/pixel</b>	
	Frame based (Imaging)	Mode	PC (10-bit) and iTOT (14-bit)	CRW: PC (8 or 16-bit)
		Frame	Zero-suppressed (with pixel addr)	Full Frame (without pixel addr)
Max count rate		~0.82 x 10 <sup>9</sup> hits/mm <sup>2</sup> /s	~5 x 10 <sup>9</sup> hits/mm <sup>2</sup> /s	
<b>TOT energy resolution</b>		< 2KeV	< 1Kev	
<b>TOA binning resolution</b>		1.56ns	<b>195ps</b> <b>8x</b>	
<b>TOA dynamic range</b>		409.6 $\mu\text{s}$ (14-bits @ 40MHz)	<b>1.6384 ms</b> (16-bits @ 40MHz)	
<b>Readout bandwidth</b>		≤5.12Gb (8x SLVS@640 Mbps)	<b>≤163.84 Gbps</b> (16x @10.24 Gbps) <b>32x</b>	
<b>Target minimum threshold</b>		<500 e <sup>-</sup>	<500 e <sup>-</sup>	



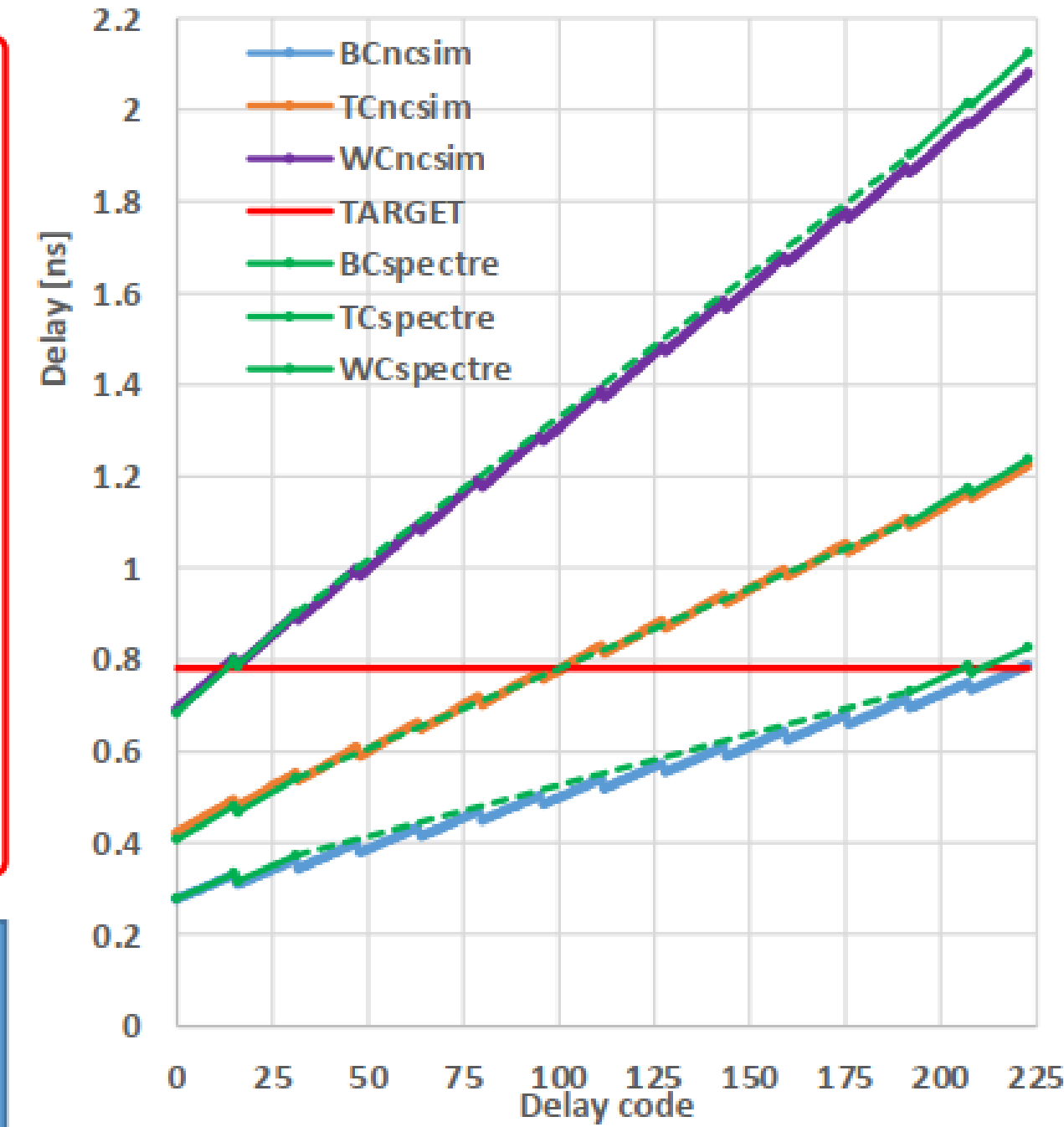
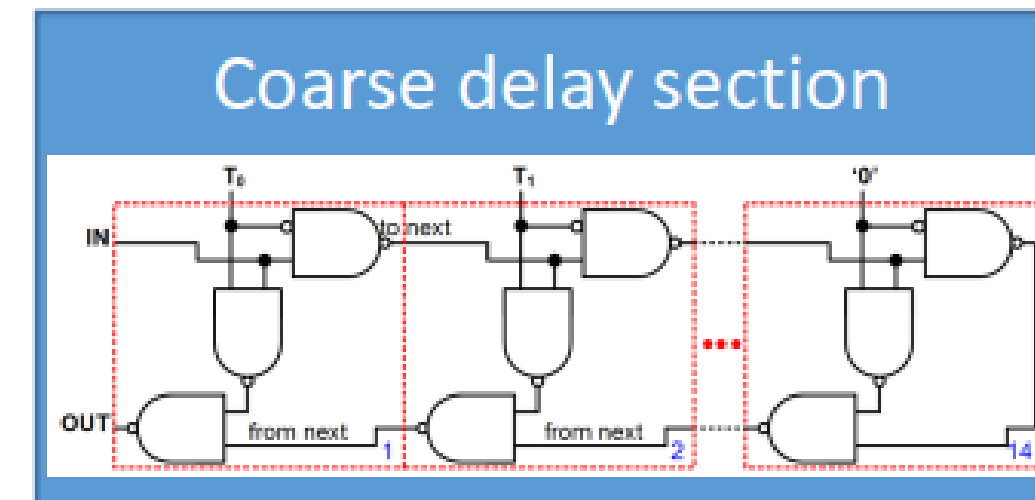
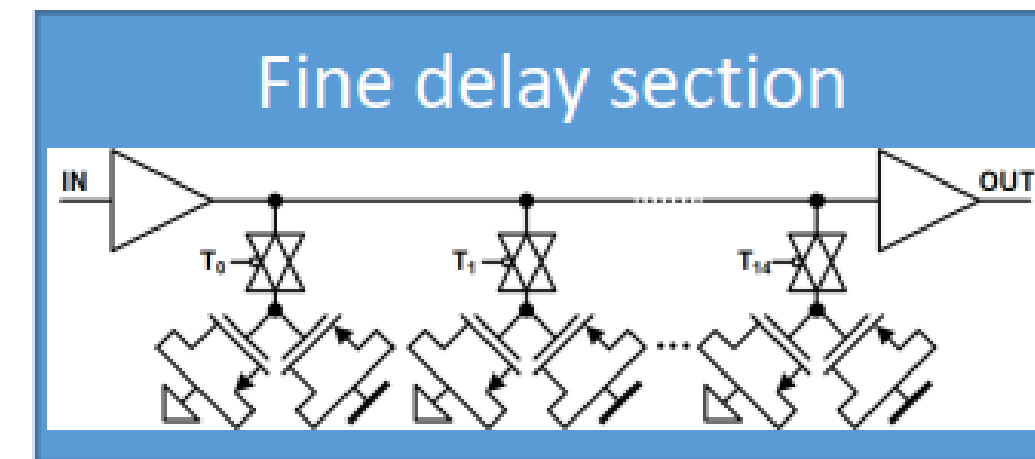
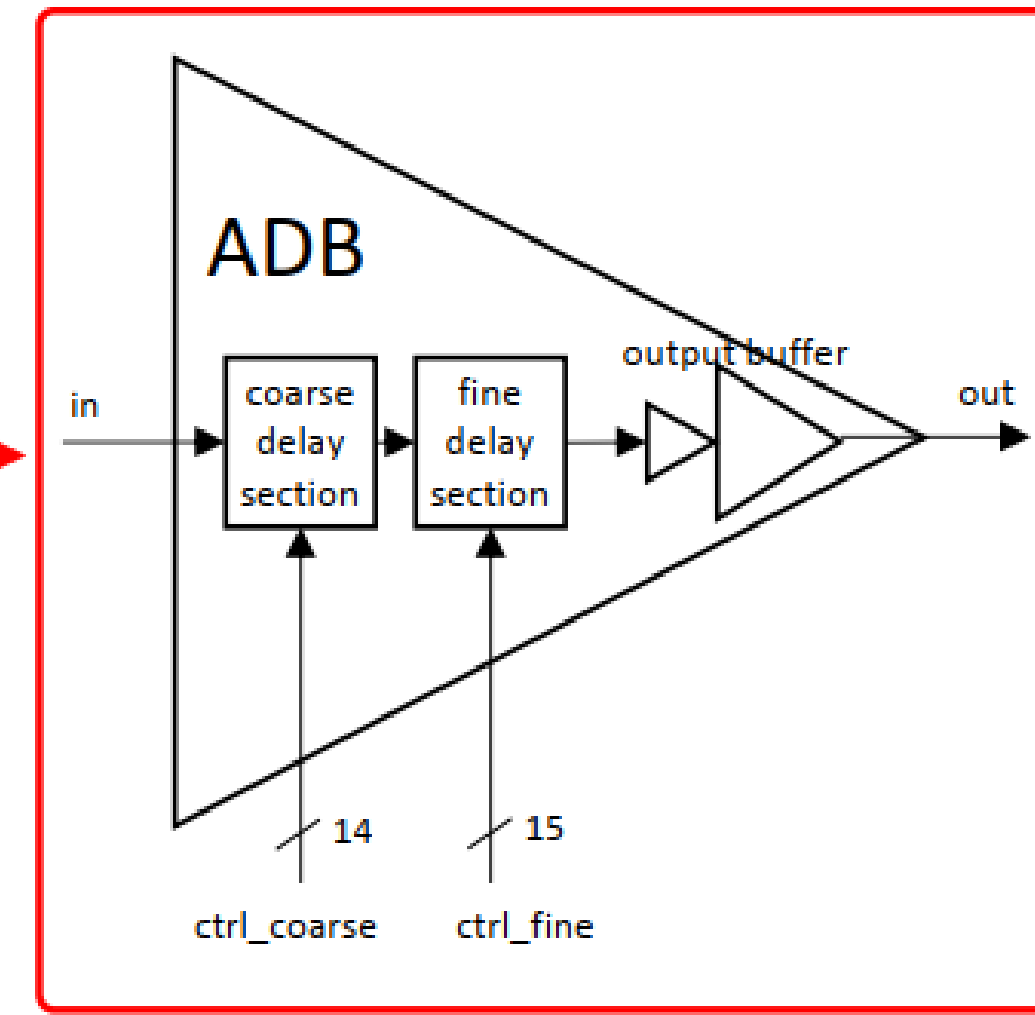
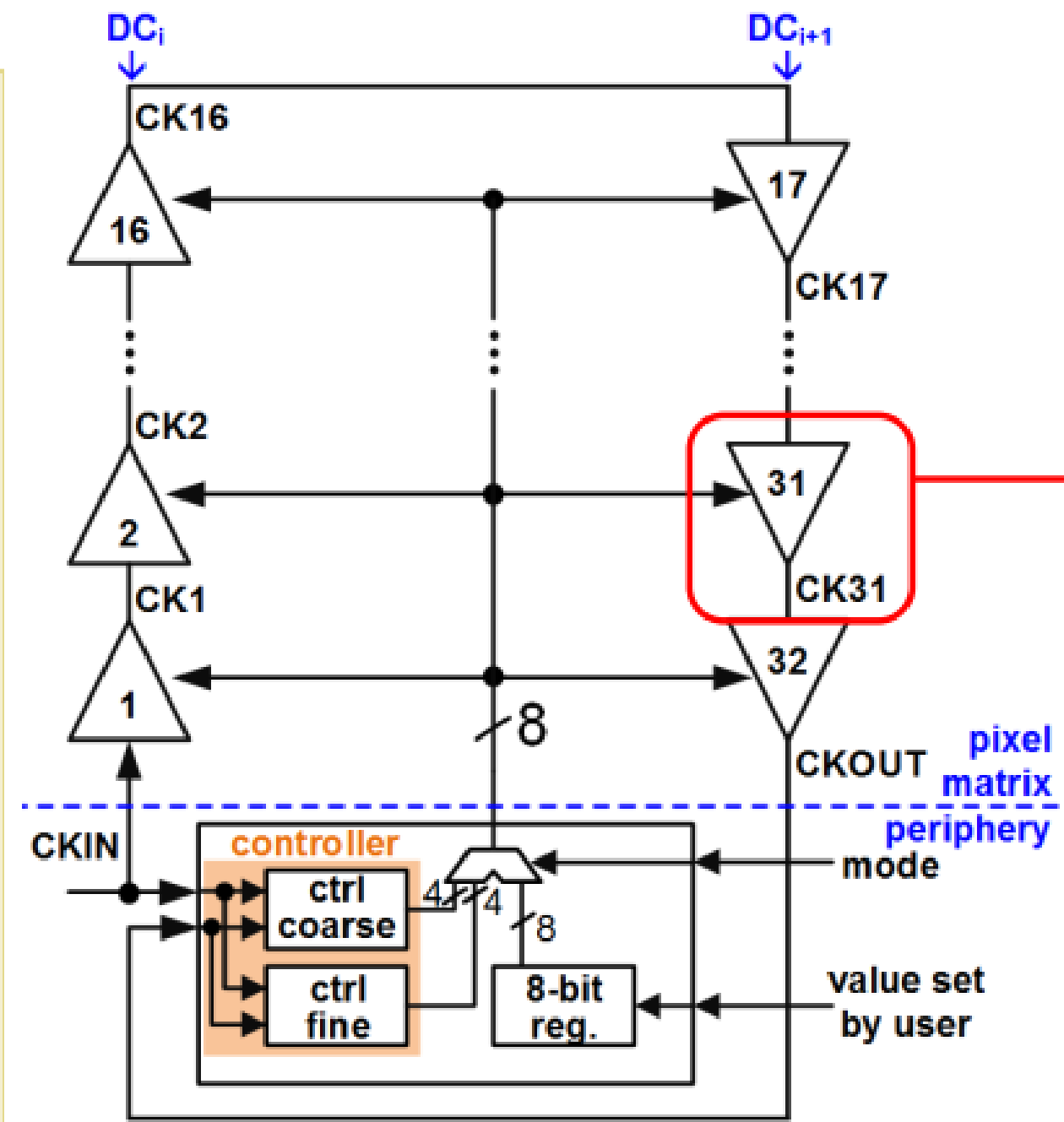
# Timepix4 front-end



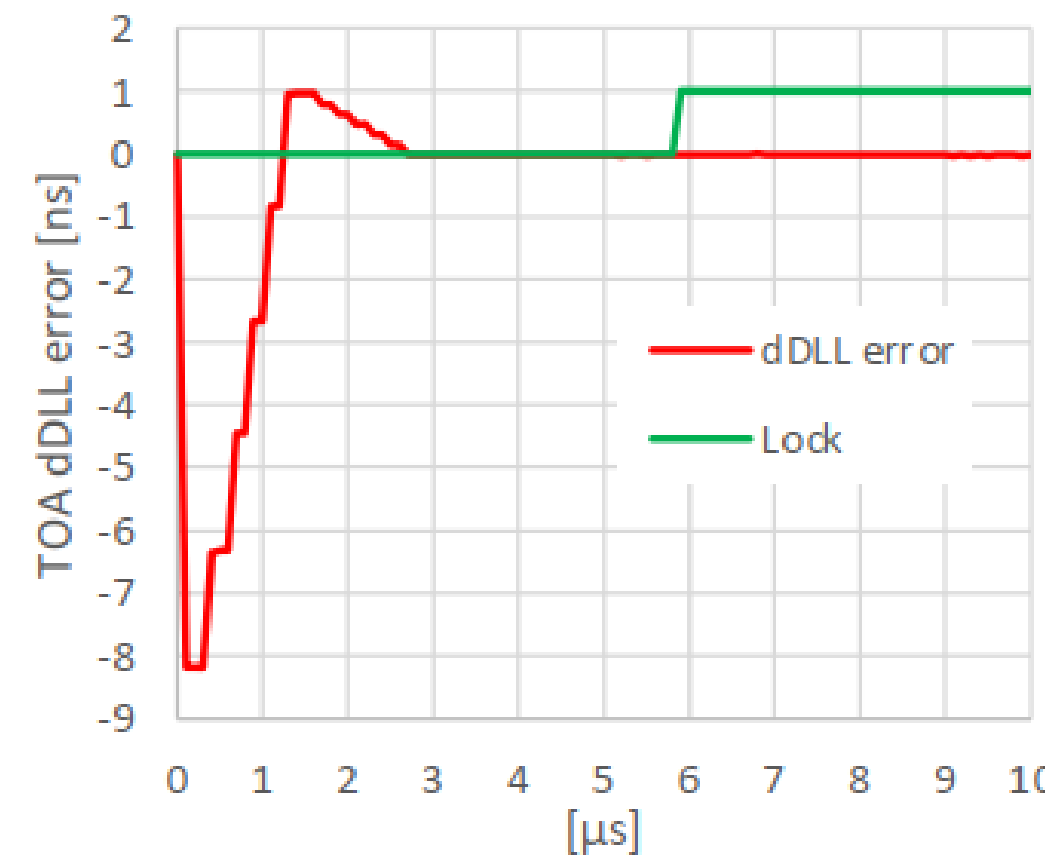


# Clock distribution – Column digital locked loop (DLL)

- The column DLL distributes the clock along the columns
- The adjustable delay buffers (ADB) precisely define the clock phase in each pixel group
- Controller tunes the total delay to 25 ns
- Possible to set the delay manually
- Individual ADB stations can be bypassed



**~22.7 mW/cm<sup>2</sup> to distribute a 40 MHz clock with a 100 ps<sub>rms</sub>**

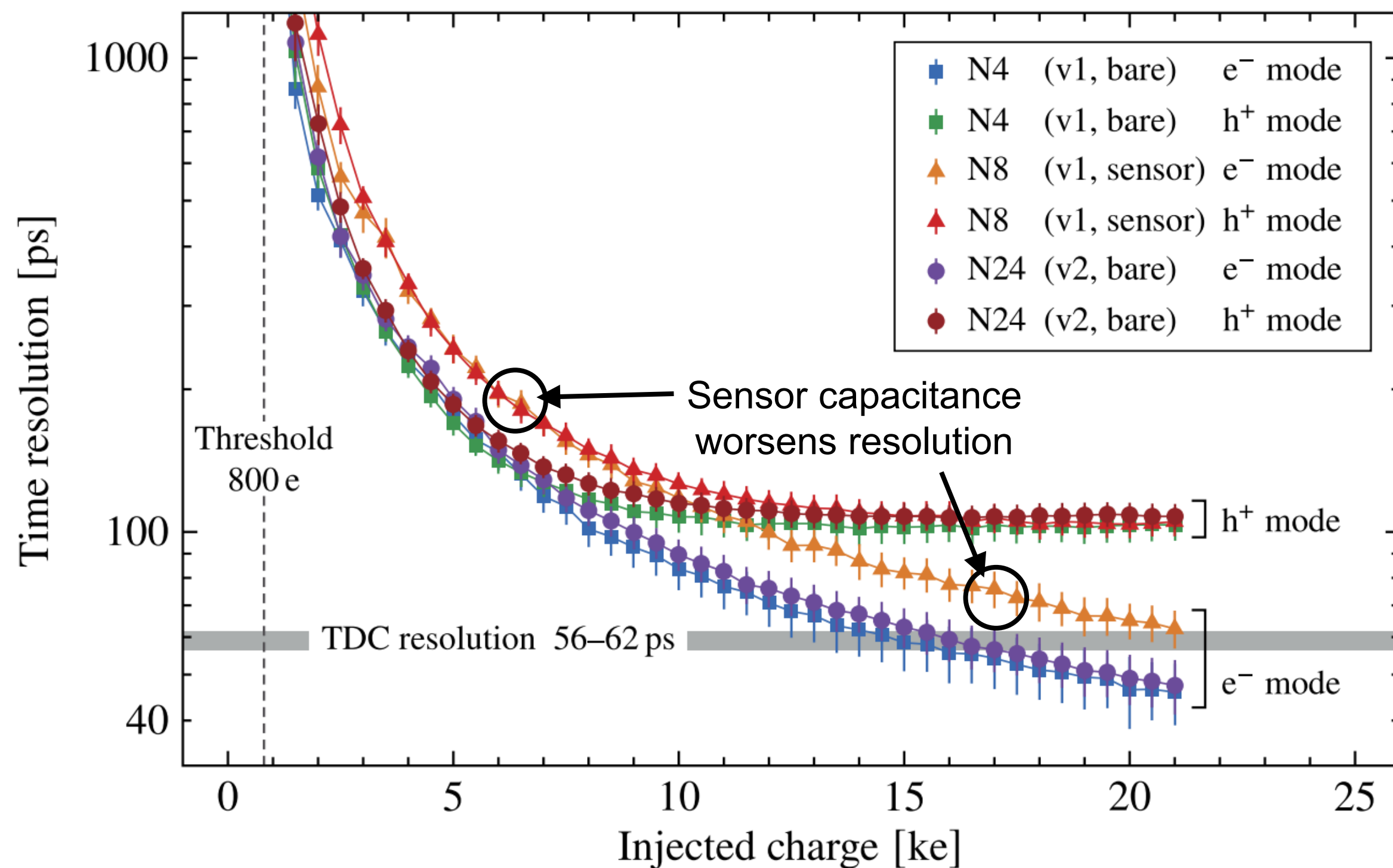




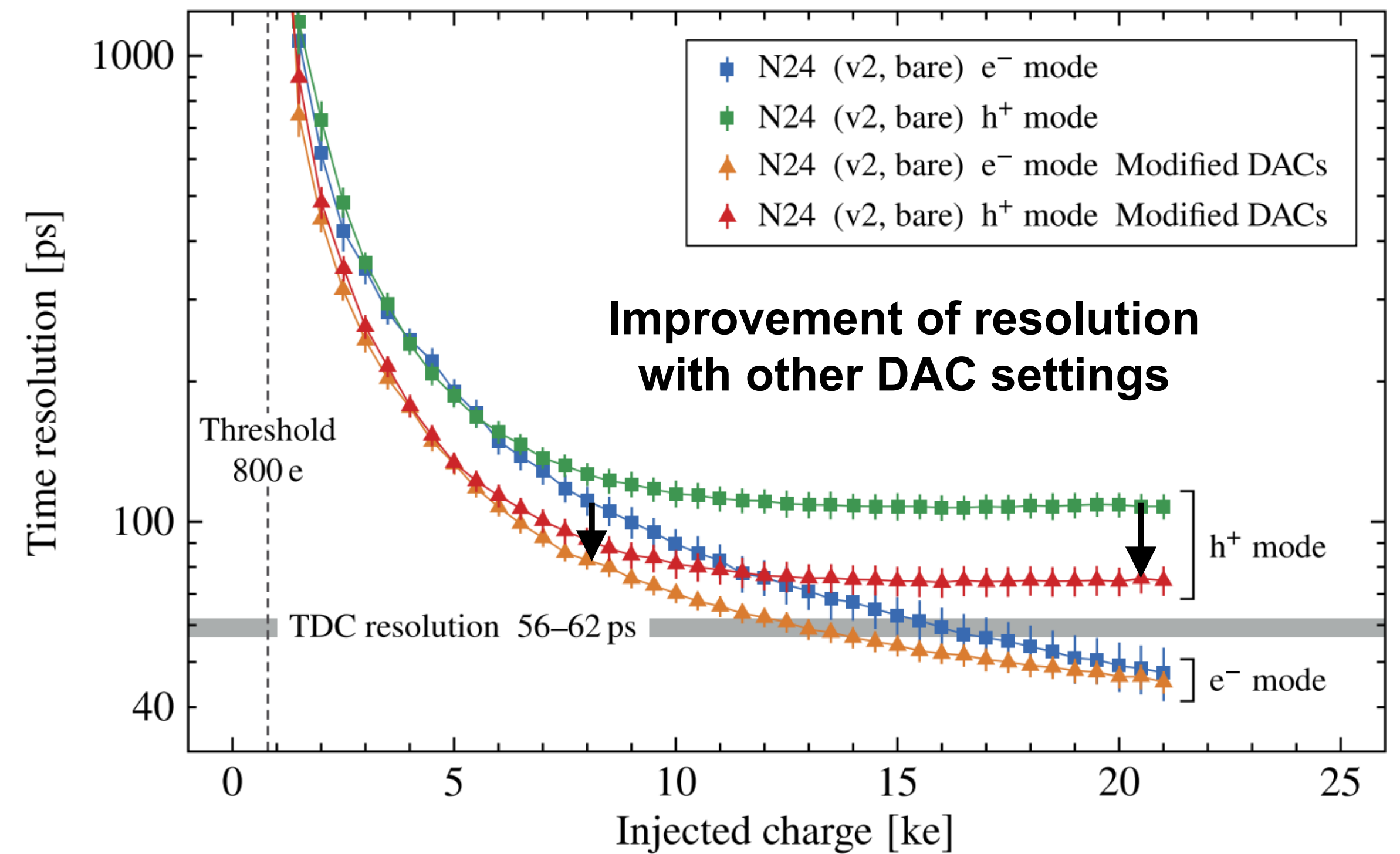
# Timepix4 – Analog front-end jitter

- Time resolution in  $h^+$  mode limited to 75–105 ps depending on DAC settings
- Pixel capacitance decreases the time resolution  
(see R. Ballabriga *et al* NIM A 1045 (2023) 167489 [DOI: [10.1016/j.nima.2022.167489](https://doi.org/10.1016/j.nima.2022.167489)])

### Analog front-end time resolution vs signal charge



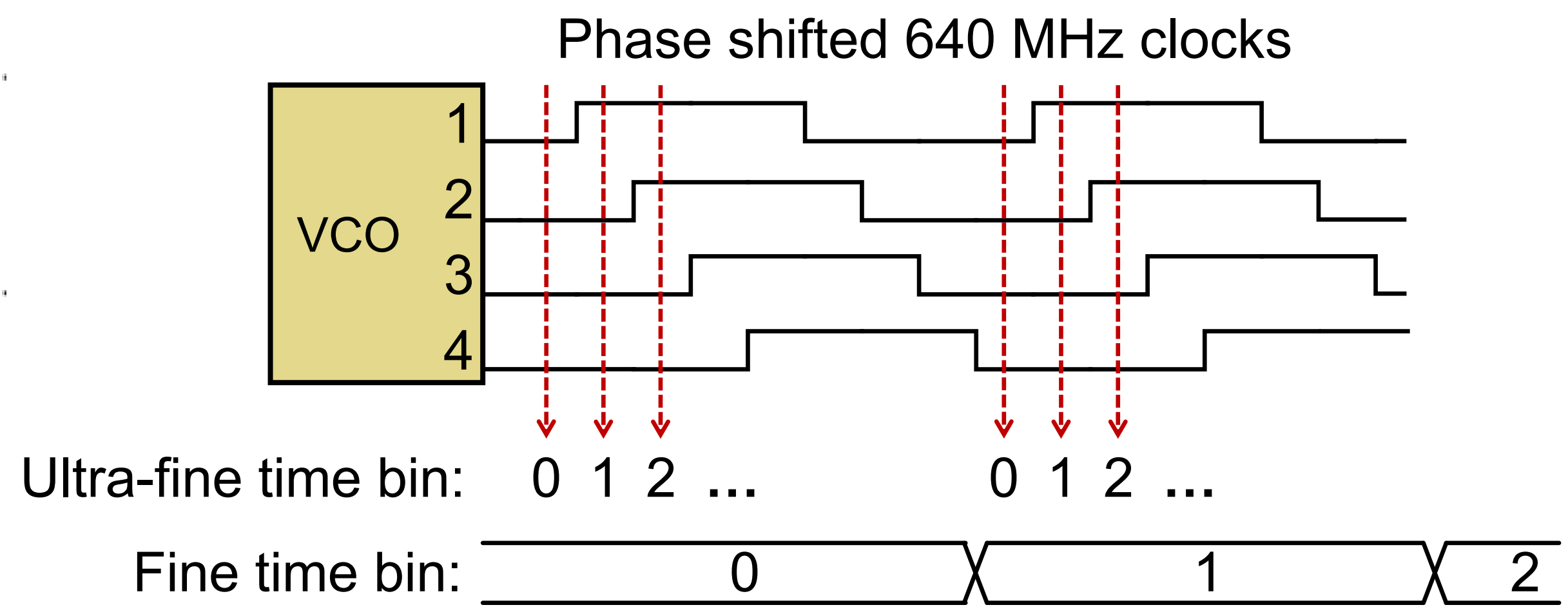
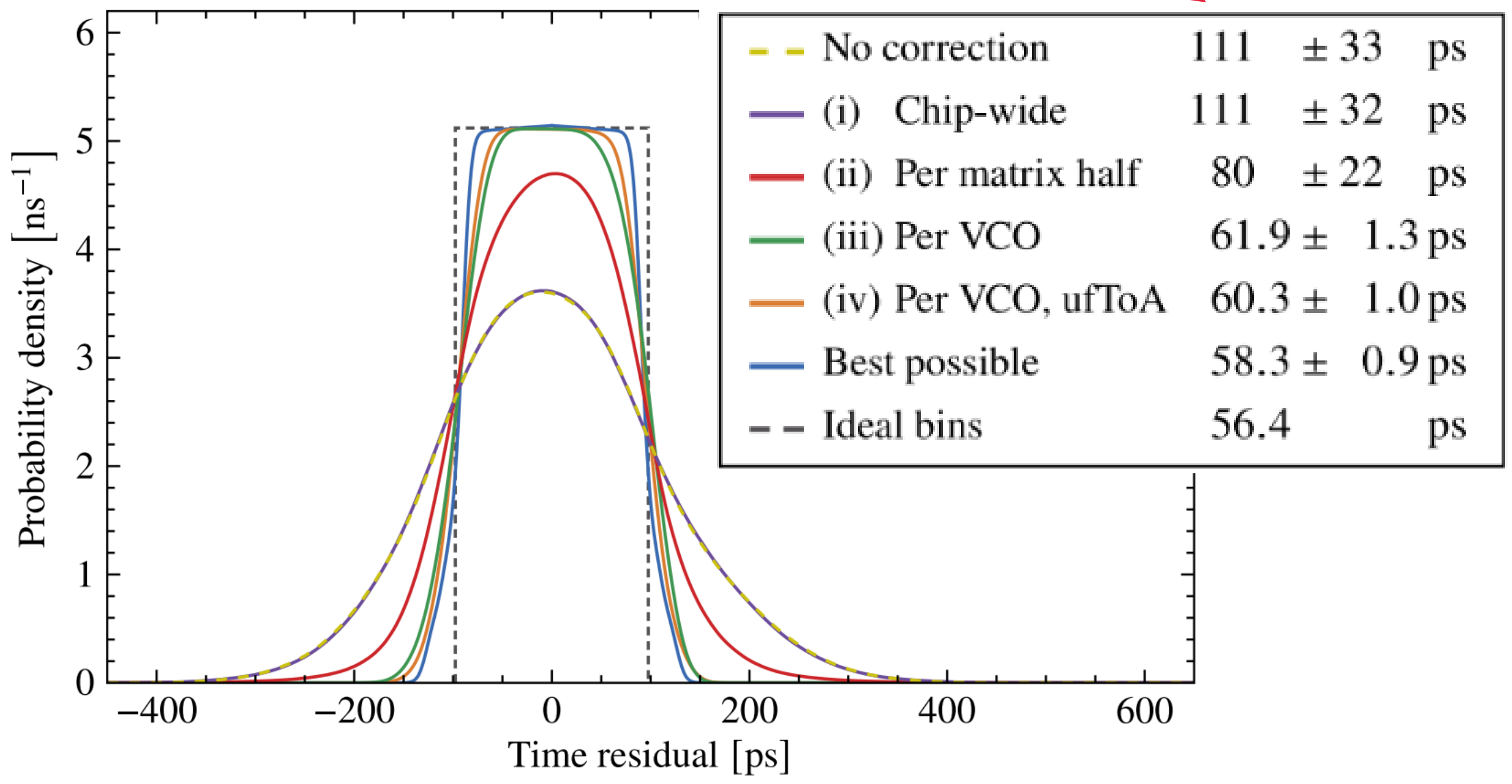
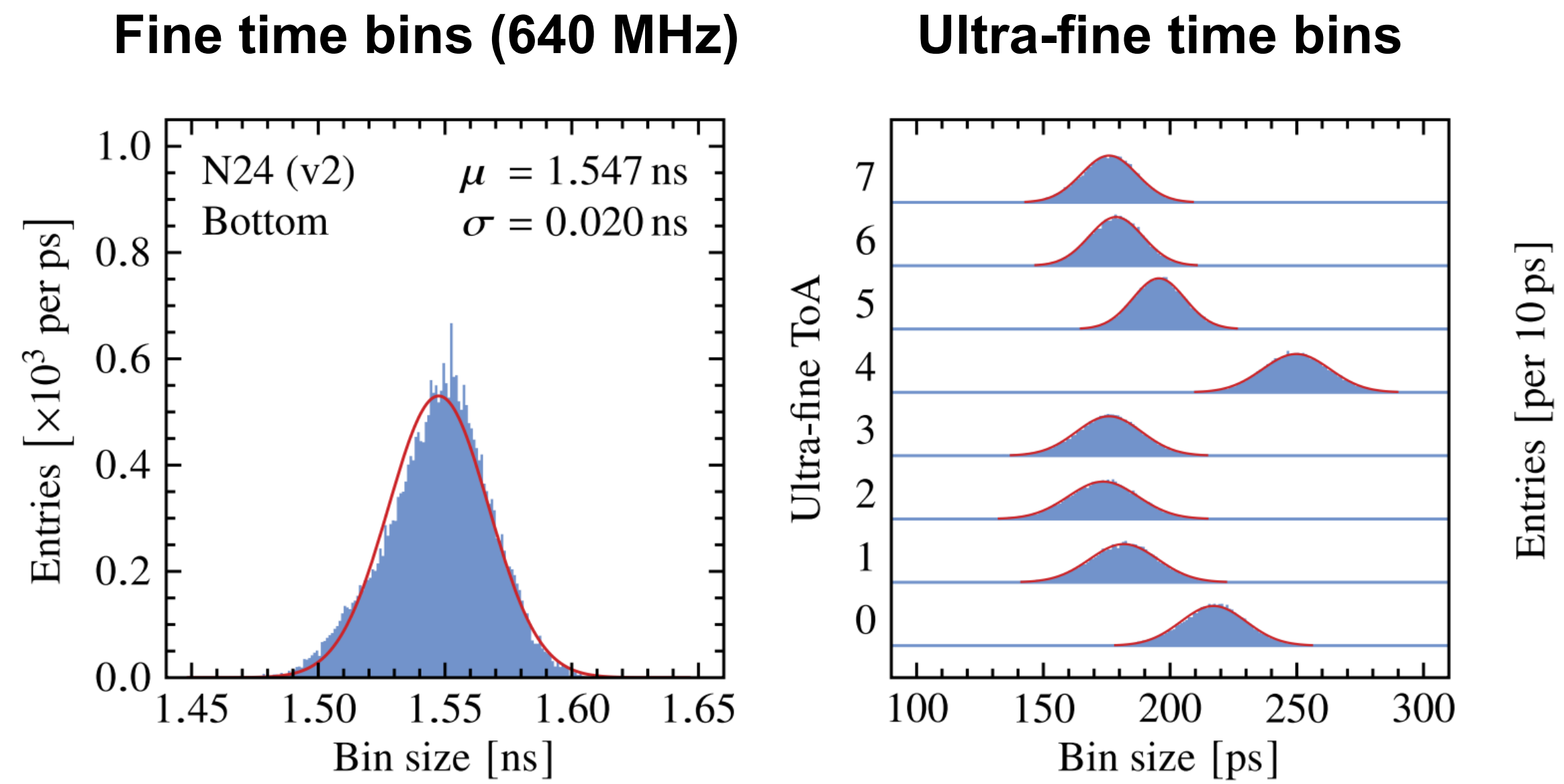
K. Heijhoff *et al* 2022 JINST 17 P07006 [DOI: [10.1088/1748-0221/17/07/P07006](https://doi.org/10.1088/1748-0221/17/07/P07006)]





# TDC resolution

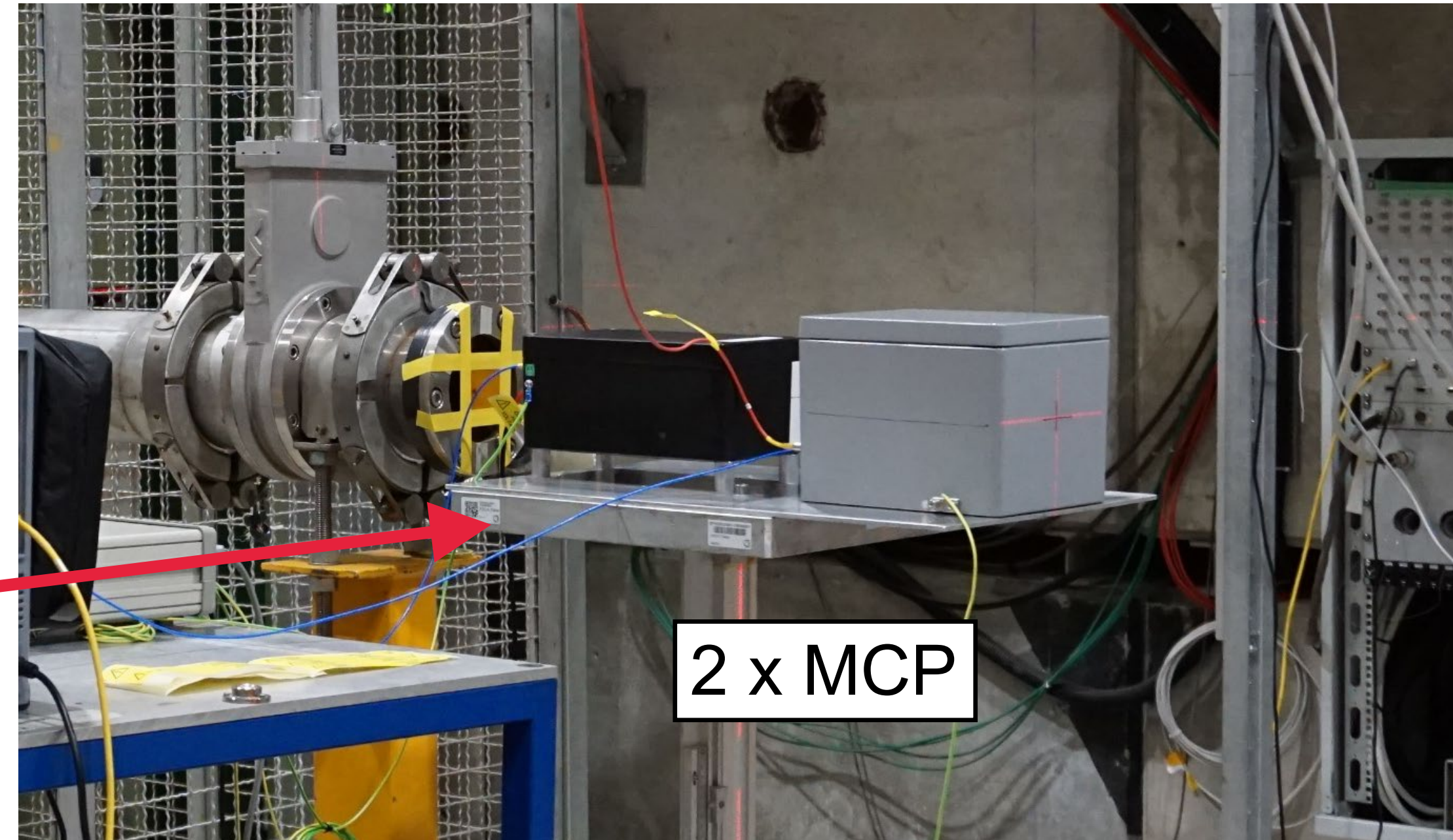
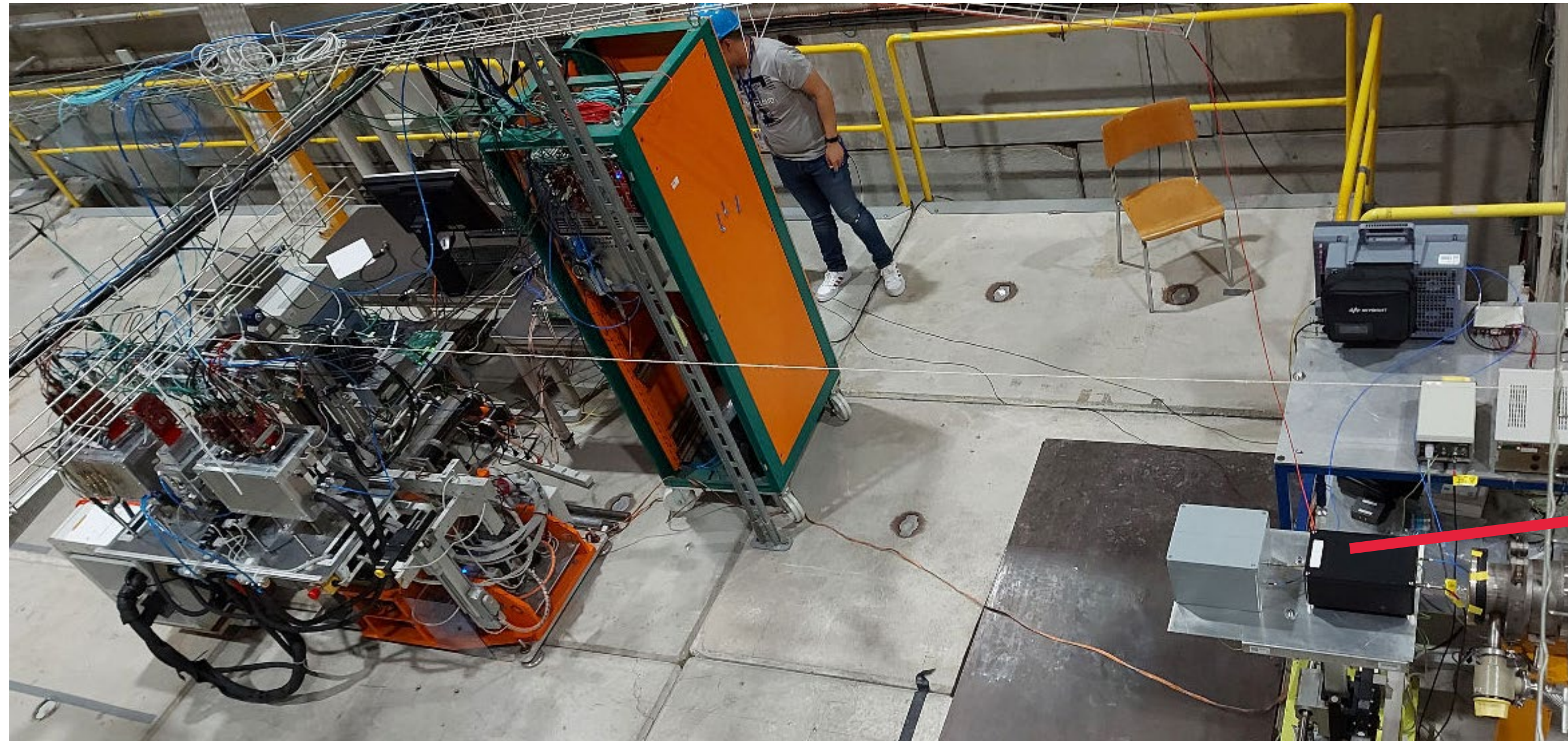
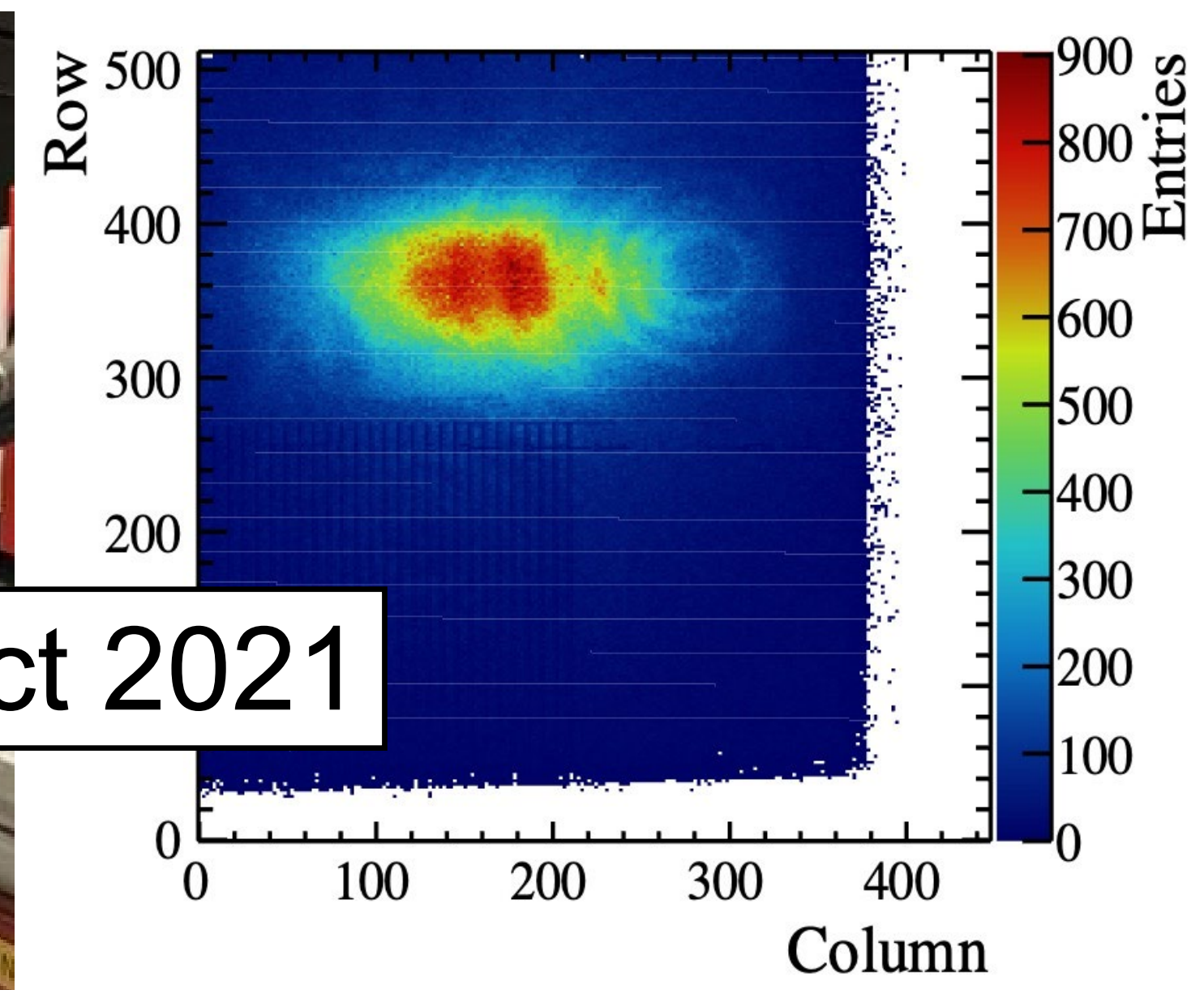
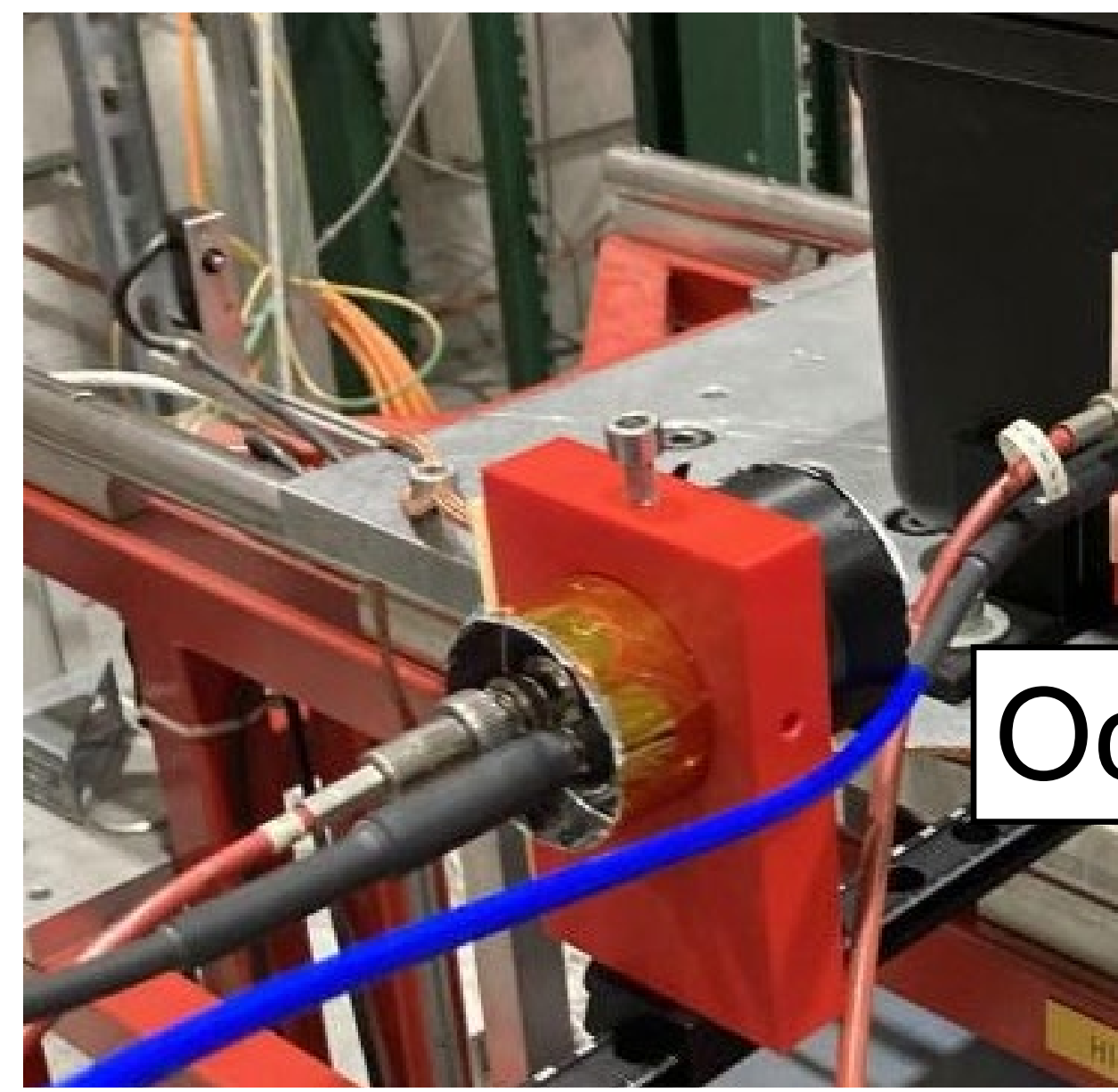
- Variation in the VCO frequency over the pixel matrix observed:  
 Bottom half:  $1.547 \text{ ns} \pm 20 \text{ ps}$   
 Top half:  $1.583 \text{ ns} \pm 14 \text{ ps}$
- Structure in ultra-fine time bins has a small impact on TDC resolution (few %)
- We have tried to predict the TDC resolution for correction methods of increasing complexity





# MCP time reference

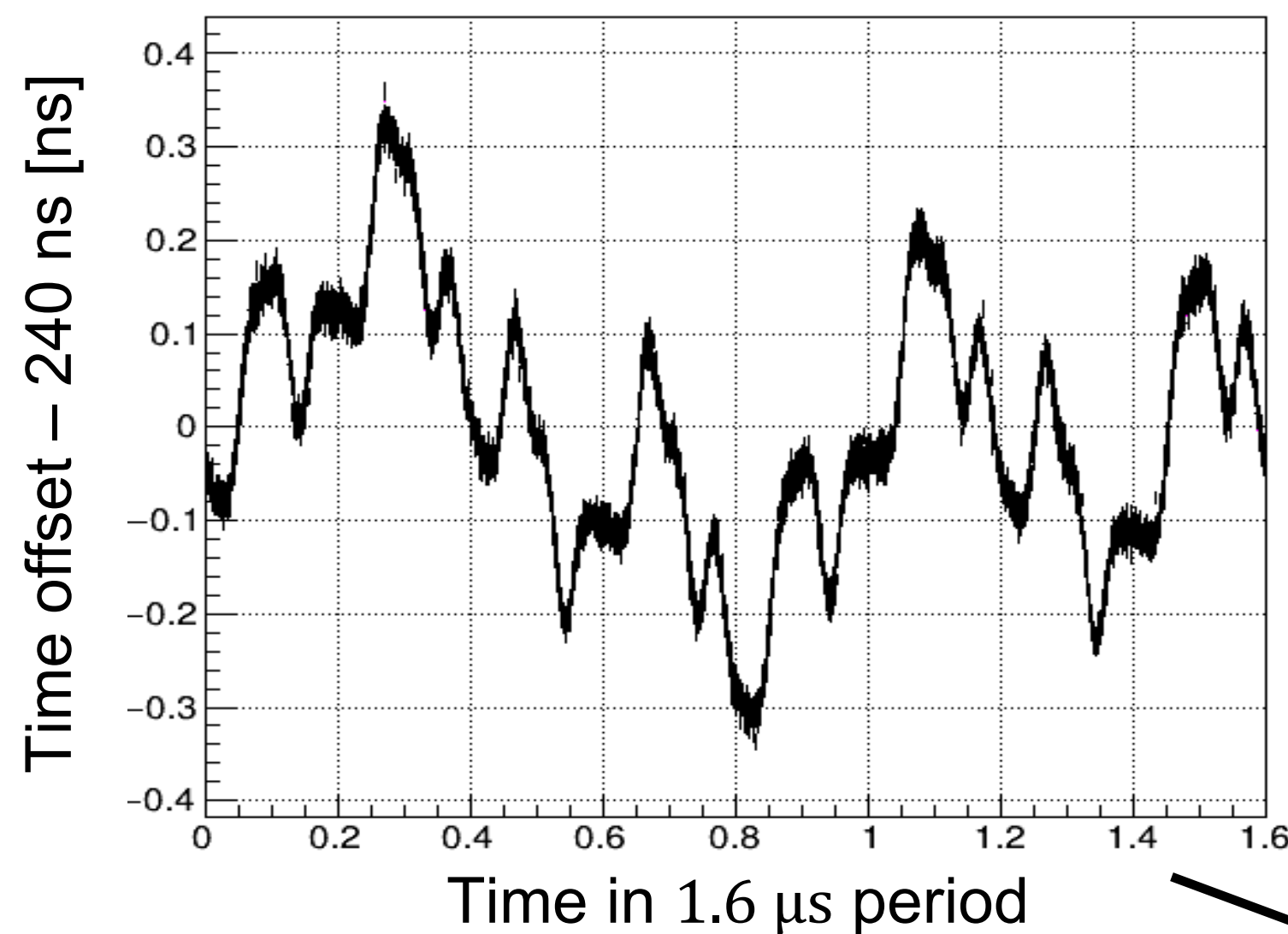
- Two MCPs provide precise time references to study timing performance of telescope
- Placed at end to not hinder other groups in same beam area
- CFDs suffered from large signals due to nuclear interactions



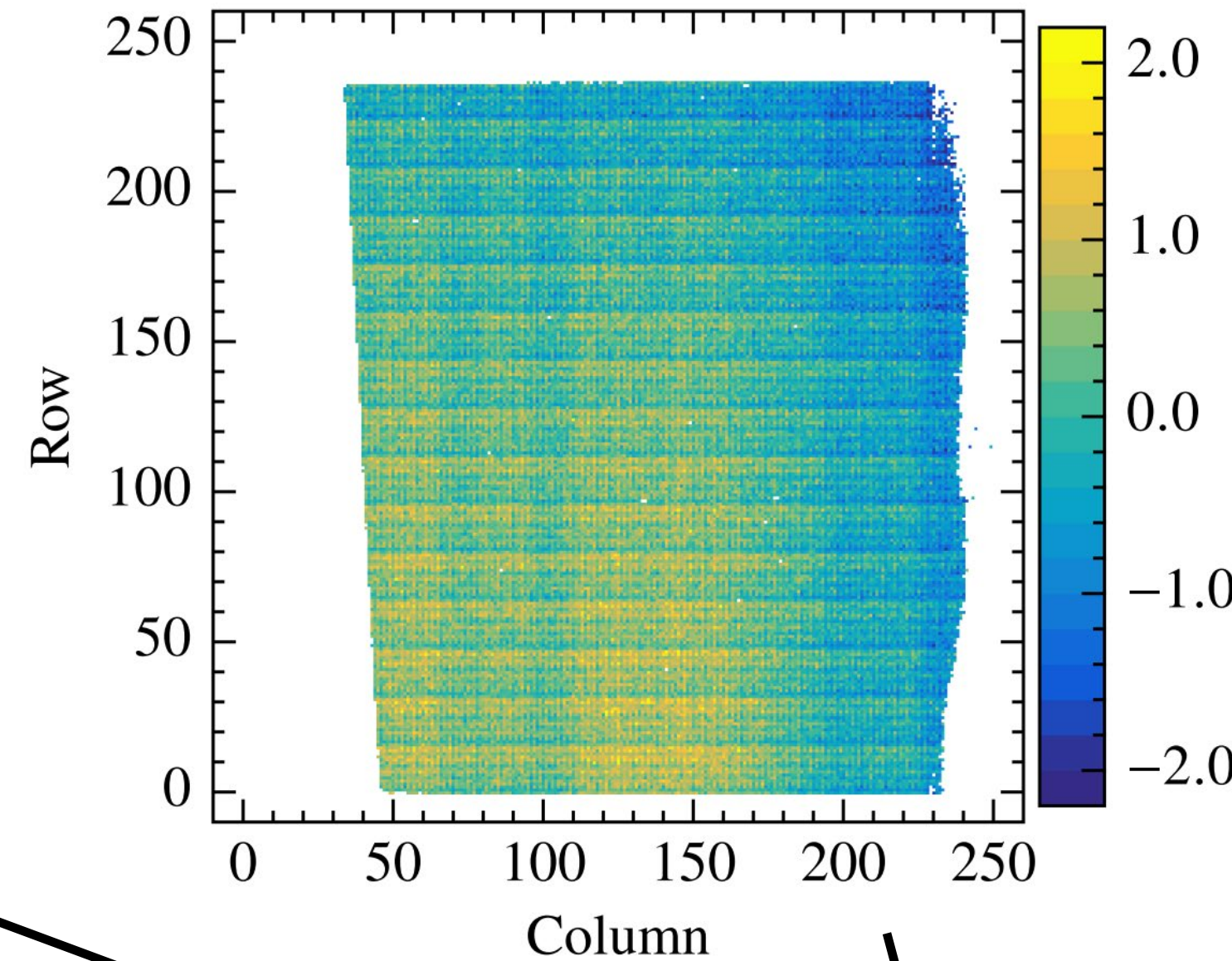


# Timing systematics in the LHCb VELO Timepix3 Telescope

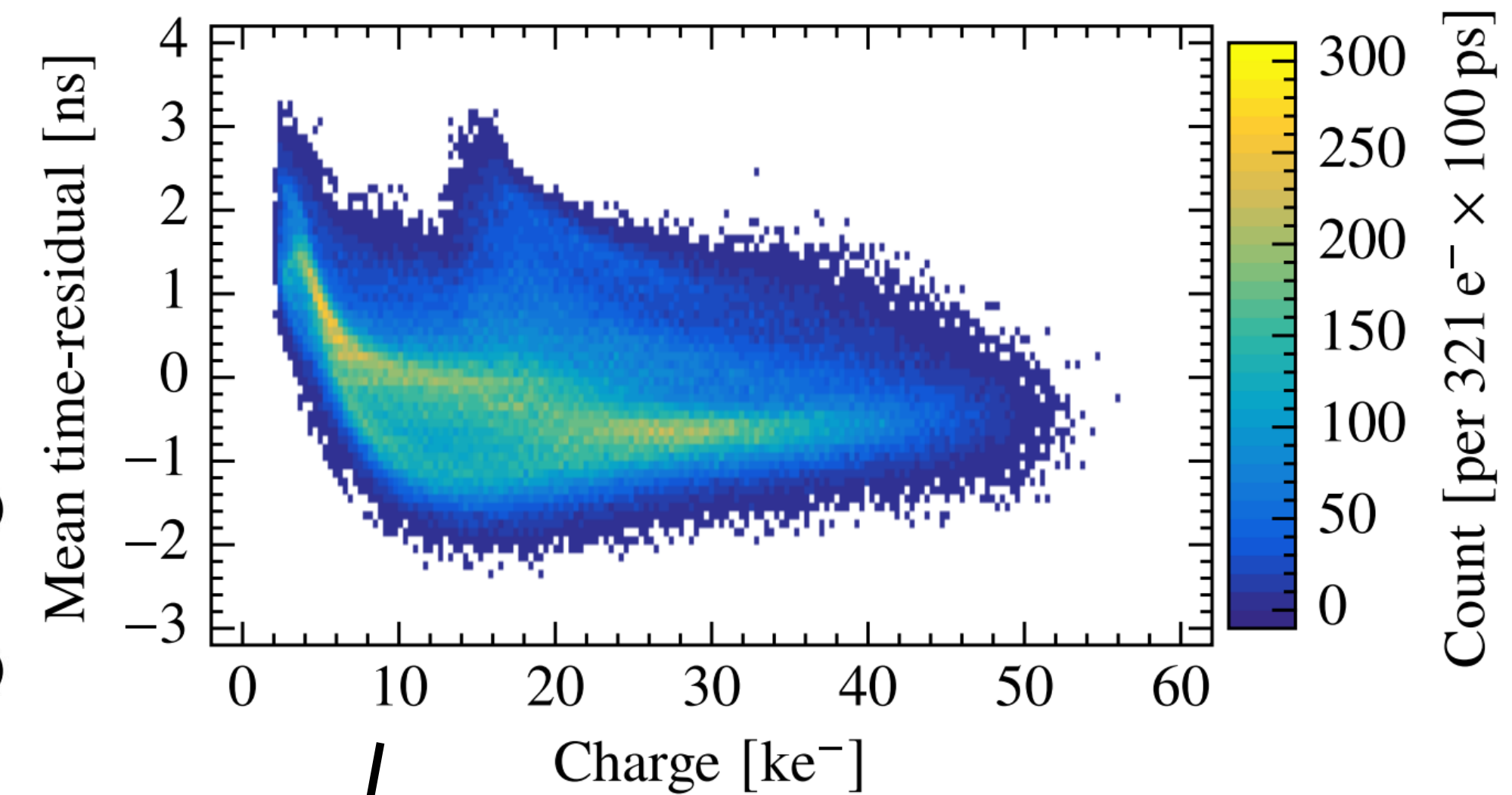
**Clock phase variation**



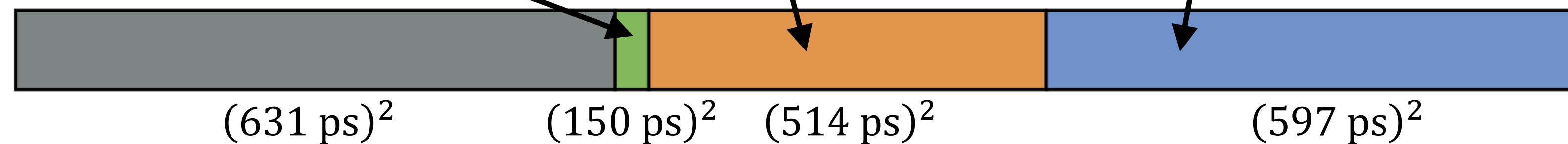
**Pixel / TDC systematics**



**Timewalk and signal induction time in sensor**



**Single-hit time:**



$\sigma_t = 1 \text{ ns}$

$(631 \text{ ps})^2$

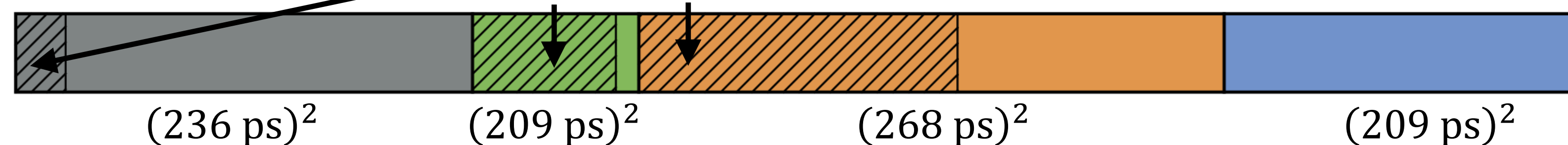
$(150 \text{ ps})^2$

$(514 \text{ ps})^2$

$(597 \text{ ps})^2$

Correlations between time measurements

**Track time:**  
(mean of 8 hits)



$\sigma_t = 438 \text{ ps}$

$(236 \text{ ps})^2$

$(209 \text{ ps})^2$

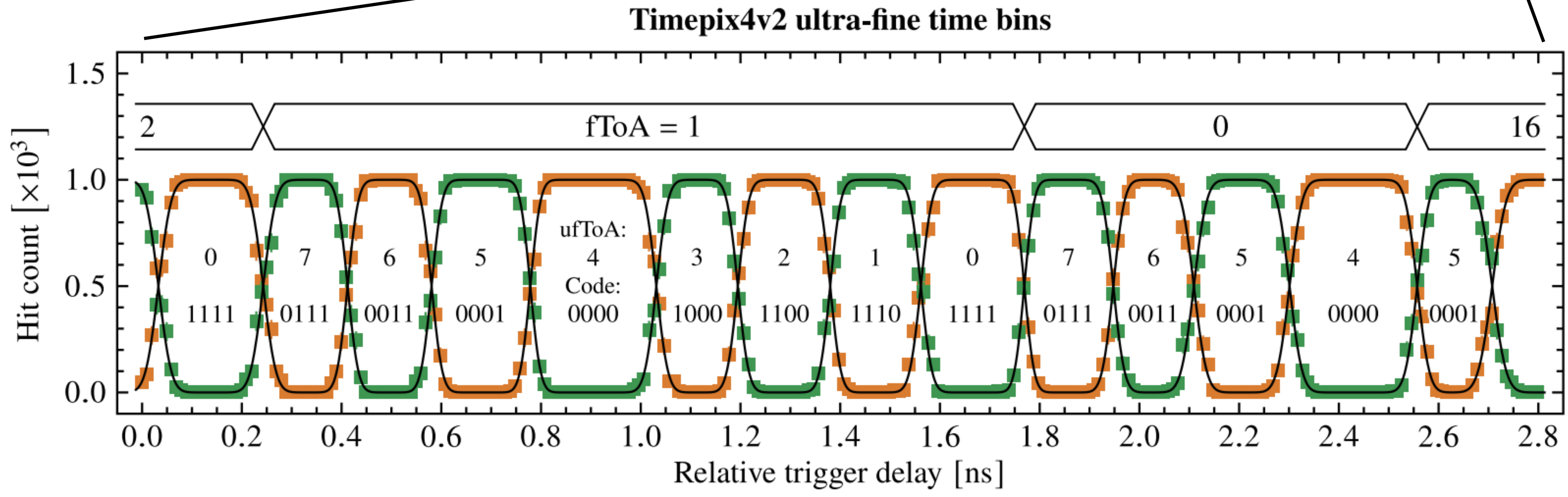
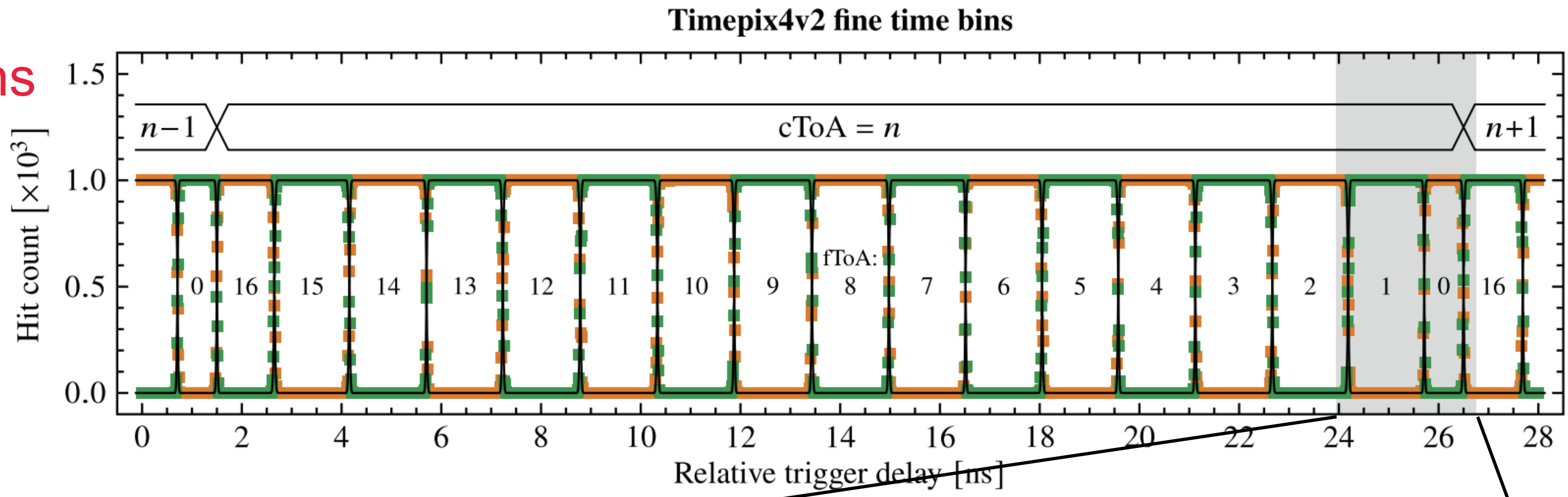
$(268 \text{ ps})^2$

$(209 \text{ ps})^2$



# Timepix4 TDC bins

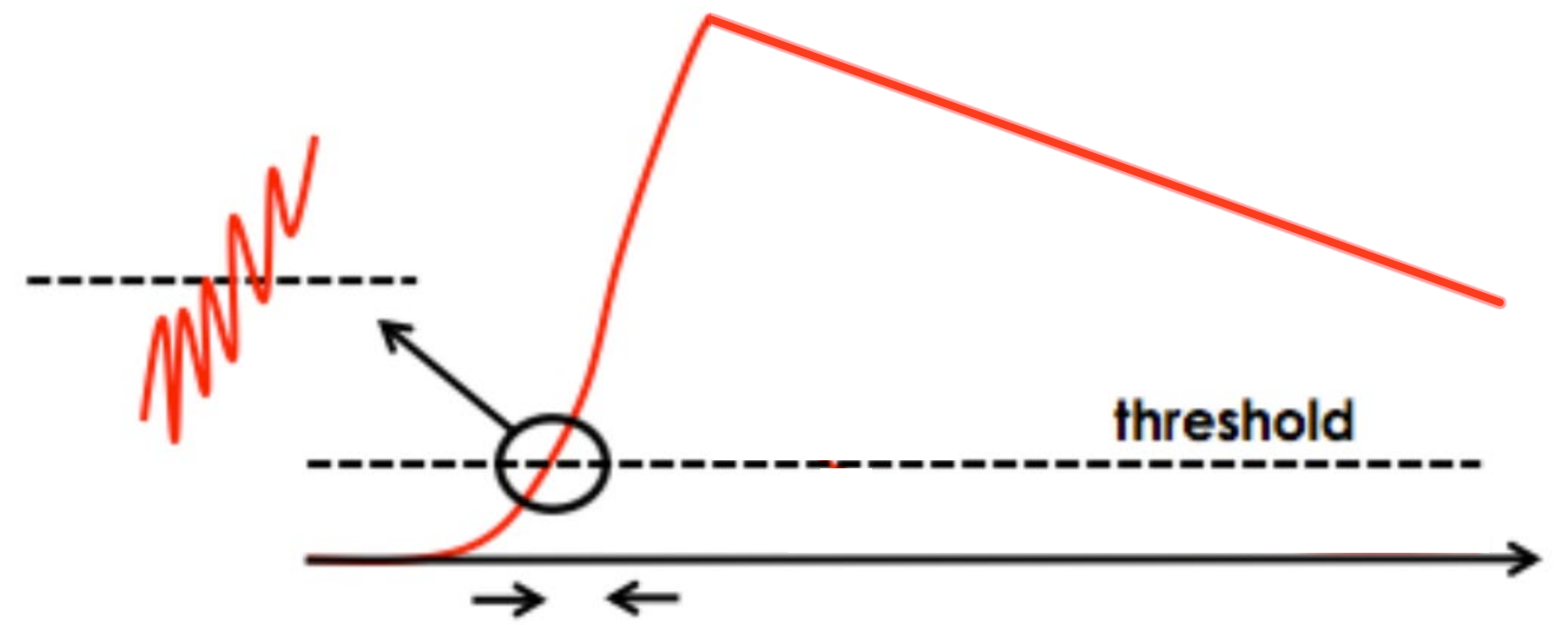
- Time bins measured using digital pixel inputs
- Timepix4v2



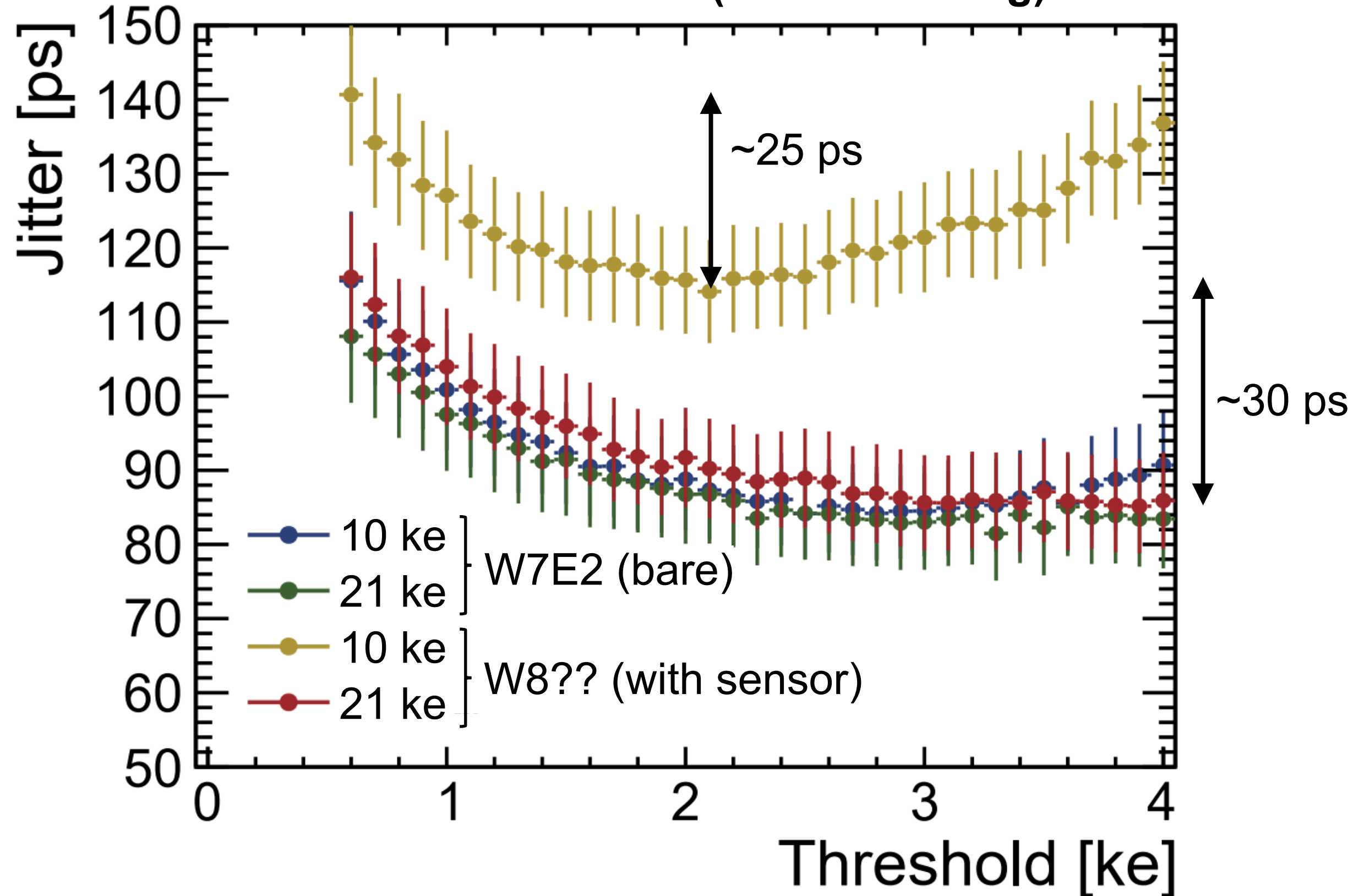


# Timepix4 – Jitter vs threshold

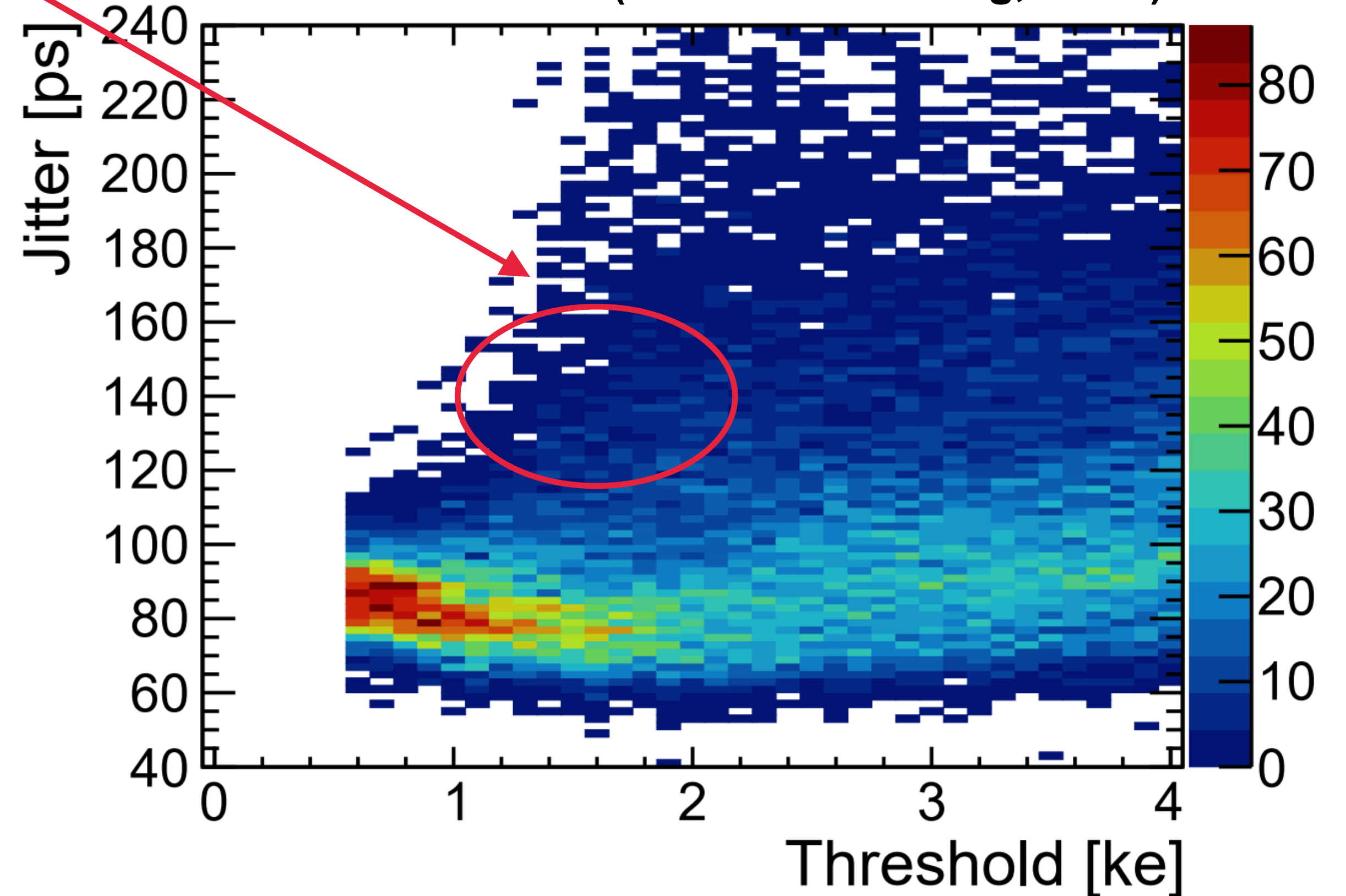
- Jitter depends on threshold
- Tail at high thresholds in electron-collecting mode not understood



### Jitter vs threshold (hole collecting)



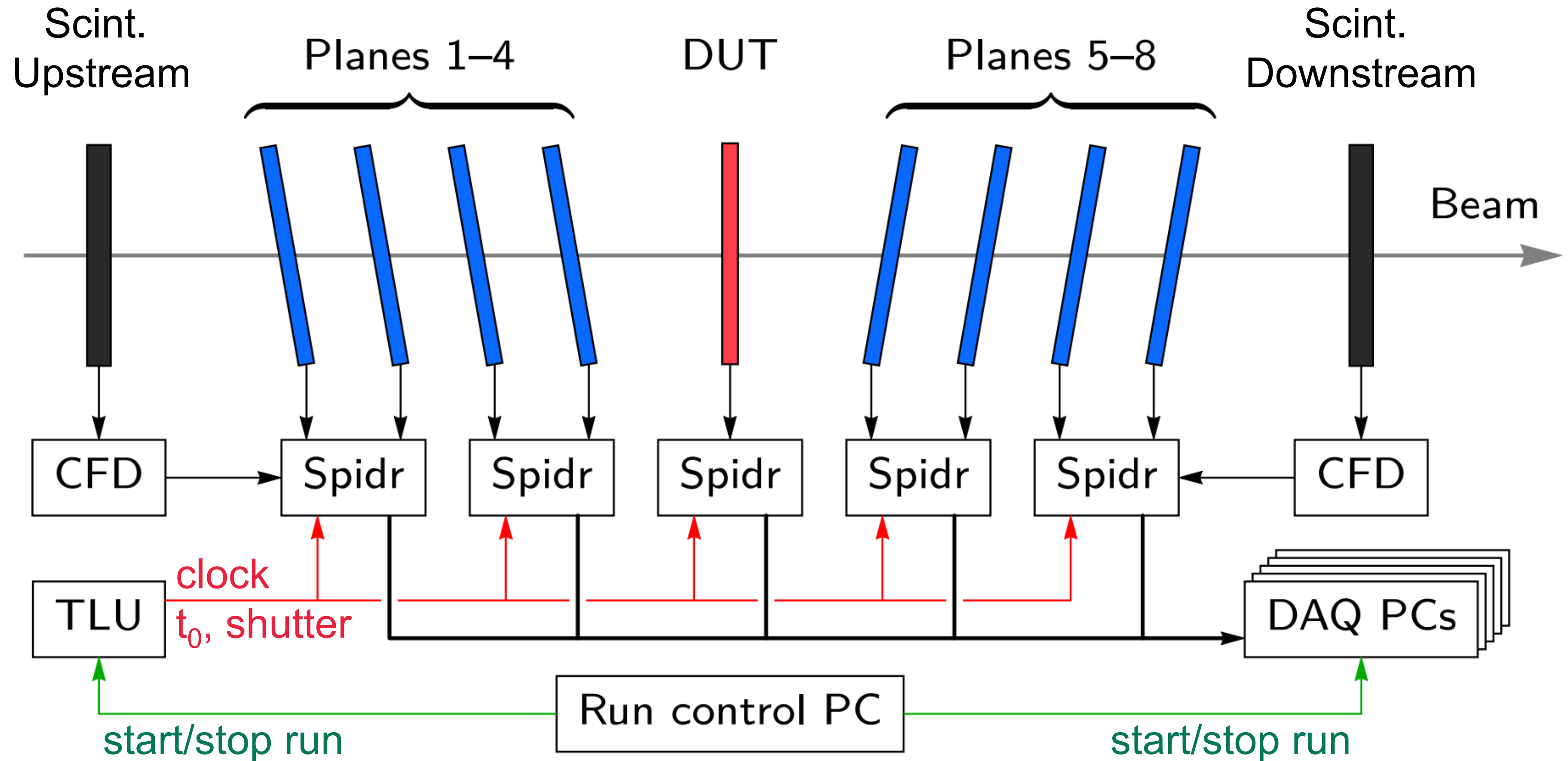
### Jitter vs threshold (electron collecting, 10 ke)





# Timepix3 telescope

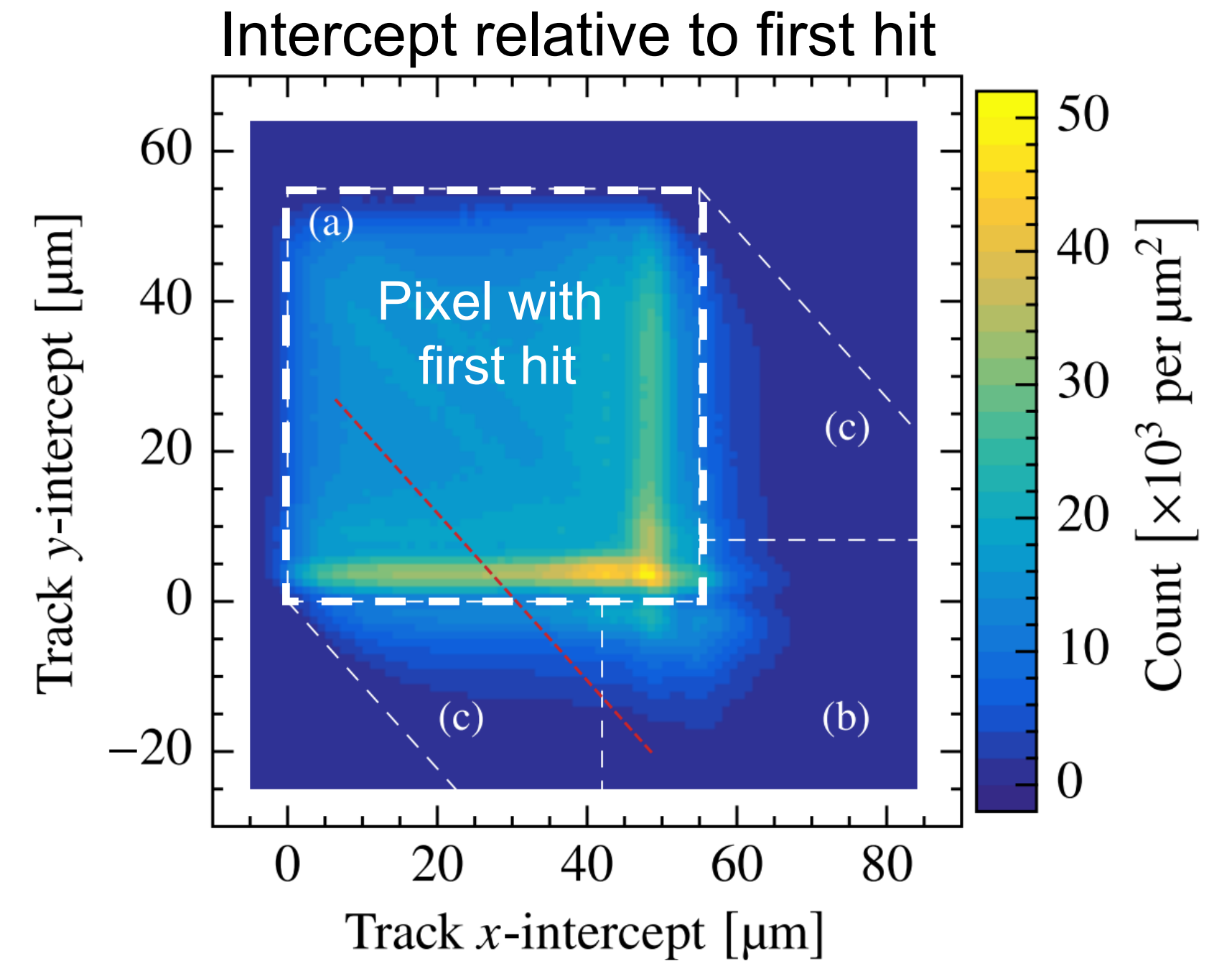
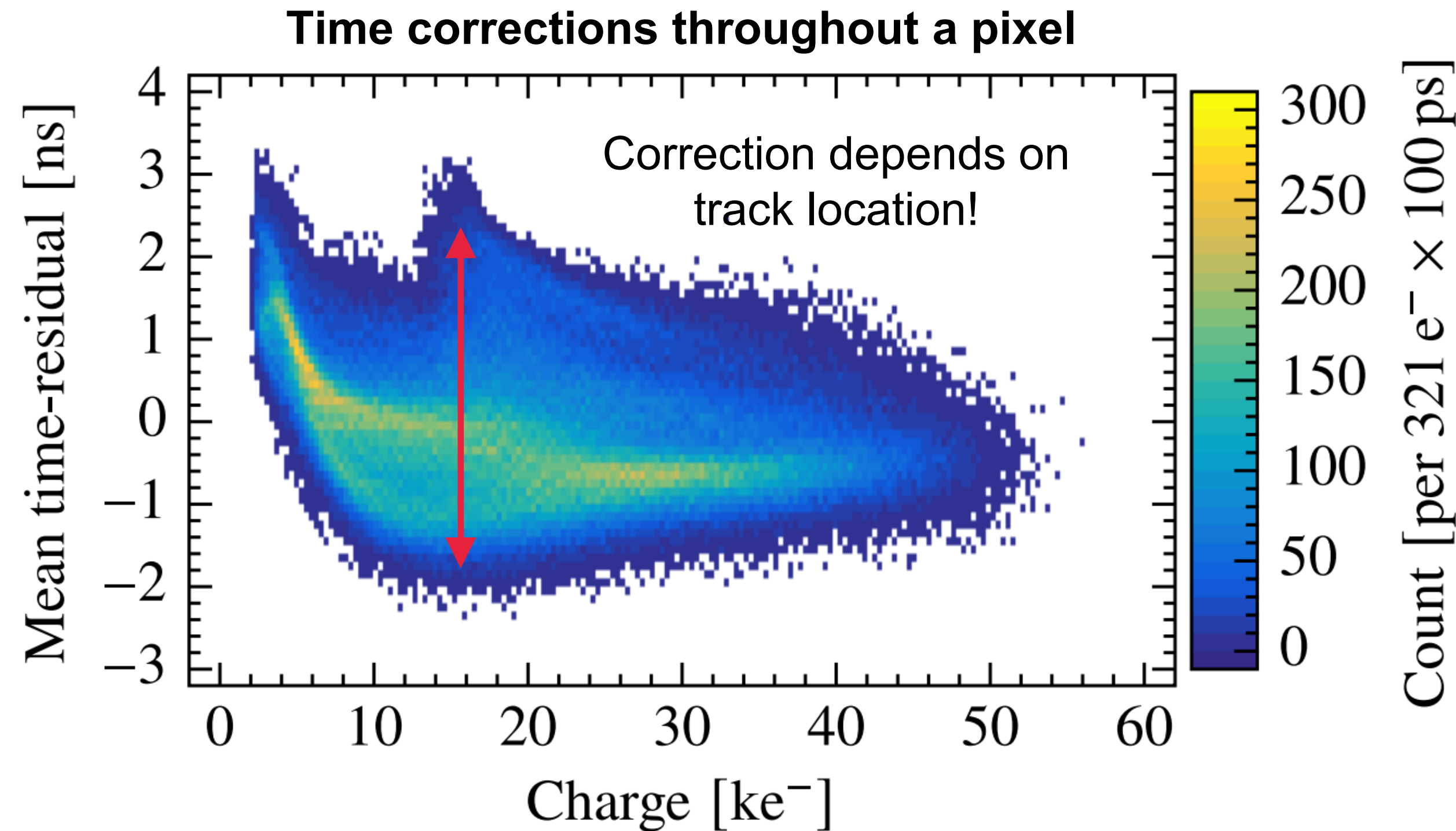
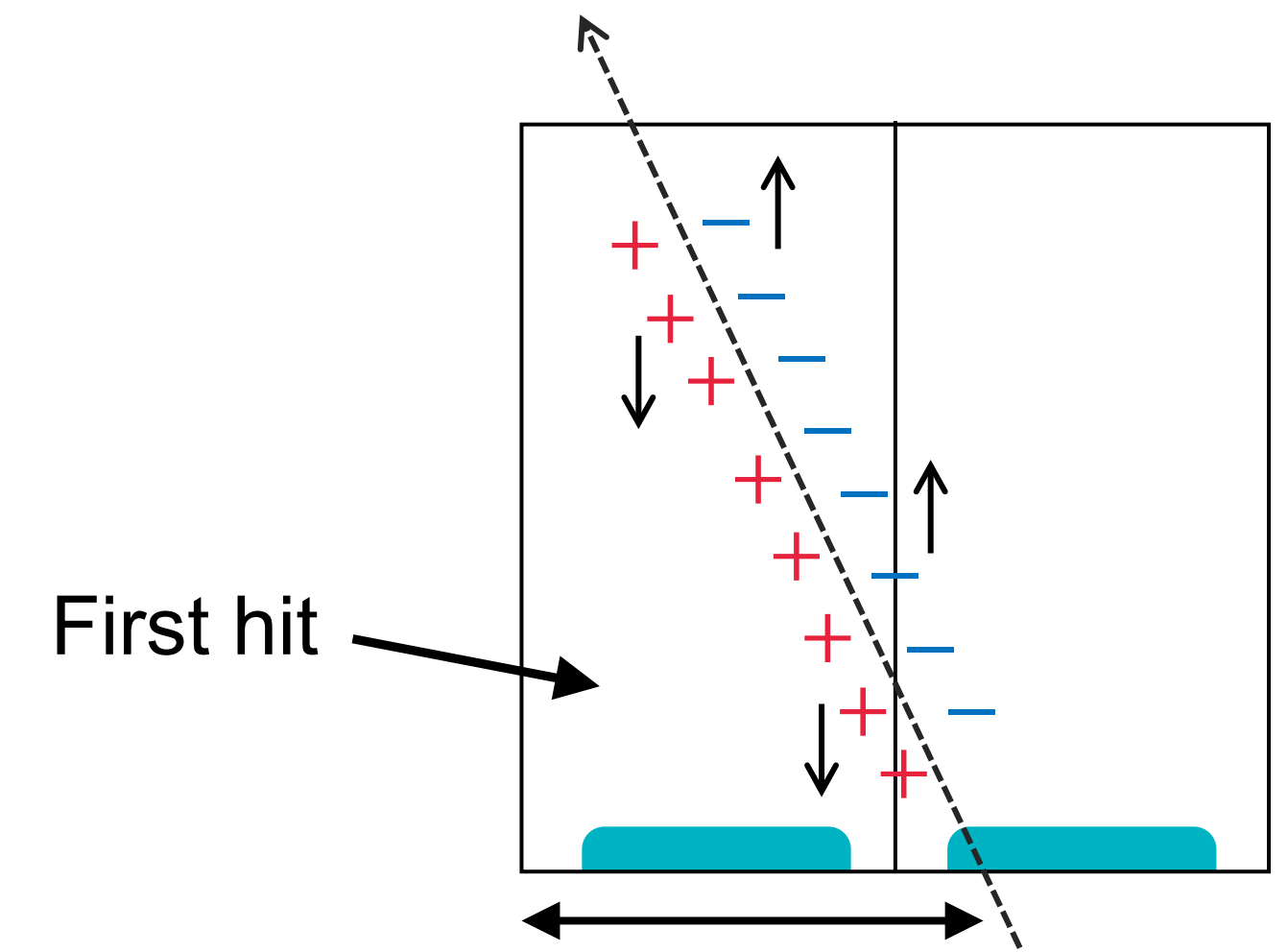
- Eight planes with Timepix3 + sensors
- Planes rotated to optimise spatial resolution
- Scintillators provide a reference time
- Constant fraction discriminators (CFDs) reduce timewalk effects
- All planes run on a common 40 MHz clock





# Timewalk and intercept correction

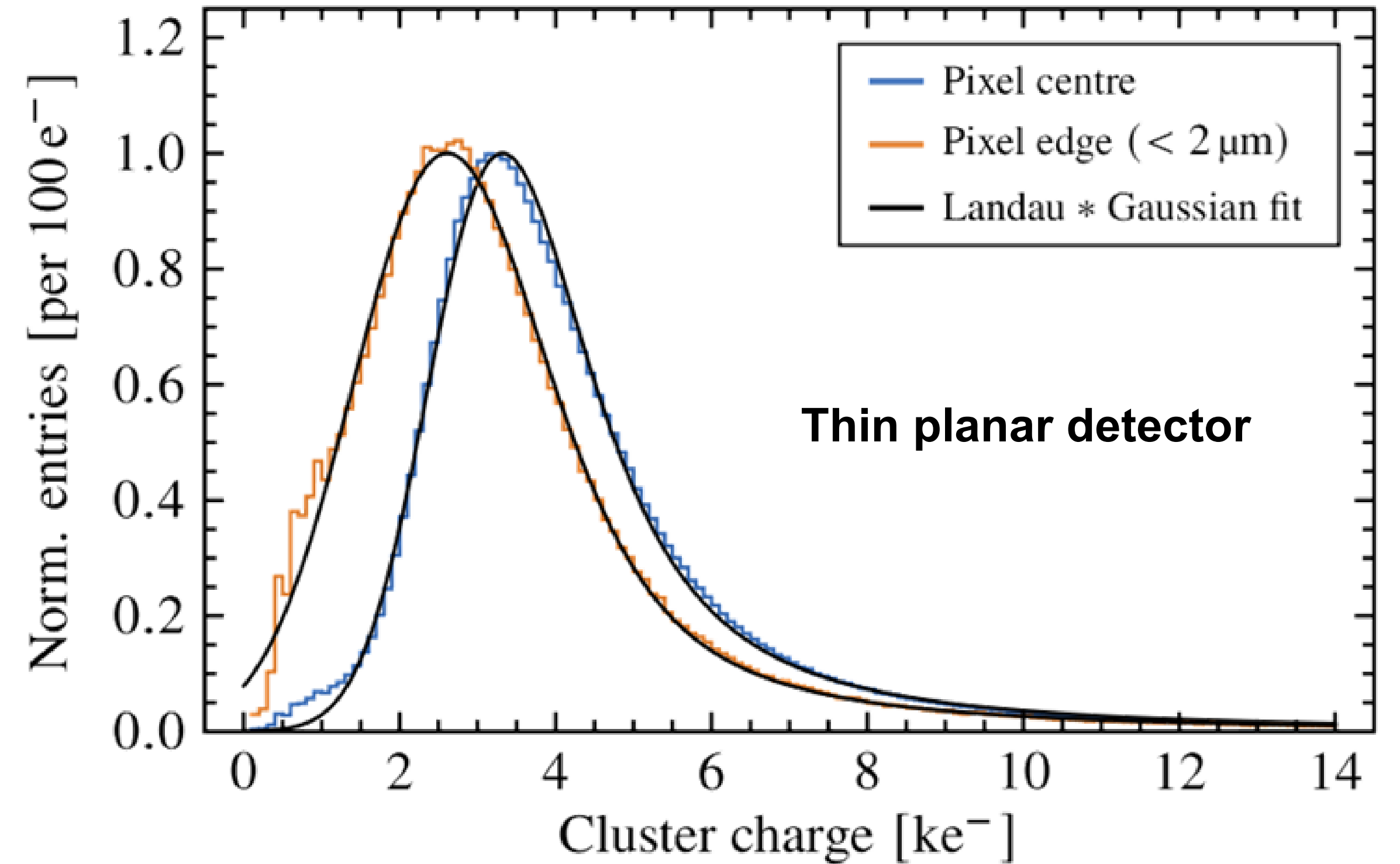
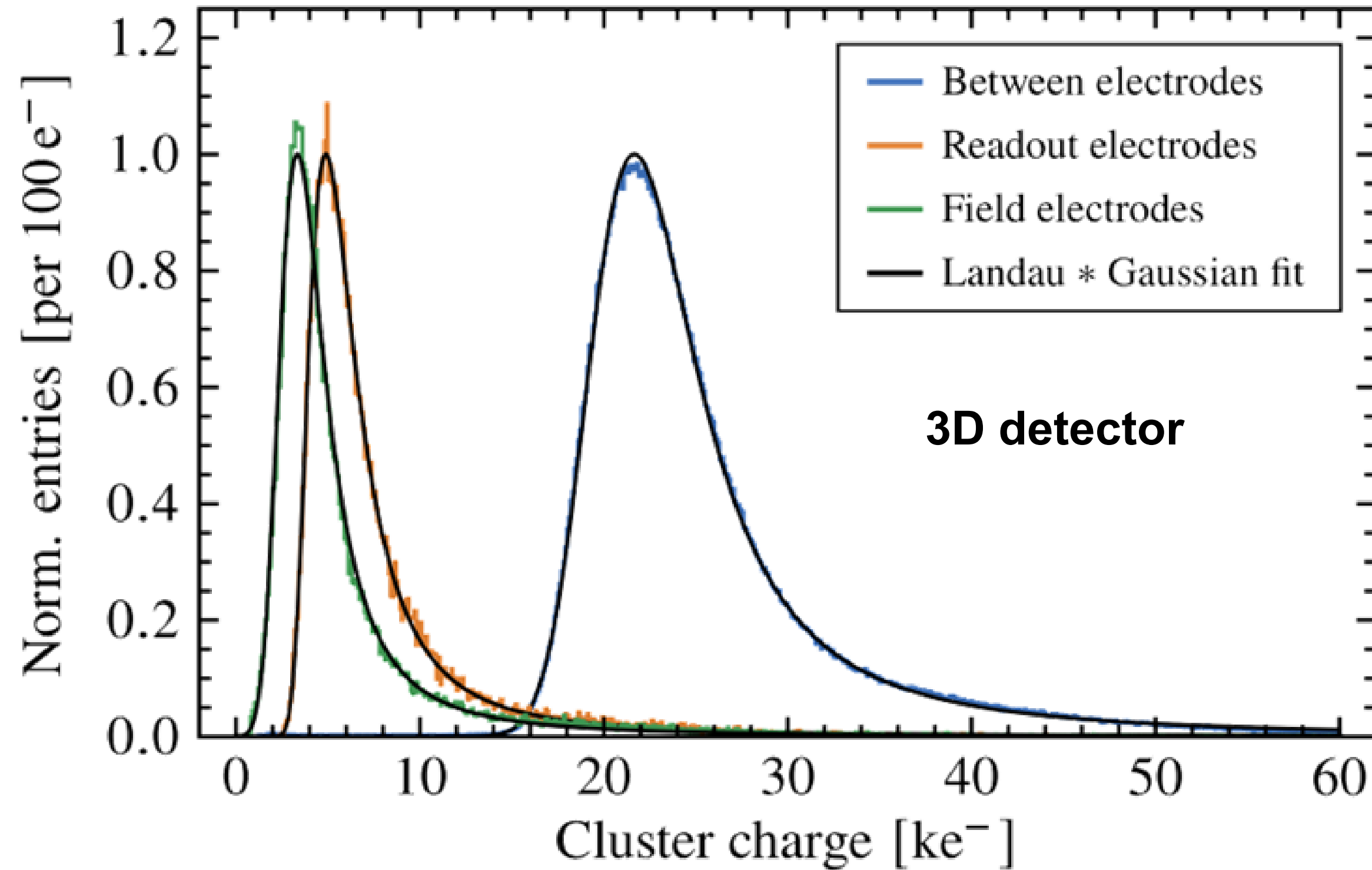
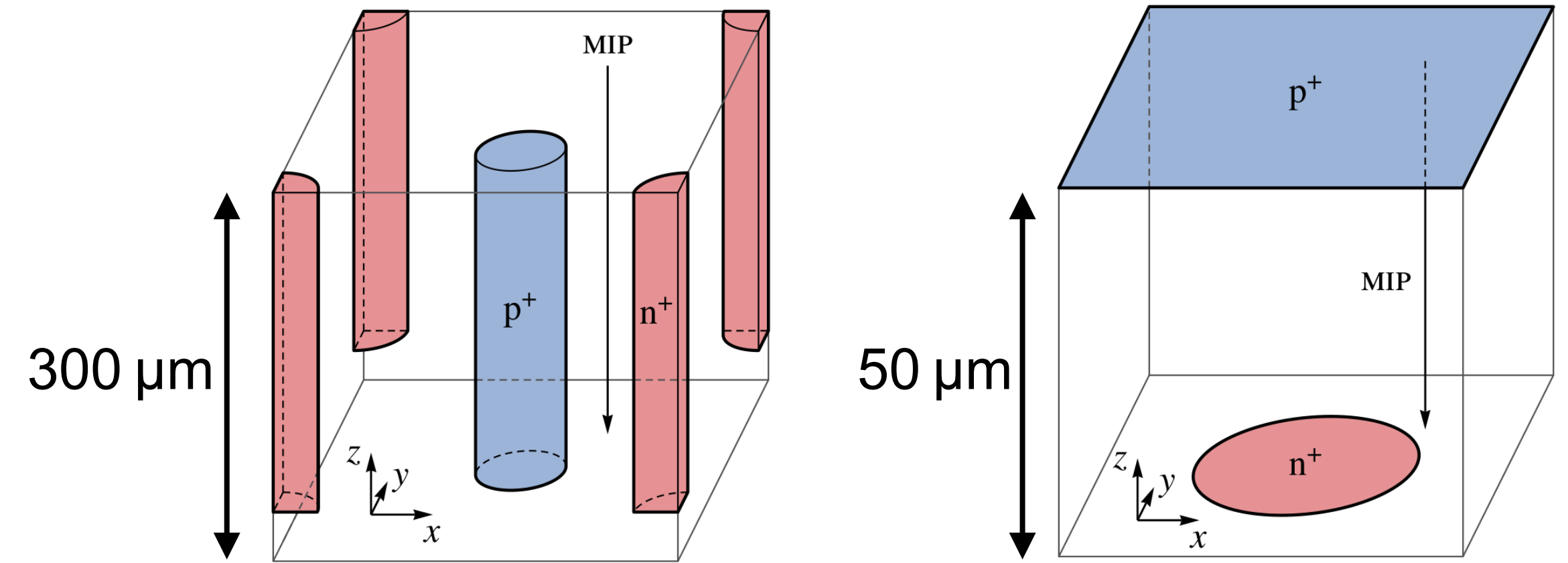
- Use both track intercept and charge to find correction in a lookup table
- Simultaneously corrects for timewalk and signal induction variations
- Improves track time resolution:  $\sigma(\text{track}) = 438 \text{ ps} \rightarrow 385 \text{ ps}$





# DUT charge distributions

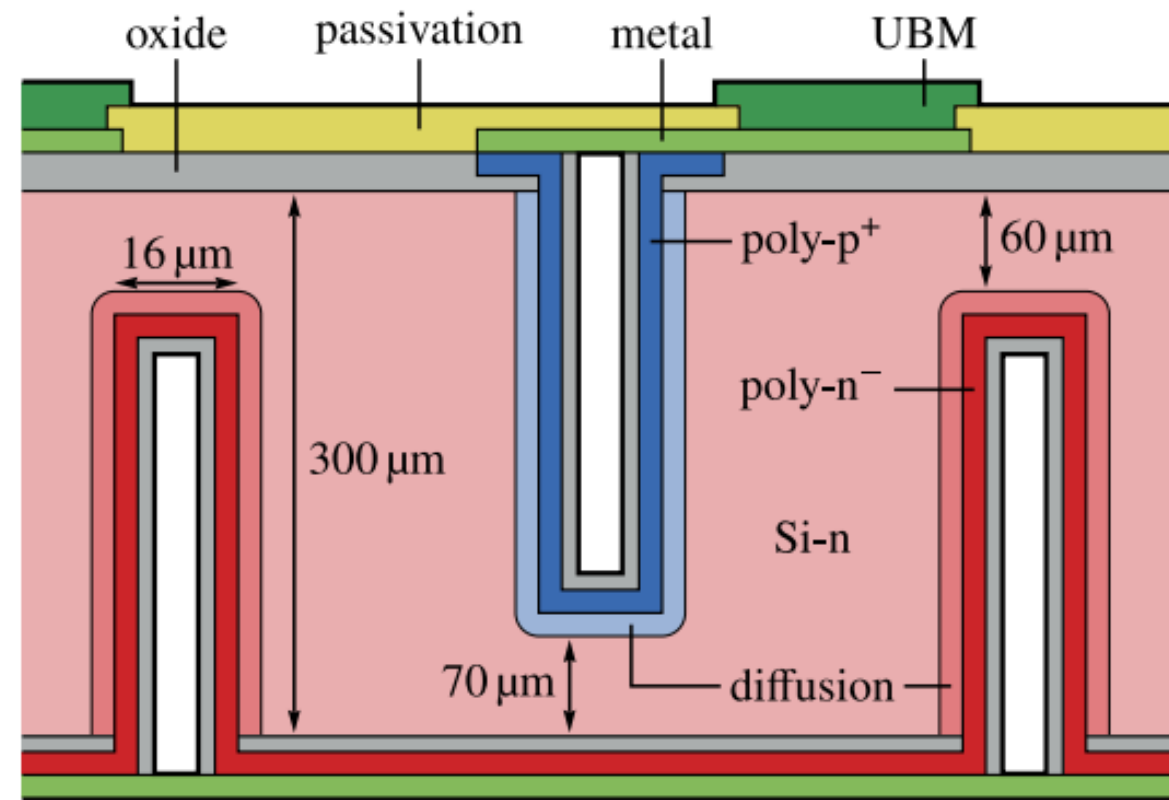
- MIPs going through electrodes of 3D sensor only generate charge in small region



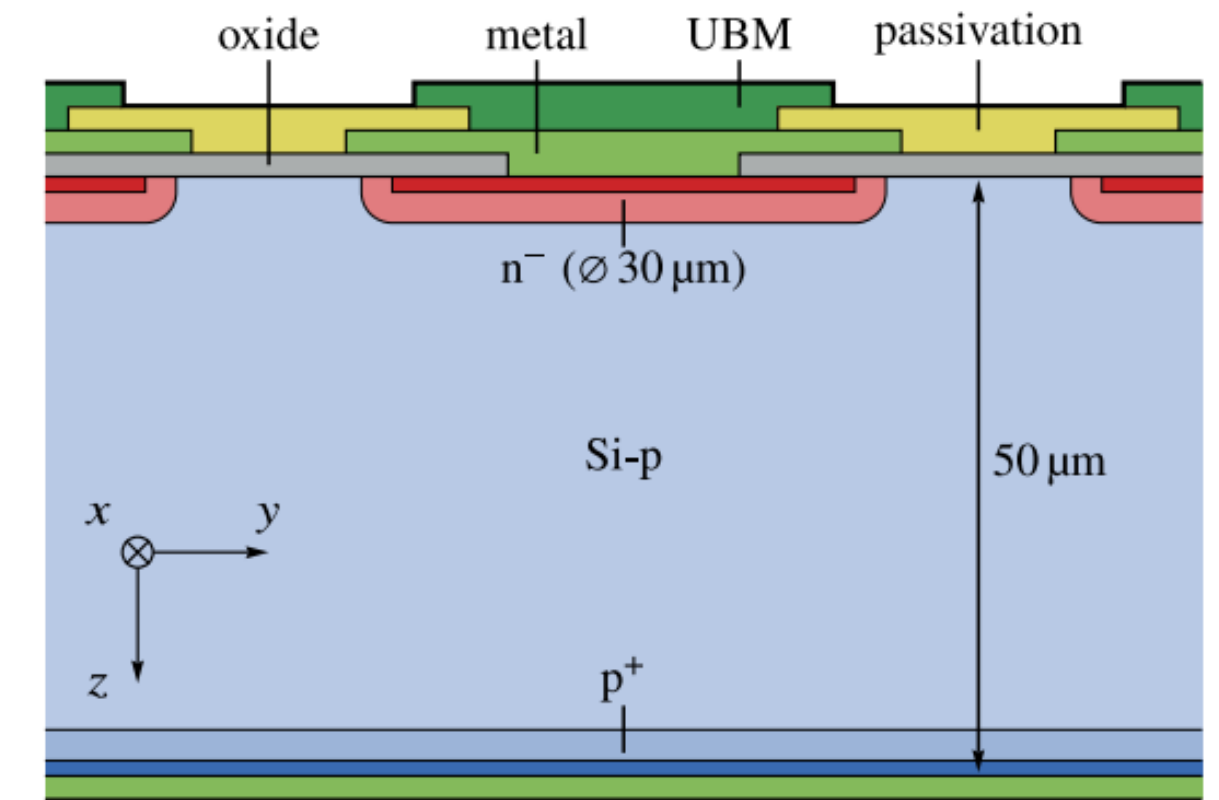


# Intrapixel time delay

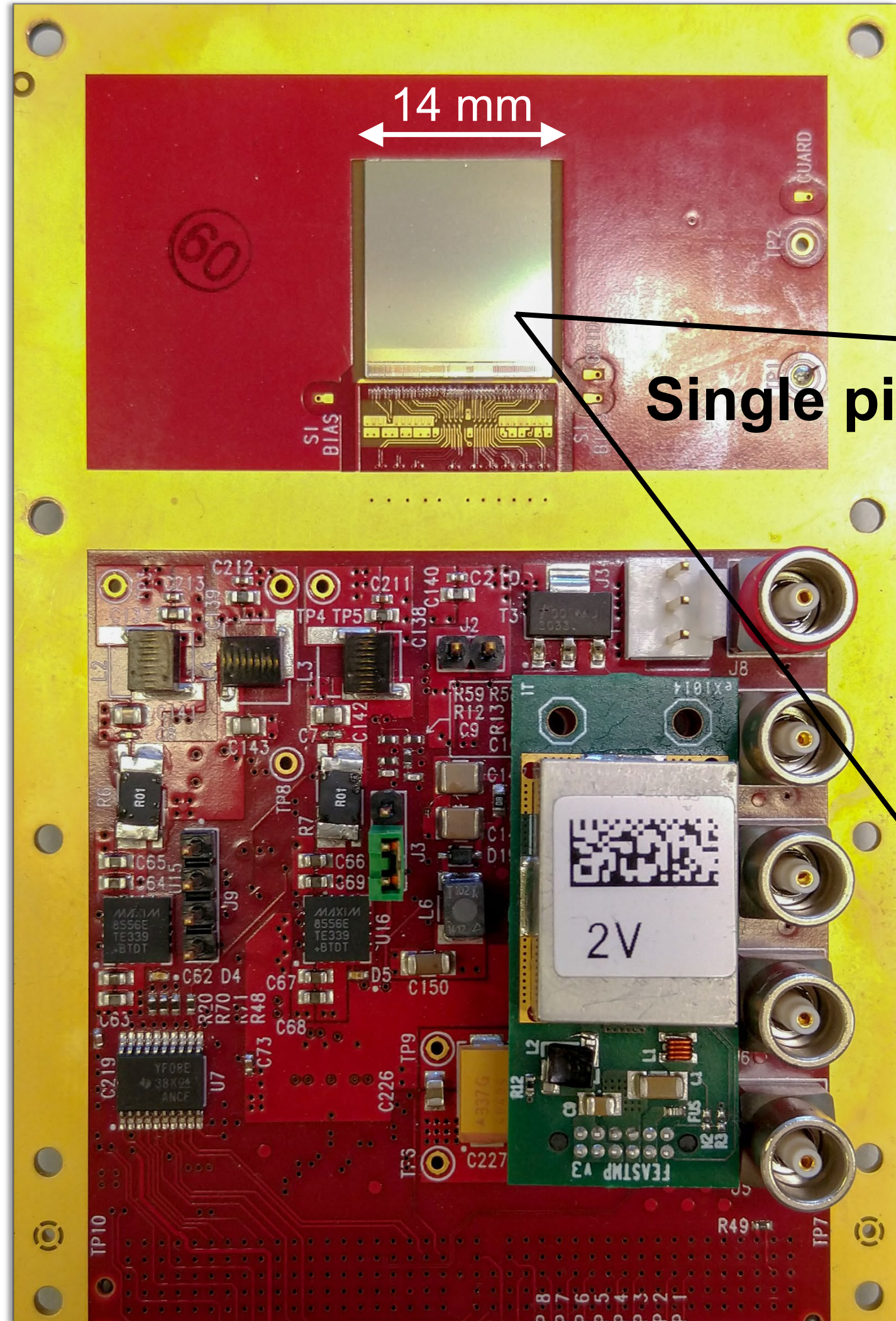
## 3D sensor technology



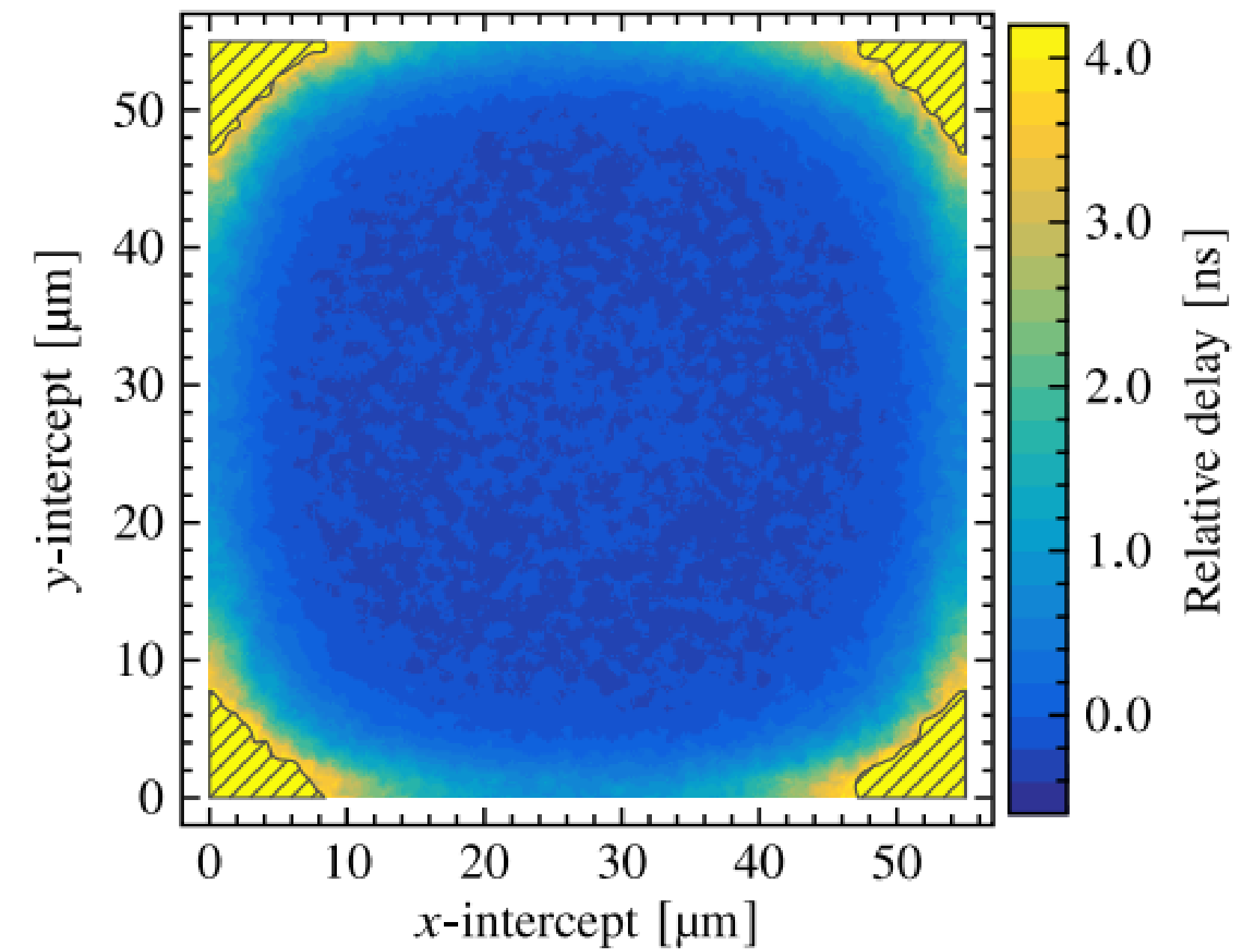
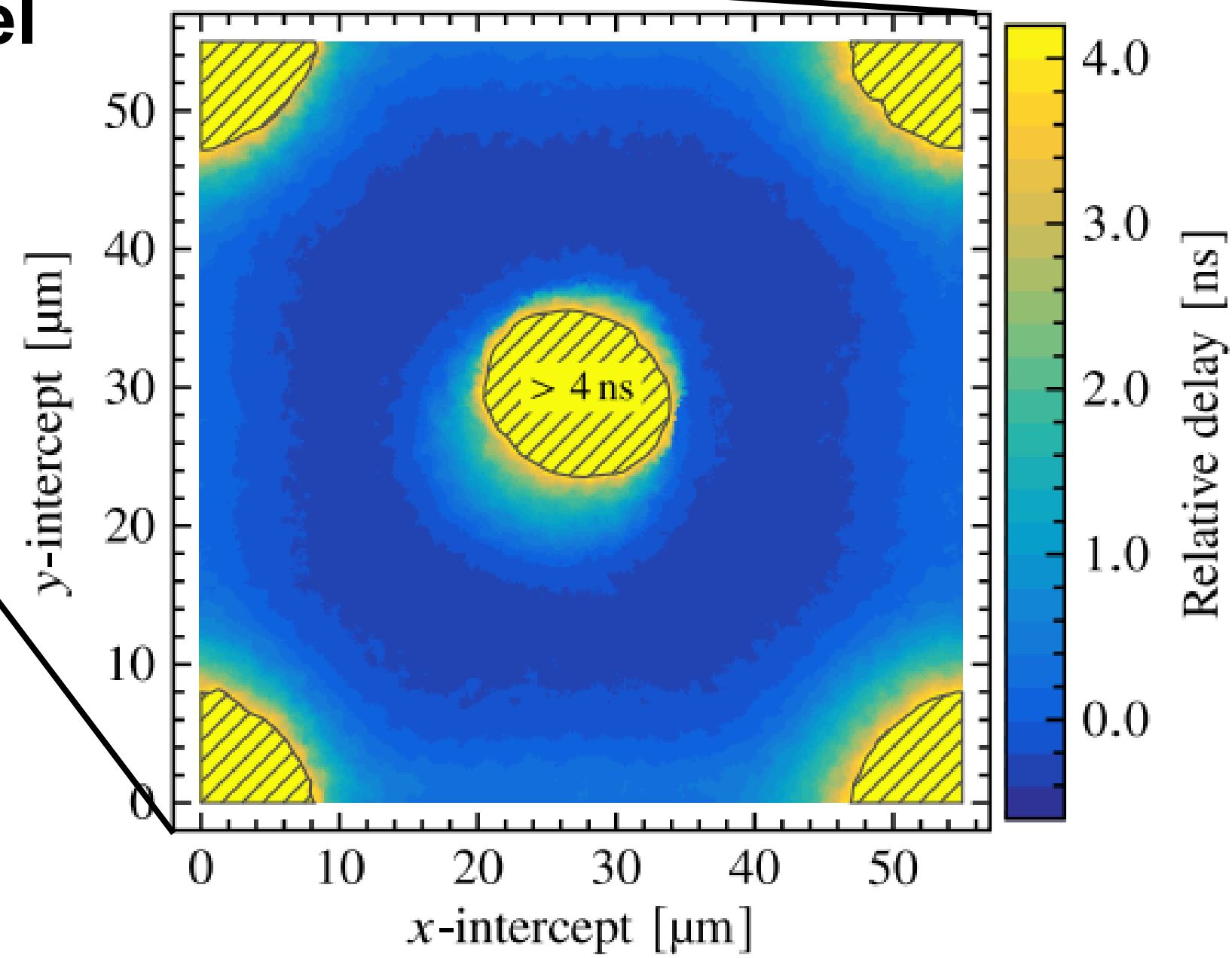
## Thin planar sensor



## Timepix3 pixel ASIC + sensor



Single pixel



K. Heijhoff *et al* 2021 *JINST* 16 P08009 [DOI: [10.1088/1748-0221/16/08/P08009](https://doi.org/10.1088/1748-0221/16/08/P08009)]